OL2311
Highly integrated single-chip sub 1 GHz RF receiver

Rev. 1 — 8 December 2011 **Product data sheet**

1. General description

A highly integrated single-chip receiver solution, the OL2311 is ideally suited to telemetry applications operating in the ISM/SRD bands. The small form factor, low power consumption and wide supply voltage range make this device suitable for use in battery powered, handheld devices and their counter parts.

The device utilizes a fully integrated, programmable fractional-N PLL (including loop filter) to control the Local Oscillator (LO), thus supporting multi-channel operation and frequency hopping schemes. This feature also allows programmable frequency steps for crystal (XTAL) drift compensation.

The device is based on a low IF direct conversion receiver architecture, with on-chip IF filtering and programmable channel bandwidth. After filtering and amplification the quadrature signals are digitized, demodulated and processed in the digital domain.

Baseband processing of the received signal comprises a demodulator, a data-slicer and clock recovery followed by a Manchester decoder. Automated signal signature recognition units are available to allow simple, fast and reliable data reception.

The device is controlled via a three-wire serial interface (SPI) with data input and output, data clock and interface enable. The interface can be configured to a full SPI interface with separate data and clock pins. Additional pins are available to access internal signals in real-time.

2. Features and benefits

- Highly integrated solution for the 315/434/868/915 MHz band
- Very few external components required
- Complies with ETSI EN300-220/FCC part 15 standards
- Near zero-IF RX architecture
- On-chip channel filtering with automatic calibration supported to provide stable cut-off frequencies and filter roll-off
- Multi-channel operation by fully integrated fractional-N PLL with on-chip loop filter
- Automatic VCO sub-band selection and calibration to reduce PLL loop bandwidth variation
- Digital RSSI with a configurable threshold
- Onboard Signal Signature Recognition Unit with Preamble Pattern Recognition
- Configurable polling timer with 2% absolute accuracy
- Level Sensitive Data slicer with self-adjusting threshold
- Low power Consumption (RX 16mA), with ultra Low 0.5µA standby current and configurable polling timer

- Single Lithium cell operation (2.1V). Operation up to 3.6V fully supported
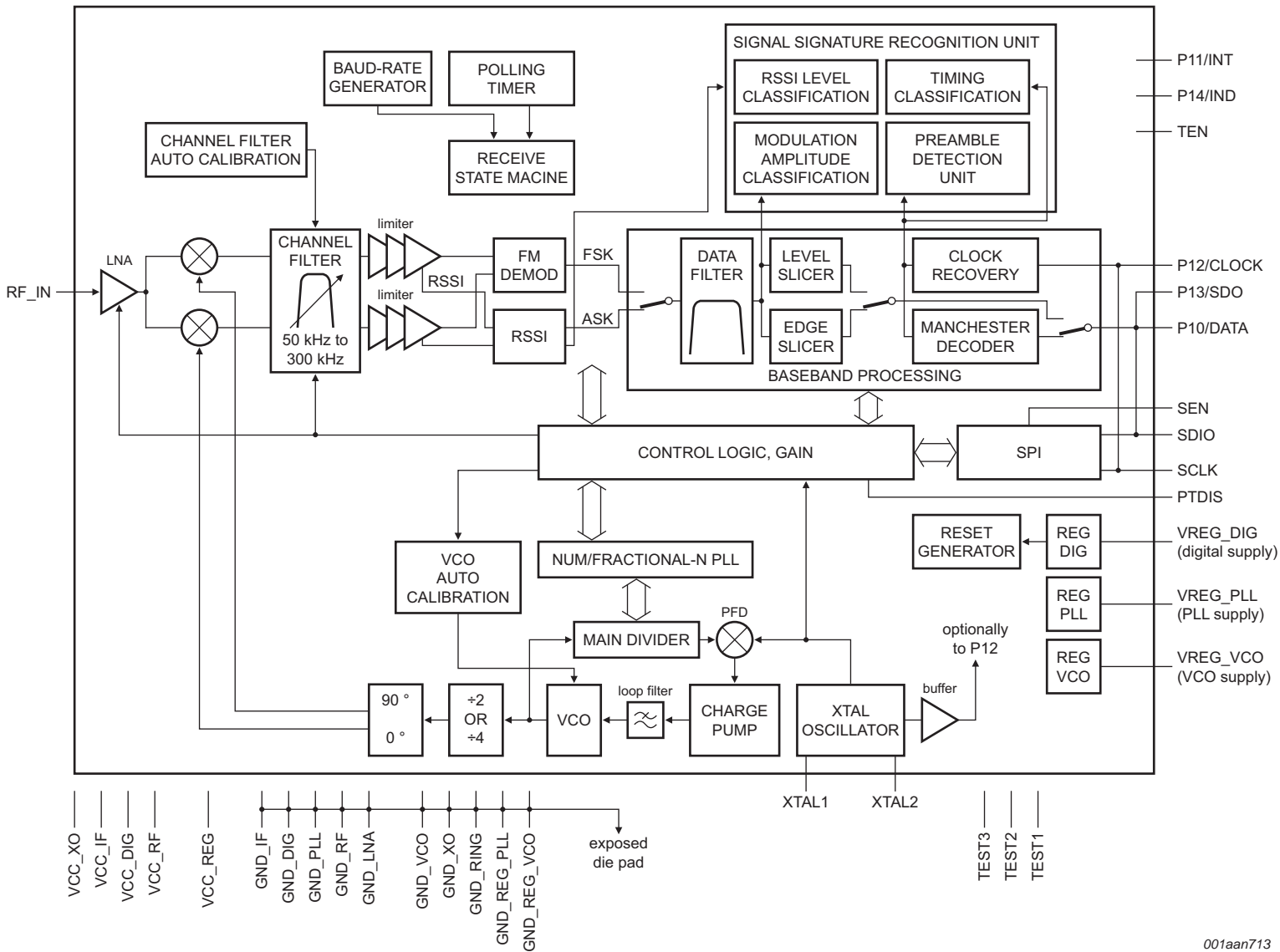- 32-Pin HVQFN32 Pb-free package

3. Applications

- Smart metering (wireless M-bus)
- Home and building security and automation (KNX-RF)
- Remote control devices
- After-market Remote Keyless Entry (RKE)
- Wireless medical applications
- Wireless sensor network

4. Ordering information

Table 1.   Ordering information

Type number	Package		Version
	Name	**Description**	
OL2311AHN	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 $\times$ 5 $\times$ 0.85 mm	SOT617-3

5. Block diagram

SIGNAL SIGNATURE RECOGNITION UNIT
RSSI LEVEL CLASSIFICATION
TIMING CLASSIFICATION
MODULATION AMPLITUDE CLASSIFICATION
PREAMBLE DETECTION UNIT
BAUD-RATE GENERATOR
POLLING TIMER
CHANNEL FILTER AUTO CALIBRATION
RECEIVE STATE MACINE
CHANNEL FILTER
50 kHz to 300 kHz
limiter
LNA
RF_IN
FM DEMOD
RSSI
FSK
ASK
DATA FILTER
LEVEL SLICER
EDGE SLICER
CLOCK RECOVERY
MANCHESTER DECODER
BASEBAND PROCESSING
CONTROL LOGIC, GAIN
SPI
VCO AUTO CALIBRATION
NUM/FRACTIONAL-N PLL
RESET GENERATOR
REG DIG
REG PLL
REG VCO
MAIN DIVIDER
PFD
90° 0°
÷2 OR ÷4
VCO
loop filter
CHARGE PUMP
XTAL OSCILLATOR
buffer
optionally to P12
P11/INT
P14/IND
TEN
P12/CLOCK
P13/SDO
P10/DATA
SEN
SDIO
SCLK
PTDIS
VREG_DIG (digital supply)
VREG_PLL (PLL supply)
VREG_VCO (VCO supply)
XTAL1
XTAL2
VCC_XO
VCC_IF
VCC_DIG
VCC_RF
VCC_REG
GND_IF
GND_DIG
GND_PLL
GND_RF
GND_LNA
GND_VCO
GND_XO
GND_RING
GND_REG_PLL
GND_REG_VCO
exposed die pad
TEST3
TEST2
TEST1

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(1) All internal domain grounds including external GND pins 1, 8, 9, 16 and 32 are connected to the exposed die pad.
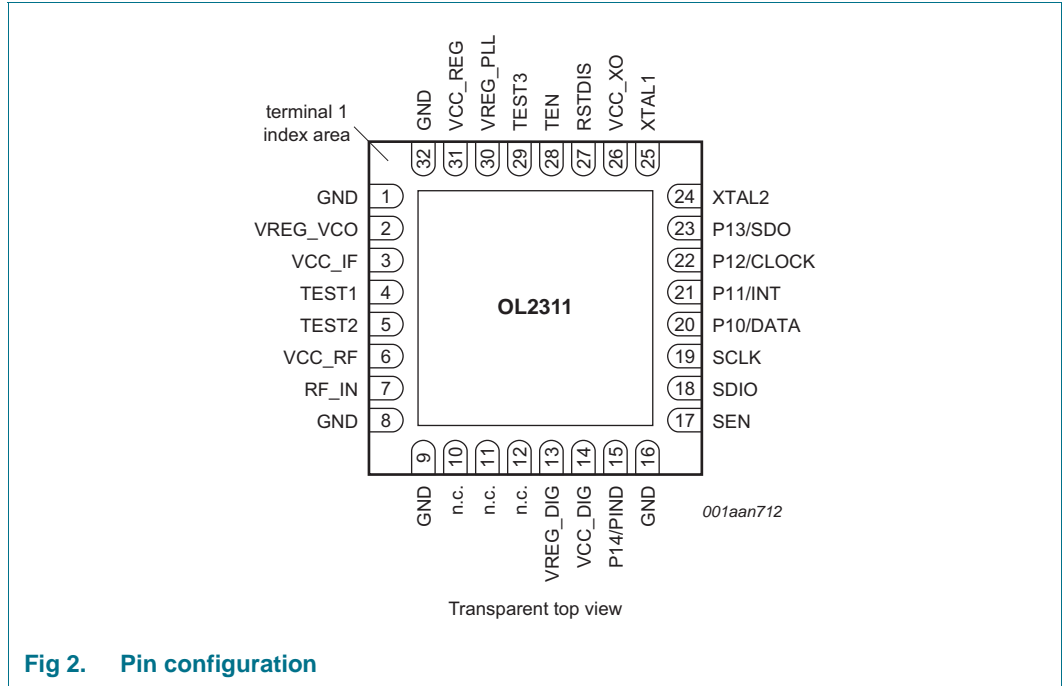
Fig 1.   Block diagram

6. Pinning information

6.1 Pinning

Fig 2. Pin configuration

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Type	Reset state	Description
GND	1	-	-	ground; use exposed heatsink as ground reference
VREG_VCO	2	A	Z	VCO regulator output voltage to decoupling capacitor
VCC_IF	3	A	A	IF section power supply
TEST1	4	A	Z	RX test I output
TEST2	5	A	Z	RX test Q output
VCC_RF	6	A	A	LNA power supply
RF_IN	7	A	A	RX RF signal input
GND	8	-	-	ground; use exposed heatsink as ground reference
GND	9	-	-	ground; use exposed heatsink as ground reference
n.c.	10	A	Z	not connected
n.c.	11	A	Z	not connected
n.c.	12	A	A	not connected
VREG_DIG	13	A	A	digital regulator output voltage to decoupling capacitor
VCC_DIG	14	A	A	digital module supply voltage
P14/PIND	15	DO	Z	digital output port with increased drive capability for PIN diode control
GND	16	-	-	ground; use exposed heatsink as ground reference

Table 2.   **Pin description** …continued

Symbol	Pin	Type	Reset state	Description
SEN	17	DI	DI	serial interface enable
SDIO	18	DIO	DI	serial interface input/output
SCLK	19	DIO	DI	serial interface clock
P10/DATA	20	DIeO	Z	digital output port, RX data output, data output of debug interface
P11/INT	21	DO	POR, interrupt output	digital output port, interrupt output, several status indicators, reference clock output, frame indicator of debug interface
P12/CLOCK	22	DO	1 MHz reference clock	digital output port, RX data clock, clock of debug interface
P13/SDO	23	DO	Z	digital output port, status indicators, serial interface data output
XTAL2	24	A	A	crystal reference clock frequency input
XTAL1	25	A	A	crystal connection
VCC_XO	26	A	A	crystal oscillator supply voltage
RSTDIS	27	DI	DI	reset disable signal
TEN	28	DI	DI	test enable input
TEST3	29	A	Z	PLL test output
VREG_PLL	30	A	Z	PLL regulator output voltage to decoupling capacitor
VCC_REG	31	A	A	PLL, VCO regulators power supply
GND	32	-	-	ground; use exposed heatsink as ground reference
exposed die pad	-	A	GND	ground connection

[1]   A = analog.

DI = digital input.

DO = digital output with enable signal.

DIO = digital input without enable signal and output with enable signal.

DIeO = digital input and output both with enable signal.

7.   Functional description

7.1   General architecture description

The OL2311 receiver is designed for use in both complex base-stations, when paired with powerful microcontrollers, and low component-count remote units with low pin-count microcontrollers. The IC features unique configuration possibilities via external pin-level configuration or SFR bit manipulation. Several automatic sequences are implemented to ease device operation, all of which can be manually influenced or overridden by control-bits.

7.1.1 Power management

The device contains a configurable power-on reset block. The device control registers are reset as the external voltage rises to ensure that the device state is in Standby mode. This is implemented by ensuring that all blocks are off except the SPI and the digital regulator. Note that the digital regulator is operating in clamp mode at this time.

7.1.2 XTAL oscillator

The main time-reference is derived from an amplitude-controlled XTAL oscillator. This 16 MHz reference is used as a reference clock for the PLL and as a timing reference for various analog calibration purposes.

7.1.3 Polling timer

Several base-station applications require a low-power polling timer for periodic device wakeup. This feature is essential to enable listening in pre-programmed time-windows when the OL2311 is used in RX mode applications. Internal configuration and trimming registers allow the setting of a wide range of different timer intervals while achieving an average timing accuracy of 2 %.

7.1.4 VCO calibration

On-chip calibration is available to reduce the VCO input voltage range and thus reduce the PLL loop bandwidth variation. The variation in system parameters such as locking time and LO phase noise can therefore be maintained within a tight window.

Calibration is performed by selecting the proper VCO sub-band according to the desired channel frequency. VCO sub-band selection and the PLL start-up sequence can be triggered by command and are supported by an automatic flow sequence. This flow can be overridden if required. Note that if the incorrect sub-band is chosen the VCO calibration is unable to tune to the desired frequency.

7.1.5 RX block

The OL2311's RX path consists of a broadband resistive-feedback LNA, a mixer (mixing down the input signal to an IF of 300 kHz), a channel-filter, a limiter, an RSSI stage (AM demodulation) and a base-band signal processing block used for FM and AM data and clock recovery. The LNA, limiter and channel-filter gain settings can be configured via control bits. The channel filter bandwidth can also be adapted.
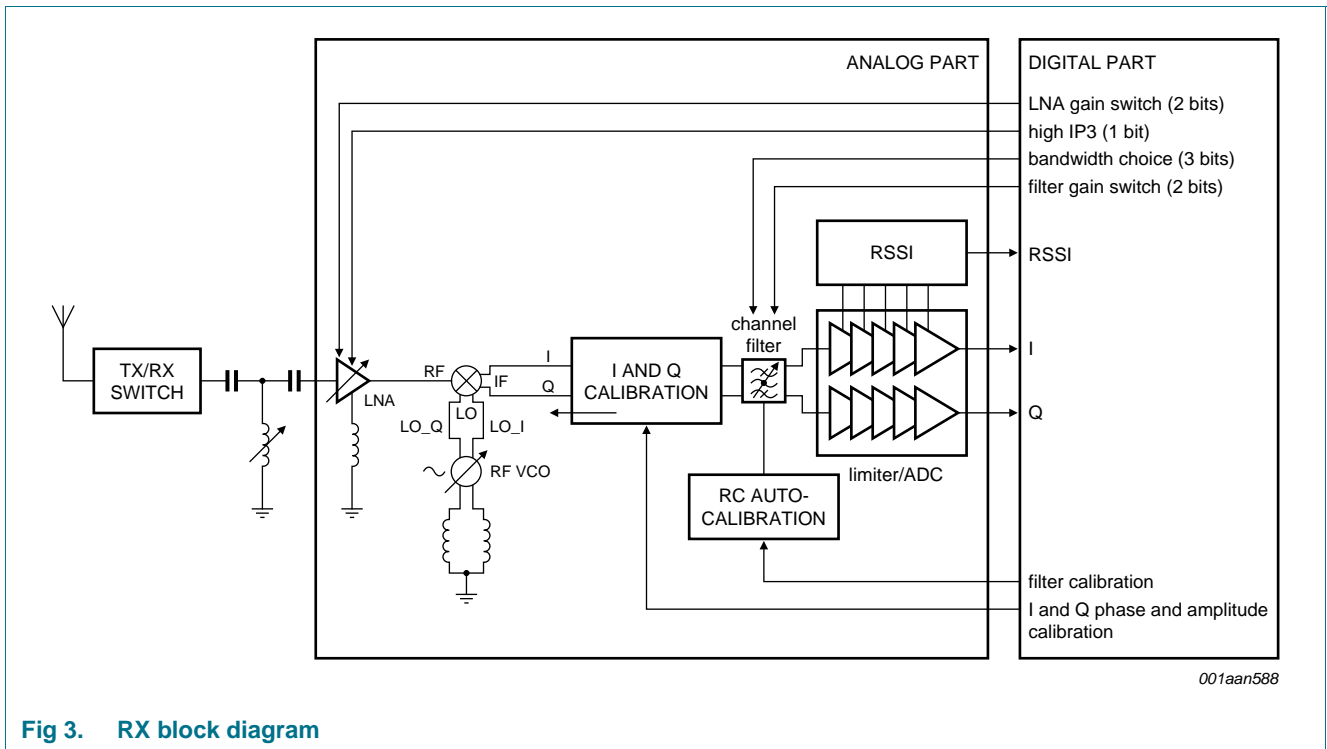
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Fig 3. RX block diagram

7.1.6 Channel filter auto-calibration

Channel bandwidth accuracy requirements vary between applications. The modulation bandwidth changes with different bit rates. Bit rates can be 0.5 kbit/s to 112 kchip/s and the IF channel filter bandwidth must be set accordingly in the range 50 kHz to 300 kHz.

Channel bandwidth auto-calibration is implemented to maintain constant performance. This ensures stable cut-off frequencies and filter roll-off over process and temperature variations. This calibration is included in the RX command.

7.1.7 I/Q calibration

I/Q calibration can be implemented to improve the channel image rejection for certain applications. This calibration improves amplitude mismatch and phase quadrature between I and Q signals.

Both parameters can be trimmed by injecting an external RF signal operating in the image channel. The RSSI can then be used to determine the optimum settings to have the minimal remaining signal. This calibration is required for each frequency band.

The I/Q calibration settings are made available to -, and must be stored by, an external microcontroller.

7.1.8 Receive command

The predefined set of RX parameters (center frequency, modulation, etc.) enables Receive mode (receiver and LO buffers switched on) to be entered quickly after receiving the RX command. Several methods of signal signature recognition are implemented. These modes of semi-automatic signal processing can be pre-selected by the RX command.

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7.1.9 Signal signature recognition unit

Several signal recognition units are implemented to provide fast and accurate signal detection. Signal signatures such as signal level (RSSI), modulation depth or baud-rate and coding can be automatically detected as wakeup criteria during the wakeup search phase.

7.1.10 Preamble detection

A configurable 1 to 32-bit pattern recognition unit can be implemented to aid power saving and avoid unintended wakeup due to ambient noise.

7.2 General operation

The OL2311 is a state machine-based receiver to be used in conjunction with a microcontroller. Study this datasheet carefully to help choose the appropriate OL2311 configuration for a specific application. The interface to the microcontroller must be defined first, see Section 7.3. Next, the correct basic settings must be identified. The operational frequency band must be chosen, all relevant registers must be programmed (exact setting of desired frequency, IF bandwidth, baseband filtering, etc). It is strongly recommended to study every aspect of this datasheet in detail and to verify correct device operation by measuring available debug-signals. The optimum operation and the highest device performance is achieved by fine-tuning and verification of all device settings. Use the automatic operating sequences after determining the optimum device configuration. Generally, the first operation is to bring the device from standby to power-up state, which is the precondition for any operation. This can be done manually, triggered by the external microcontroller, or automatically by the built-in polling timer. In this device mode, the XTAL oscillator is operational. SFR register bits (configuration data) can be changed. This mode can be left by issuing an RX command. To save power and operating time the command can be prepared by the 'prepare RX' command.

7.3 Interface description

7.3.1 Port connections

The minimum connection between a host controller and the OL2311 comprises three SPI lines: SDIO, SCLK and SEN. SPI communication and data transfer can be achieved by multiplexing the SPI data and clock lines. The host controller's SPI must be set in slave mode after the RX command is sent, the SCKL then shifts the out/in data via the host controller's SPI.
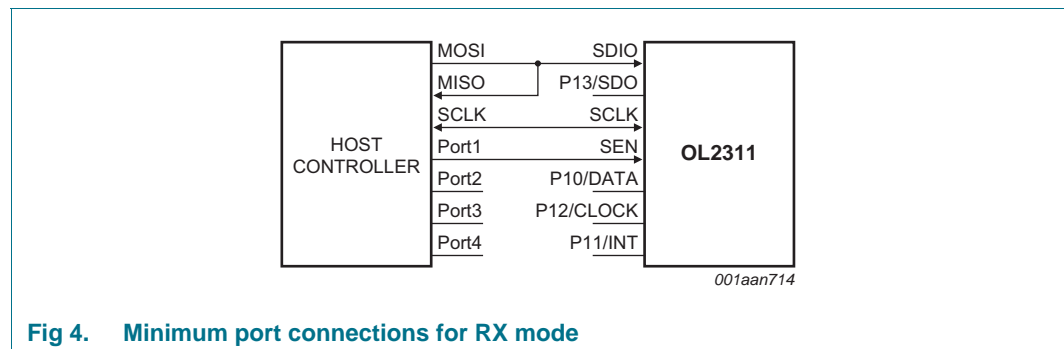

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Fig 4. Minimum port connections for RX mode

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The device also supports full four-line SPI mode, the line SDIO serving as data input and P13/SDO as data output.

Alternatively, the device can be configured for separate data inputs and outputs. The lines SDIO, SCLK and, if selected, P13/SDO can be reserved for SPI command handling. In this case, RX data is handled by the port pin P10/DATA, the clock is carried by port P12/CLOCK. The OL2311's remaining ports can be used for additional status information.
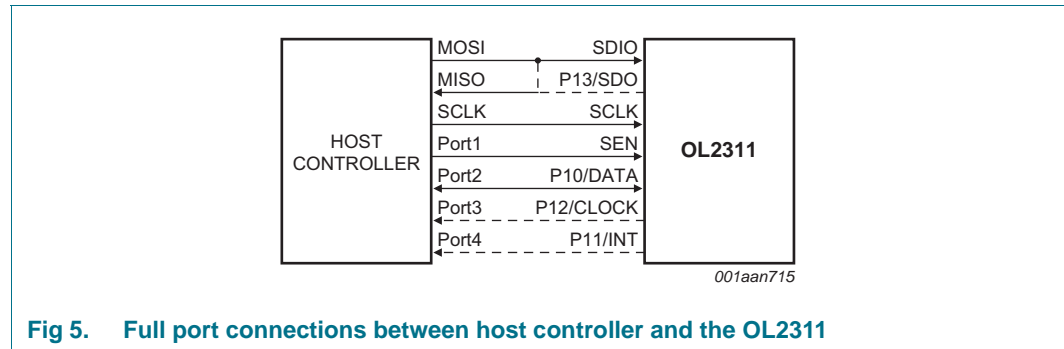

Fig 5. **Full port connections between host controller and the OL2311**

7.4 Special ports

7.4.1 TEN

The test enable input (pin TEN) must always be connected to GND. This pin is only required for a factory test and has no user-operable functionality.

7.4.2 TEST1, TEST2 and TEST3

Test pins for internal analog test-signals. In the application, these pins must be left open.

7.4.3 RSTDIS

The status of pin RSTDIS defines the polling timer state enable bit after power on. When the pin is LOW, the device is initialized with the polling timer enable bit set to 1.

7.5 General purpose ports

The device features five general purpose ports: P10 to P14, with selectable dedicated user functions; see Section 7.8.3 "Reset and power mode register" on page 15. The port function is controlled by bits P1xCx. The width of these control bits for every port depends on the number of selectable signals.

All general purpose ports, except P11/INT and P12/CLOCK, are in 3-state after power-on reset. Port P11/INT is initialized as an output driving the active-LOW POR interrupt. Note that this interrupt is non-maskable.

Port P12/CLOCK is initialized to provide a 1 MHz reference clock as the default output.

7.5.1 P10/DATA

Priority of functions:

- Output signal of receiver debug interface
- RX data output, if bit SEP_RX_OUT is logic 1 and the receiver is activated

If register PORTCON2 bit SEP_RX_OUT is set and if P12C[2:0] = 010b, the port delivers the RX clock associated with the data provided at P10/DATA. This clock is activated after the RX DATA command's ninth SCLK pulse. If the RX command is a PRDA, this clock is activated after successful preamble detection. In both cases the clock continues as long as the receiver state machine is in its DATA state. This clock is recovered from the RX signal timing and informs the controller when it can sample the data delivered at the P10/DATA line.

Note that in contrast to P10/DATA, where setting bit SEP_RX_OUT overrules the normal port function, this is not the case for P12/CLOCK. The clock is only output if selected when P12C[2:0] = 010b.

Bit P10INV inverts output data, including RX data.

7.5.2 P11 and P12

P11 and P12 together with P10, form the serial interface when the receiver debug mode is activated; see Section 7.32 "RX debug interface" on page 72.

7.5.3 P14

P14 can be used to control an external circuit, such as a RX switch or an LNA.

7.6 Serial configuration interface description

7.6.1 General SPI information

The chip is configured via a three- or four-wire serial interface consisting of an 8-bit shift register and 80 × 8-bit registers holding the configuration data.

Data can be exchanged with multiple 8-bit frames (auto-incrementing) or in portions of 8 bits (1 byte), which provides an advantage when using a hardware SPI-interface. Data in the shift register is loaded into the addressed register on the last edge of SCLK within the last bit of the transferred byte.

7.6.2 SEN

A logic LOW applied to pin SEN disables the SPI interface. The internal state machine halts and every activity on pins SDIO and SCLK is ignored.

If the device is in Power-down mode, a positive edge on pin SEN activates the device. The crystal oscillator is always on, unless the device is in Power-down mode. The watchdog is cleared with a HIGH level on pin SEN; see Section 7.11 "Watchdog" on page 23.

7.6.3 SCLK

SCLK is the clock pin for the serial interface. Every edge of SCLK shifts data into or gets data from the SPI register-set. The second clock edge (SCLK) is used for data capturing. SDIO direction switching between input and output is accomplished with the first clock edge of the ninth bit. An additional clock edge is necessary at the start of a RX command.

The clock polarity for an SPI command can be selected; see Section 7.6.5.

If desired, pin SCLK can carry the recovered RX clock during a RX command.

7.6.4 SDIO

SDIO is the serial interface's bidirectional data input/output pin. Data in or data out operation is adapted automatically during SPI communication sequences.

If desired, pin SDIO can be used to input RX data if a RX command is active.

7.6.5 General SFR access information

If SCLK is HIGH at the rising edge of SEN, the data is transferred with the rising edge of SCLK; see Figure 6 and Figure 7. If SCLK is LOW at the rising edge of SEN, the data is transferred at the falling edge of SCLK.

For continuity, all figures and examples in this data sheet assume SEN is LOW at the rising edge of SCLK, unless otherwise stated. The first edge of SCLK is referred to as the rising edge and the second as the falling edge.

7.7 Write and read access to SFR

7.7.1 Write access to SFR

Fig 6. **Write serial interface timing diagram**

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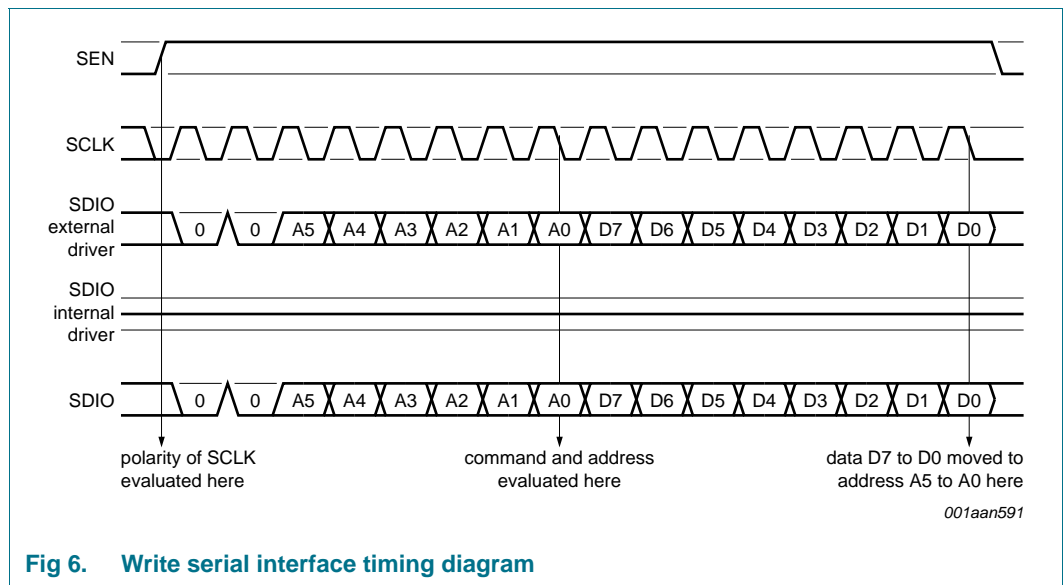
7.7.2 Read access to SFR
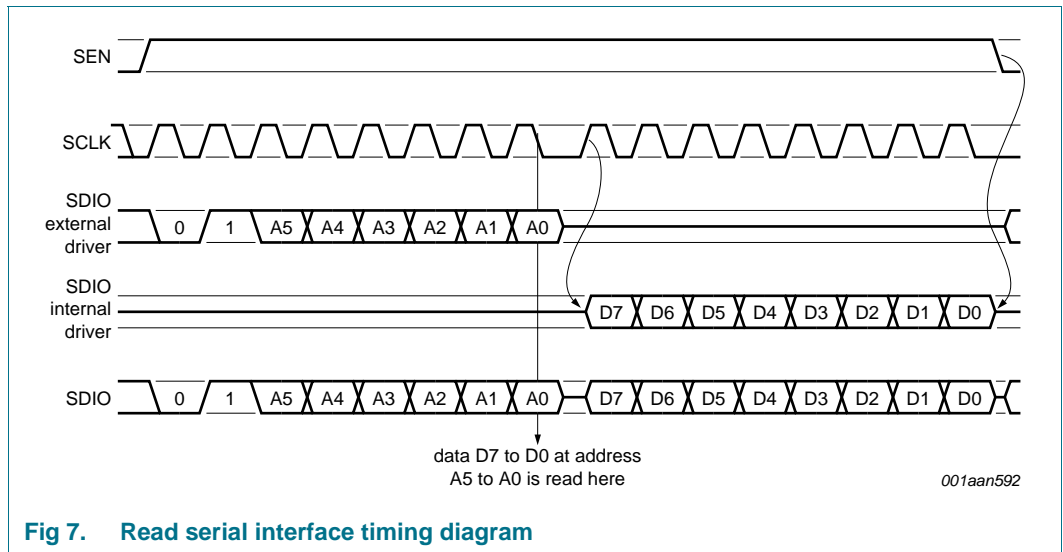
Fig 7. **Read serial interface timing diagram**

7.7.3 Separation of SDI and SDO line

A four-wire SPI interface can be implemented using pin SDIO for MOSI and pin P13/SDO for MISO. Timing and output control of pin SDO is the same as for the internal SDIO driver.
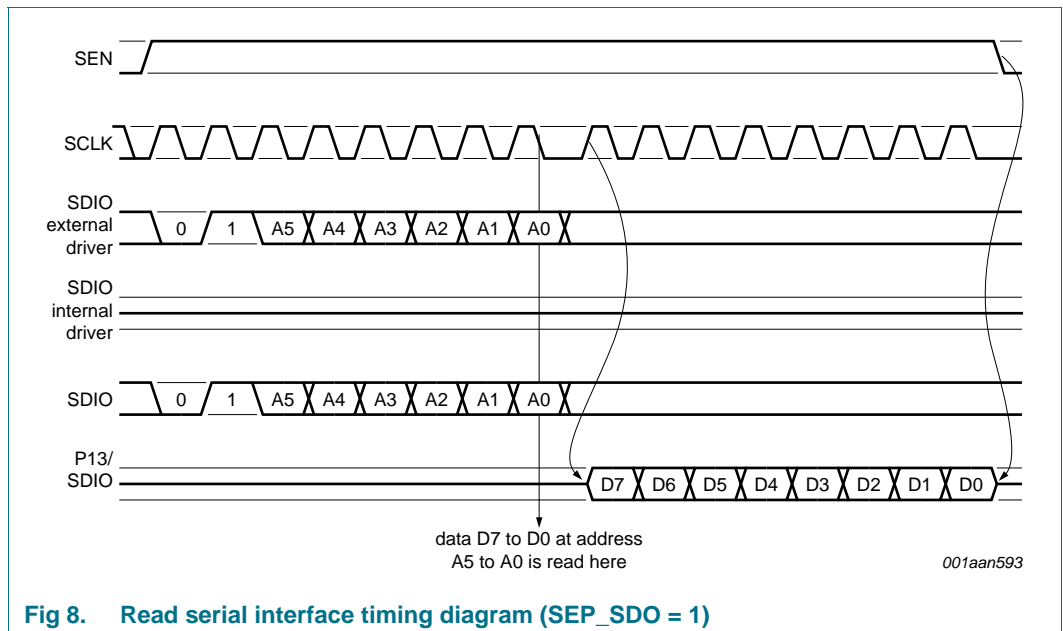
7.7.4 Read access to SFR with separate SDO line

Fig 8. **Read serial interface timing diagram (SEP_SDO = 1)**

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7.7.5 Read and write access to SFR with auto-increment function

If the SPI clock (SCLK) is still applied after the first 8 data bits are transferred, the auto-increment function automatically increments the address by one for the following 8 data bits. This enables data to be written to a continuous range of bytes without having to set the address for every single data-byte. The auto-increment function is terminated on the falling edge of SEN.

If the address reaches the end of the address range (3Fh) an additional increment causes the address to start at 00h again. This wrap around is accomplished in the current address bank. The auto-increment function has no influence on the bank selection.

7.7.6 Write access to SFR with auto-increment function
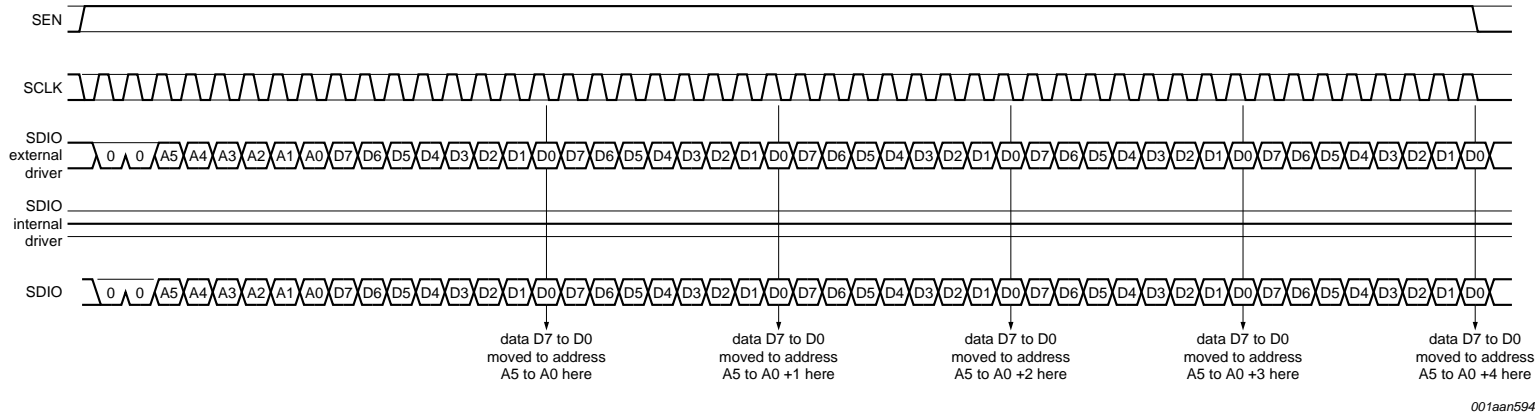
Fig 9. Write serial interface auto-increment timing diagram

SEN must be forced LOW after registers are written to indicate end of write. Figure 9 is an example showing 5 successive bytes stored.

7.7.7 Read access to SFR with auto-increment function
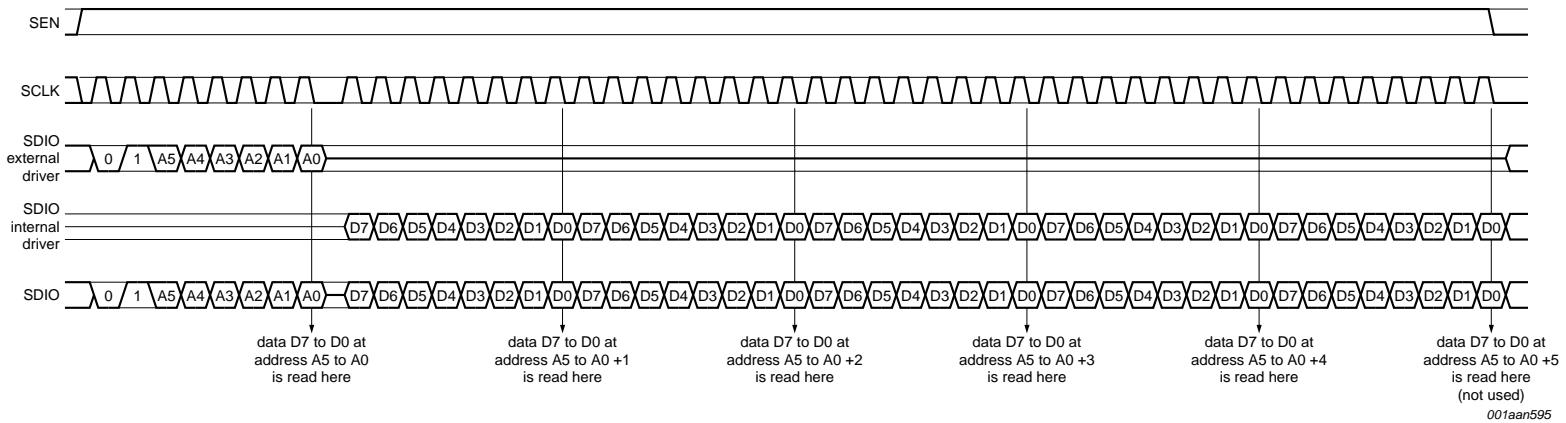
Fig 10. Read serial interface auto-increment timing diagram (SEP_SDO = 0)

SEN must be forced LOW after registers are read to indicate end of read. Figure 10 is an example showing 5 successive bytes read.

7.8 Device mode description

7.8.1 Automatic start-up procedures

The device features the following automatic start-up procedures for easy device handling and configuration:

- Power-on and crystal oscillator start-up
- PLL and VCO start-up including calibration
- Preparation for RX mode
- VCO auto-calibration at every centre frequency change

7.8.2 General description

The automatic start-up procedures are implemented to aid the quick and easy transition between operational states. Most procedures are controlled by changing bits in the PWRMODE register. Certain configurations can be directly entered by the RX command.

7.8.3 Reset and power mode register

The PWRMODE register acts as the device's 'main power on/off/standby switch'. Setting the RESET bit of this register brings the device into the reset condition equal to the power-on reset state. This power-down state is also reached automatically at first power-on (battery insertion). If this bit is set with a write command, the effect on all registers with a reset condition is a 'hard-reset'. If, with the same SPI write command, other bits are simultaneously written to the PWRMODE register, they are changed automatically to the power-on reset state; see Section 8.2.1.10 "General power mode register PWRMODE" on page 87.

7.8.3.1 First power-on reset

The non-maskable interrupt flag IF_POR is set when the initial power-on reset takes place (battery insertion).

7.8.3.2 Power-down

Setting bit PD brings the device into low current consumption standby mode. All analog receiver and transmitter circuitry including the crystal oscillator are turned off and all dynamic digital activity is stopped. Only the SPI and the polling timer, if enabled, are active. Bit PD is also under automatic device control and is set under the following conditions:

- power-on reset or setting bit RESET (setting bit RESET overrides all others)
- the watchdog timer times out

7.8.3.3 Device mode states

Three important static device internal enable signals are decoded from DEV_MODE: PLLEN and RXEN.

- PLLEN is set whenever the DEV_MODE is not logic 00
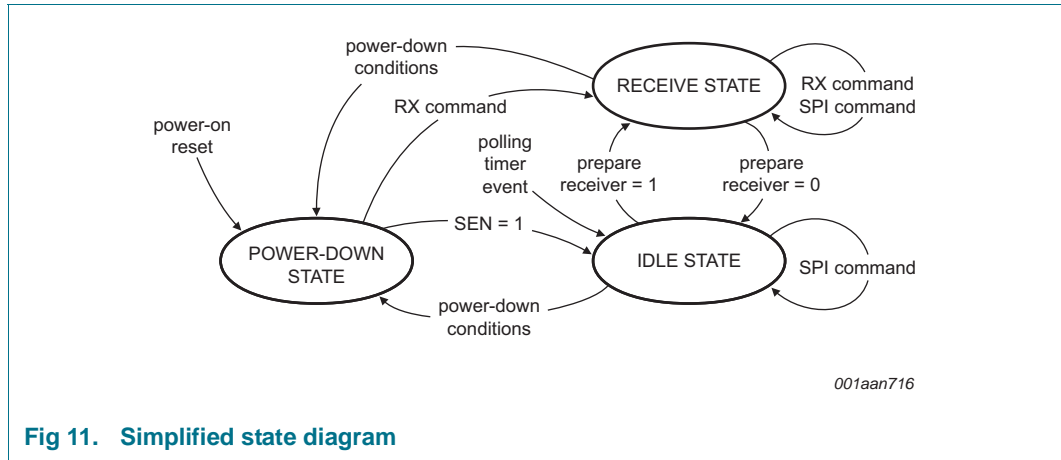- RXEN is set only if DEV_MODE is logic 10

Fig 11. Simplified state diagram

DEV_MODE bits can be either set directly by writing the PWRMODE register or by sending a RX command, where a RX command sets DEV_MODE to logic 10.

Setting bit RESET or setting bit PD (power-down) resets DEV_MODE to logic 00, where only the crystal oscillator is (potentially) enabled.

7.8.4 Flow description

The following actions are performed if the device leaves power-down state and enters active state. The internal control signals of these states are explained in more detail in later sections.

Power-down state indicator is cleared.

7.8.4.1 Digital regulator start-up

The digital voltage regulator is turned on whenever the device leaves the power-down state.

7.8.4.2 XTAL oscillator start-up

The crystal oscillator or the buffer for the external clock is turned on depending on the states of CLOCKCON register bits XODIS and EXT_CLK_BUF_EN.

Bit XO_RDY is logic 1 once the crystal oscillator has settled. The device waits for several clock periods until the clock output's frequency and duty cycle have fully settled to within the required specification. The end of this waiting period is indicated by bit REFCLK_RDY changing to logic 1. This enables the master clock gate at the root of the clock distribution tree and if applicable, the reference clock for the digital section is enabled. A polling timer recalibration is also initiated at this point.

7.8.4.3 PLL start-up

This sequence is controlled by the internal control signal PLLEN. The voltage regulators for the PLL and VCO (REG_VCO_ON, REG_PLL_ON) are turned on.

Wait until the voltage regulators have settled. This sequence ends, if LO_PWR_RDY = 1.

7.8.4.4 Turn on VCO

The phase frequency detector (PFD_ON), prescaler (PRESC_ON), clock for the PLL (CLK_PLL_ON) and PLL lock detection are turned on with the next clock cycle.

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7.8.4.5 Perform VCO calibration

This sequence is complete once the PLL is locked (LO_RDY is set). A manual VCO calibration immediately stops any RX command.

7.8.4.6 Preparation for RX mode

This mechanism is invoked by issuing device mode logic 10 (prepare for RX) or by sending a RX command.

The bandgap reference circuit for the receiver section (bit RX_GAP_ON), VCO clock divider for the receiver section (bit PLL_LOCK), reference clock for the RX path (bit CLK_RXA_ON), and the analog section of receiver (bit RXA_ON) are enabled.

7.8.4.7 Perform channel filter calibration

The channel filter calibration is performed every time the device enters RX mode. This sequence ends if the channel filter calibration ends.

7.8.5 Changing device modes

Intermediate device modes may be required in an operation sequence e.g. start digital regulator and XTAL to initialize/change SFR contents or to re-trim the polling timer. This can be carried out by changing the corresponding registers. However, the direct commands may be more useful if the only operation required is the entering of RX mode. The corresponding sequences start automatically and operation enabled after all internal settling times are met.

7.8.6 Interrupts

TheOL2311 can generate various interrupts which can be enabled by the IEN register and read from the IFLAG register; see Section 8.2.1.11 "Interrupt enable register IEN" on page 88. The IFLAG register is always cleared after it is read. Certain pins can also be configured to present these interrupts; see Section 7.3 "Interface description" on page 8.

7.9 Power supply and reset

Each main functional block is equipped with its own dedicated supply voltage pin. Therefore, several supply pins are available on the package and all must be connected. Note that all ground connections of these functional blocks are bonded to the exposed die pad of the package (metal plate underneath the die). Some blocks are supplied via dedicated integrated low-dropout voltage-regulators. Note that for all regulators the output voltage is available both internally and externally on a pin for connection of a decoupling capacitor. The following blocks have regulated supplies.

Table 3.   Blocks with regulated supplies

Block	Regulator supply pin	Pin to decouple
PLL	VCC_REG	VREG_PLL
VCO	VCC_REG	VREG_VCO
digital	VCC_DIG	VREG_DIG

7.9.1 Voltage regulators operation

All regulators are operated automatically by selecting the corresponding device modes. The device modes are set by DEV_MODE[1:0] in register PWRMODE; for details see Section 7.8.3 "Reset and power mode register" on page 15.

The regulators can also be independently controlled by the control bits located inside the TEST registers. Individual operation of the voltage regulators can be necessary for debug or measurement purposes. The following paragraphs describe each individual regulator and its purpose.

7.9.2 Digital regulator

Before the device can be operated, the digital regulator must be switched on. In standby state (power-down state) the digital regulator is bypassed and supplies the digital section with a low supply voltage to guarantee data retention in the configuration registers. If the digital regulator is switched on, the voltage reaches its stabilized value of approximately 1.8 V. The digital regulator can be activated or deactivated by bit REG_DIG_DIS in TEST1 register. Clearing the bit enables the regulator, depending on the selected device mode. Setting the bit always disables the regulator.

7.9.3 PLL regulator

To start any PLL operation the PLL regulator must be switched on. This happens automatically with operation of bit REG_PLL_ON in the TEST2 register.

Remark: this bit only starts the PLL regulator, all PLL functional blocks are enabled individually by separate control-bits.

7.9.4 VCO regulator

For stability and immunity reasons the VCO is supplied via an independent voltage regulator. This regulator can be manually controlled via bit REG_VCO_ON in the TEST2 register.

Remark: this bit only starts the VCO regulator. VCO operation is enabled individually by a separate control-bit.

7.9.5 Device reset

A device reset occurs whenever the supply voltage is applied on the VCC pins (battery insertion). The device utilizes two power-on detection mechanisms, one digital and one analog. These reset circuits constantly monitor the supply voltage. Setting bit RESET in the PWRMODE register performs the same operation by software. This is equivalent to a power-on reset. If bit RESET is set via a command, it is cleared automatically when SPI signal SEN goes LOW after the next write register command.

7.10 Main control and timing blocks

7.10.1 Crystal oscillator

7.10.1.1 Circuit description

The crystal oscillator is the source of the reference clock for the PLL, the digital section and the mixed signal blocks in the receiver chain. The crystal oscillator circuit diagram is shown in Figure 12.
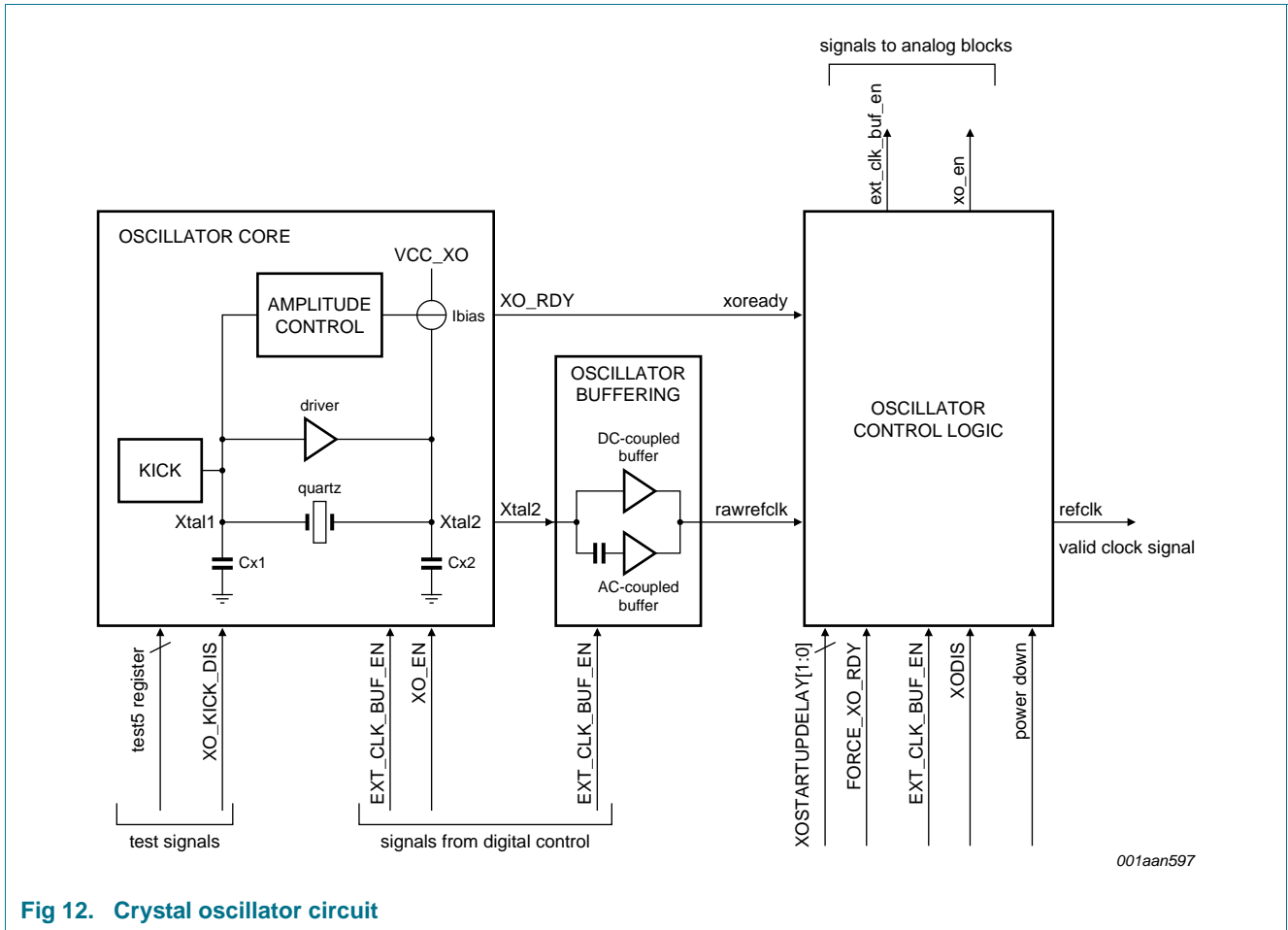
Fig 12. Crystal oscillator circuit

The crystal oscillator consists of three main blocks: the oscillator core, the oscillator buffer and the oscillator control logic.

The oscillator core is a low power quartz based Pierce oscillator. The oscillation frequency is defined by the quartz and the tuning capacitors CX1 and CX2. The driver's low capacitance has negligible impact on the frequency value. The oscillator core is supplied by pin VCC_XO.

When the oscillation starts and the amplitude successfully detected, the amplitude control releases the signal XO_RDY to the oscillator control logic for validation. This signal indicates that the amplitude control loop has entered regulation mode and not that the oscillator has settled. An extra delay is still needed to ensure the frequency accuracy; see Table 98 "XOSTARTUPDELAY bit functions" on page 108.

After start-up, the amplitude control avoids clipping and excessive driving power in the crystal unit.
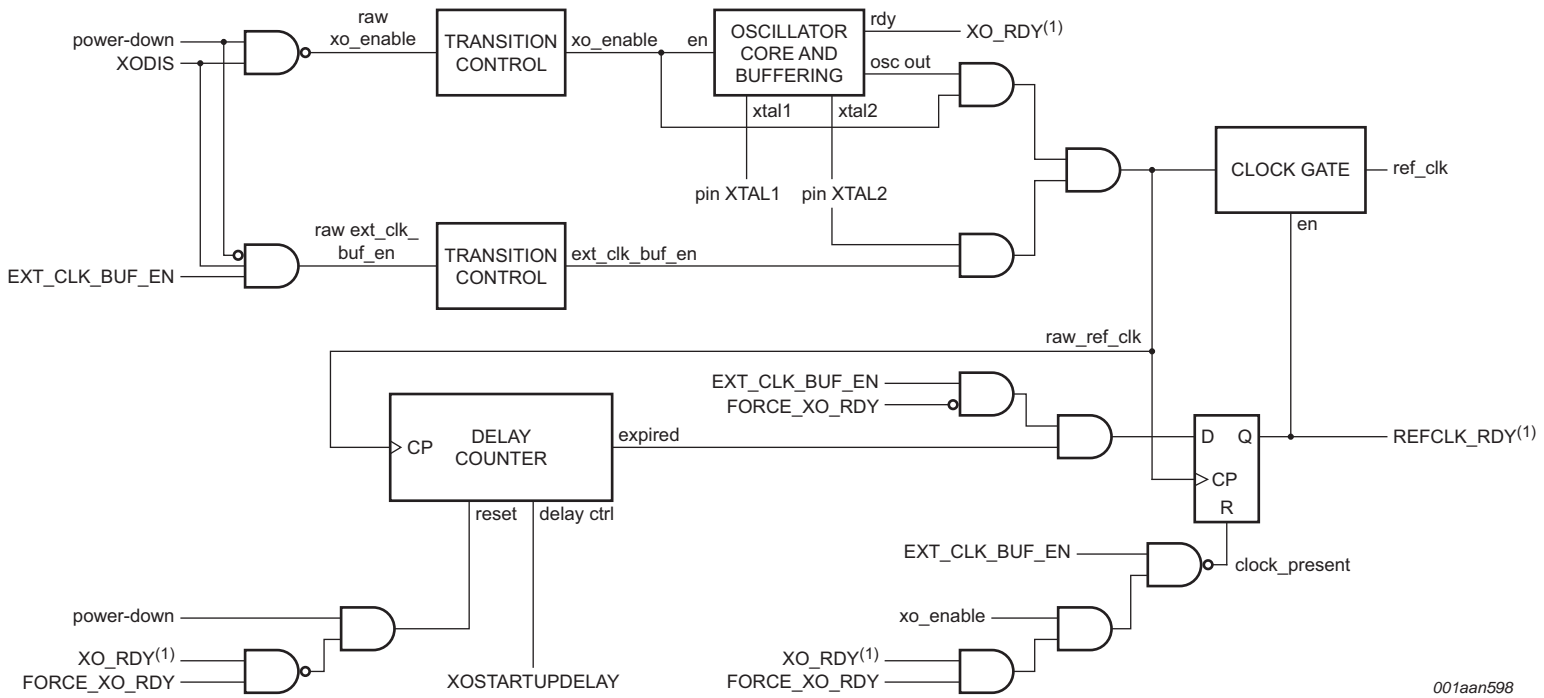
The oscillator control logic validates the oscillator signal and provide configuration facilities. The oscillator control logic is supplied by the digital regulator to the level VREG_DIG.

The oscillator buffer consists of two amplifiers connected in parallel: one low-noise AC-coupled amplifier for crystal operation and one high-input voltage DC-coupled amplifier for testing purposes only. The buffer plays the role of level-shifter for the signals in PLL and digital supply domains. The buffer circuitry is supplied by the PLL and digital regulators accordingly.

Alternatively, an external clock signal can be applied at pin XTAL2; see the external clock buffer description in . The applied signal must comply with the logic levels in the digital core (0 V for LOW and 1.8 V for HIGH). With the OL2311 properly configured, the DC-coupled amplifier replaces the low-noise AC-coupled amplifier. This provides the possibility to skip the internal oscillator's start-up sequence and also allows the customer to stop the clock sequence for test purposes.

Remark: The use of an external clock signal requires special care in the hardware configuration. The oscillator core circuitry connected to pin XTAL2 cannot withstand levels higher than 2.8 V. Therefore, the use of this test mode with supply voltages higher than 2.8 V requires a hardware modification for pin VCC_XO. The recommended solution is to connect pin VCC_XO to pin VREG_DIG. In that configuration the circuit's integrity is ensured but the digital noise needs to be considered.

The crystal oscillator is always active either in oscillator mode or in external clock buffer mode when the device is not in Power-down state.

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(1) Denote internal and official status signals.

Fig 13.   Diagram for crystal oscillator with clock selection circuitry

7.10.2 Oscillator control and control bits

The oscillator control logic is described in Figure 13. Upper case signal names denote control bits in the OL2311's register set. Upper case signal names labelled '(1)' denote (internal and 'official') status signals. Lower case signal names denote internal signals.

The enable logic is visible at the top left corner for both modes: the crystal oscillator mode and the external clock buffer mode. The crystal oscillator is turned on when both, power-down and XODIS, are false. The transition control ensures that no glitches can be generated when turning the oscillator on and off. The external clock buffer is turned on when the device is not in power-down mode and both control bits, XODIS and EXT_CLK_BUF_EN are set; see Section 8.2.1.15 "Clock connection register CLOCKCON" on page 90. As a consequence, putting the device in power-down mode disables all clock activity, and turning the crystal oscillator on has priority over turning the external clock buffer on.

If the crystal oscillator is turned on (XO_ENABLE becomes true) and a crystal is connected to the oscillator, the raw clock becomes available after the oscillation reaches a significant amplitude, which is then signalled with the internal XO_RDY status signal. This internal status signal can be routed to pin P12/CLOCK for observation. While the crystal oscillator is disabled, it is ensured that the clock from this clock source is held at the zero level.

If the external clock buffer is activated (bit EXT_CLK_BUF_EN is true) the signal connected to pin XTAL2 is taken as the clock source. While the external clock buffer is disabled, it is ensured that the clock from this clock source is held at the zero level.

Since only one clock source can deliver a clock at a given time they can be easily merged. The clock is only fed into the circuit when the clock gate is enabled. The following paragraphs explain the conditions for enabling this clock gate separately for each clock source.

When using the crystal oscillator, the delay counter, in Figure 13, is held in reset state during Power-down mode or if both, the internal status signal XO_RDY and the expert control bit FORCE_XO_RDY, are false. If the oscillator signals XO_RDY after start-up (or if the FORCE_XO_RDY is set), the delay counter is released from reset, which lets it count the raw clock pulses from the oscillator. Note that counting will not occur if the oscillation amplitude is too low or if the clock pulses are too 'thin' (duty cycle near 0 % or near 100 %). Therefore it is ensured that the delay counting will not start before the raw clock has a usable shape. After a programmable count (Table 98 on page 108) is reached, the counter stops and signals the end of the delay.

The digital oscillator start-up delay can be controlled by bits XOSTARTUPDELAY[1:0] in register EXPERT1.

After the delay counter's end status reaches the REFCLK_RDY flip-flop, (shown at the lower right corner of Figure 13), it is sampled by the raw clock, now stabilized, and this declares the reference clock ready. This also enables the clock gate which passes the clock on to the circuit starting with the following clock pulse. The REFCLK_RDY status flip-flop is immediately reset when the raw clock is no longer present, which happens when the crystal oscillator is turned off or bit XO_RDY is false due to any reason which may have stopped the oscillation.

Note that special care is needed when non-recommended crystals are used. The use of non-recommended crystals and resonators may have a negative impact on the start-up behavior, on the frequency stability and on the PLL noise performance.

The oscillation amplitude is always large enough for recommended crystals so the amplitude control can properly detect that the start-up and noise generated by the AC-coupled buffering is appropriate for PLL operation.

If the crystal is replaced by a resonator with a low Q factor, the resulting amplitude may not be large enough for the XO_RDY status to be properly detected, although the generated clock may still be usable. To use the OL2311 under such conditions, the XO_RDY status must be overridden by using the expert control bit FORCE_XO_RDY. Note that the delay counting mechanism will not start counting before the raw clock reaches a certain quality.

If the external clock buffer is used, it is assumed that the clock source, which is connected to pin XTAL2, provides a stable clock with a duty cycle close to 50 % at the time when bit EXT_CLK_BUF_EN is set. Therefore the delay counter is not needed in this case. But even without the delay counter, the circuit provides a well-controlled startup sequence, which is enforced by the REFCLK_RDY flip-flop and the clock gate, so that no glitches are generated when the clock buffer is turned on or off. Note that not using the delay counter in this normal case requires the FORCE_XO_RDY expert control bit to be in the cleared state.

However, if bit FORCE_XO_RDY is set when using the external clock buffer, the delay mechanism is activated. This is how the delay counter is tested in the production test but it may also help to overcome start-up problems in the external clock source. The XO_RDY, REFCLK_RDY signals can be observed for oscillator testing via the test buffer. The resulting clock can be probed at pin CLOCK.

7.11 Watchdog

The device features a watchdog timer to recover from situations when activation is not desired. The watchdog timer runs with the reference clock and it is activated, if the device is not in Power-down mode.

The watchdog is cleared and temporarily stopped under the following circumstances:

- Pin SEN is HIGH

- A terminating wakeup search is executed, i.e. either a pessimistic wakeup search is activated (bit WUPSMODE = 0) or the timer for the wakeup search is activated during an optimistic wakeup search (bit WUPSMODE = 1 and bits WUPSTIMEOUT not equal to 0).

- A terminating preamble detection is executed, i.e. the timeout for the preamble must be activated (bit EN_PREADET_TIMEOUT = 1 and bits WUPSTIMEOUT not equal to 0).

Bit EN_PREADET_TIMEOUT can be found in register SIGMON1; see Section 8.2.2.2 "Signal monitoring control register SIGMON1" on page 99. Bit WUPSMODE can be found in register SIGMON0; see Section 8.2.2.1 "Signal monitoring register SIGMON0" on page 98. Bits WUPSTIMEOUT can be found in register WUPSTO; see Section 8.2.2.4 "Register WUPSTO" on page 100.

The watchdog timeout can be adjusted according to Equation 1.

$$watchdogtimeout = 2\frac{15 + WUPSTIMEOUT}{CLK_{REF}} \qquad (1)$$

where:

CLK$_{REF}$ = 16 MHz

watchdogtimeout = desired watchdog timeout

It is not possible to turn off the watchdog completely. The watchdog can be disabled for an arbitrary period only if pin SEN is set HIGH.

7.12 Polling and wakeup timer

The device features a low power oscillator, which can be used to generate wakeup events. A polling timer overflow always generates an interrupt request. Moreover, if selected, the device can be automatically released from the Power-down state and it can enter the RX state.

The low power oscillator has a nominal period of 40 μs and a tolerance of $\pm$ 50 % over the entire temperature and supply voltage range and over process-dependent device spread.
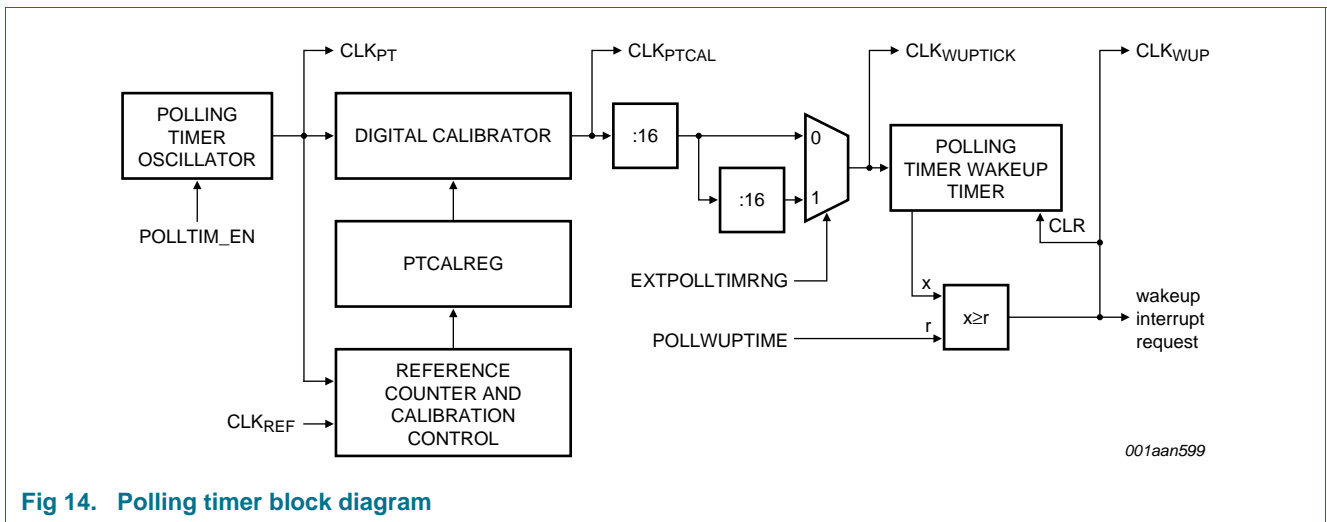

Fig 14. Polling timer block diagram

The polling timer employs a digital calibration with a modulo counter. The crystal oscillator clock CLK_{REF} is used as a reference clock for the calibration. The calibration procedure measures one period of the polling timer clock CLK_{PT} and determines the appropriate calibration value for the modulo counter. The output clock CLK_{PTCAL} has a nominal period of 62.5 μs.

The polling timer can be turned on and off with bit POLLTIM_EN in the PWRMODE register. The state of this bit after a master reset is determined by the level on pin RSTDIS.

Note that due to the absence of the reference clock it is not possible to trim the polling timer directly after a master reset. The calibration register PTCALREG is set to its nominal value after a master reset.

After exiting Power-down mode, the polling timer calibration is triggered automatically if the crystal oscillator starts properly. It is also possible to trigger a manual calibration by setting bit MANUALPTCAL. Setting this bit generates a short pulse, which starts the calibration routine. Reading bit MANUALPTCAL always yields zero. The manual calibration is only executed if the polling timer and the crystal oscillator are running otherwise the request is ignored. Setting bit MANUALPTCAL at the same time as POLLTIM_EN is not supported. The calibration is only performed after the polling timer oscillator settles.

The value in the calibration register is consistent under all circumstances. This must also be the case if a running calibration is interrupted. Direct read or write access to register PTCALREG is not supported.

The polling timer wakeup time can be set with the 8-bit control register POLLWUPTIME. The wakeup time calculates to:

$$T_{WUP} = (POLLWUPTIME + 1) \times T_{WUPTICK}$$ (2)

The achievable resolution and wakeup times can be selected in two different ranges, a normal and an extended polling timer range according to the setting of bit EXTPOLLTIMRNG in the CLOCKCON register.

It is possible to change the register POLLWUPTIME while the polling timer is running. If the new value is greater than the polling timer counter's current content, the running period is not interrupted and the newly set wakeup time is seamlessly adjusted. This mechanism allows the setting of a new wakeup time with respect to the last wakeup event. If the newly set value in register POLLWUPTIME is smaller than the polling timer counter's current content, the counter is reset immediately.

The digital calibration is implemented so that the accuracy of wakeup times greater than 10 ms is better than 1 %. This allows an overall timing error of less than 2 % for the given range.

7.12.1 Actions at polling timer wakeup

Register POLLACTION defines which action the device carries out after a polling timer event; see Section 8.2.1.14 "Polling action register POLLACTION" on page 89.

POLL_MODE[1:0] defines the device's operating mode after a polling timer event.

RX_GAIN[1:0] means the same as the RX flags RE and RF (gain step/switch selection bits). The RX_CMD bit means the same as RX flag RC. It allows a choice between a WUPS (0) and a PRDA command (1). RX_FREQ[1:0] means the same as RX flags RA and RB (frequency selection).

The last bit in the POLLACTION register, SET_RX_FLAGS, defines whether the RX flag register's current content is used for the automatically initiated RX command (if 0) or whether the RX flags RA, RB, RC, RE and RF flags are overwritten with the contents of the RX_FREQ, RX_CMD and RX_GAIN bit settings of this register, respectively, before the command is actually launched (if 1). If the flags are overwritten, RX flag RD is set to logic 1 to make the sub-command either a WUPS or a PRDA command; see Section 7.23.2 "Receive command" on page 42 for more information.

7.13 Baud-rate generator

The baud-rate generator generates the nominal, unsynchronized chip clock according to Equation 3.

$$baudrate = \frac{16\,MHz}{2^{PRESC}} \times \frac{2^{11} + MAINSC}{2^{12}} \times \frac{1}{128}$$ (3)

where PRESC is an exponent in the range from 0 to 7, and 2^{11} + MAINSC is the mantissa in the range 2048 to 4095. The resulting baud-rate clock can jitter by one prescaler clock cycle CLK$_{PSC}$.

The mainscaler MAINSCL lower bits can be found in register TIMING0.

The MAINSCH and the PRESC bits can be found in register TIMING1; see Section 8.2.1.5 "Timing register TIMING1" on page 82.

The divide-by-128 divider is used as a 'clock' for several other blocks to measure the sub-timing within one chip interval.

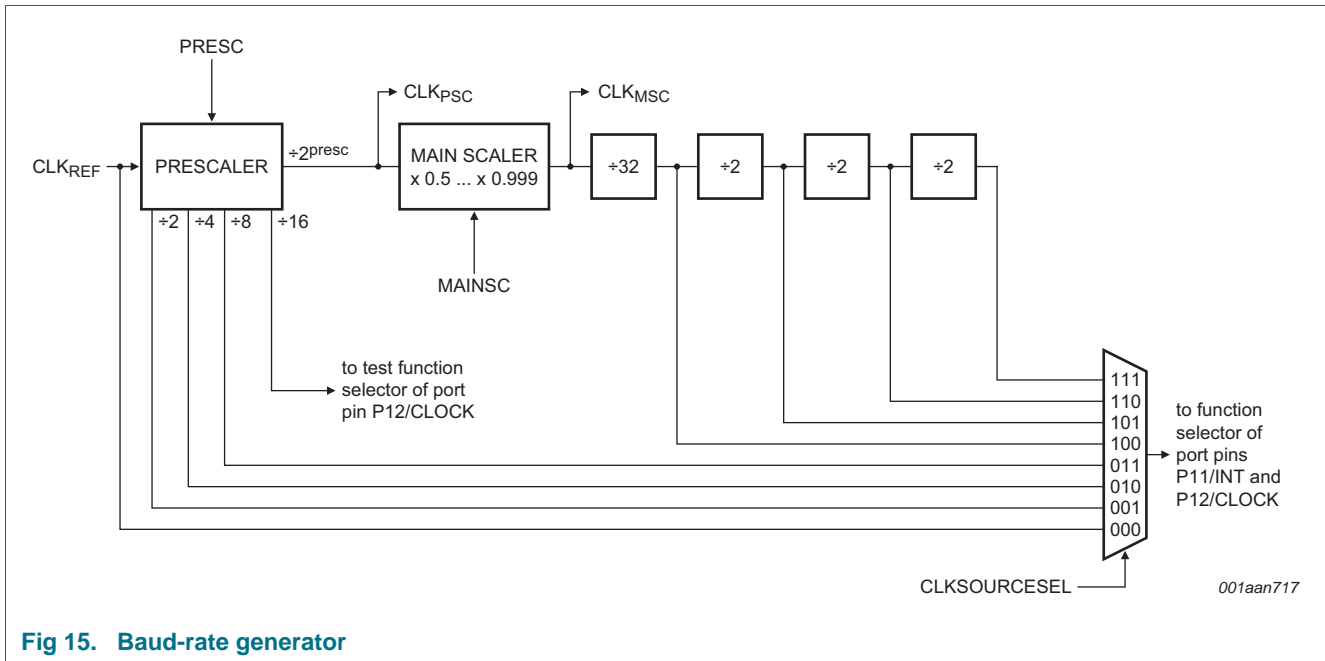This baud-rate generator is used as a time reference for the clock-recovery in RX mode.

Fig 15. Baud-rate generator

Bits CLKSOURCESEL are in register CLOCKCON; see Section 8.2.1.15 "Clock connection register CLOCKCON" on page 90.

7.13.1 Clock recovery for RX mode

The clock-recovery for RX mode is dependent on the baud rate accuracy. If the absolute correct baud rate cannot be selected, choose the next available integer value. The clock recovery is able to cope with a 1 % tolerance to be able to operate correctly with standard XTAL cutting and temperature inaccuracies. The clock recovery is implemented as a digital phase control loop with a fixed operating frequency determined by the baud-rate generator setting. The baud-rate generator's mainscaler clock acts as the reference clock for the clock-recovery PLL (128 times the actual chip clock). The clock recovery PLL is programmable with regards to its settling speed. The settling of the clock-recovery speed can be set to reach its final state within 3, 7, 15 or 31 chips. If the clock-recovery is locked to the bit-stream the actual possible phase-error is proportional to the selected settling speed setting. Highest settling speed (settling within 3 chips) produces the smallest actual phase error due to fast regulation; slowest speed (settling within 31 chips), allows for the largest phase error due to the slowest regulation time constant; see Table 85 "CLOCK_RECOV_TC bit functions" on page 102.

Note that the decoding of NRZ signals with long constant bit-periods is directly influenced by the accuracy of the selected baud rate. Proper coding can significantly improve sensitivity and the BER of NRZ decoding.

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7.14 Phase-locked loop

A complete on-chip PLL is available to provide an RF carrier in RX mode. The PLL is a 4th-order fractional-N PLL. The PLL analog section is described in Section 7.14.1 and the PLL digital section is described in Section 7.14.7.
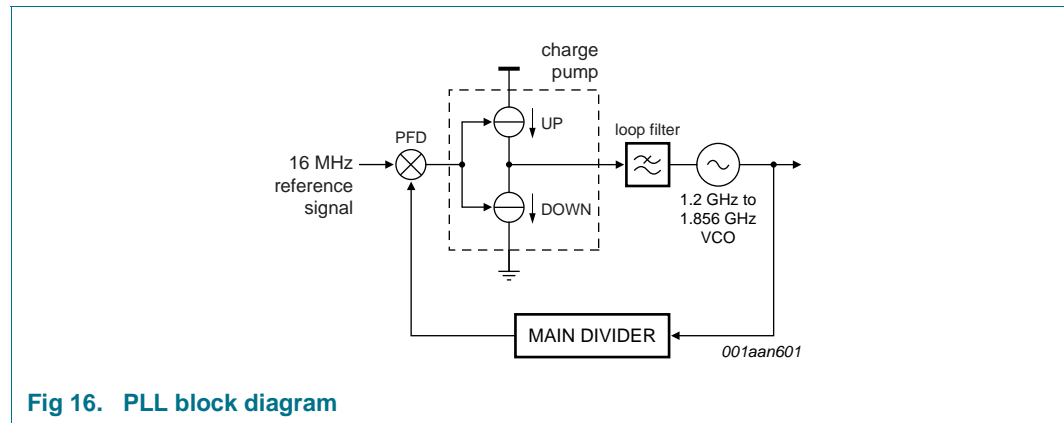

Fig 16. PLL block diagram

7.14.1 PLL building blocks

All PLL building blocks except bit VCO_BAND in register LOCON and the charge pump reference current (PLL_ICP[4:0]) settings are automatically configured and operated by selecting the corresponding device modes. The following paragraphs describe the function of the internal control signals. These control signals can be influenced, if desired, by operating control bits located in the EXPERTn and TESTn registers.

7.14.2 PLL and VCO regulators

To operate the whole PLL, both regulators must be switched on; see Section 7.9.3 "PLL regulator" on page 18.

7.14.3 General PLL operation

The following blocks are enabled after switching on the regulators so that the entire PLL is operational: VCO (VCO_ON), phase-detector (PFD_ON), prescaler (PRESC_ON) and reference clock buffer (CLK_PLL_ON).

7.14.4 Charge pump

This block delivers the charge to the loop filter. The polarity and amount of charge are proportional to the phase error reported by the phase detector.

The peak current of this charge pump is automatically adjusted. It can be overridden by PLL_ICP[4:0] in register EXPERT0; see Section 8.2.4.1 "Register EXPERT0" on page 108. The charge pump peak current is a function of the icp control bits: icp[0] * 15 μA + icp[1] * 30 μA + icp[2] * 60 μA + icp[3] * 120 μA + icp[4] * 240 μA.

This means that a value from 15 μA up to 465 μA can be selected. The purpose of this programmability is to compensate for gain variation in other blocks, especially RF VCO, and to keep a constant PLL loop bandwidth. The recommend value is to set PLL_ICP to 2.

7.14.5 RF VCO

The very low phase-noise on-chip RF oscillator is based on an LC oscillator.

A capacitor bank is integrated to centre the resonant frequency of the LC tank on the desired RF frequency. The VCO auto-calibration routine automatically trims the VCO to the correct sub-band. Whenever a different frequency setting is used, the VCO auto-calibration is carried out automatically. Automatic trimming can be blocked by setting bit SKIP_VCO_CAL in the LOCON register except during the PLL start-up; see . The trimming (sub-band selection) can be manually modified by control bits VCO_SUBBAND[5:0] in register VCOCON; see . Frequency sub-band setting 0 corresponds to the maximum frequency, and 3Fh to the minimum frequency.

Note that this RF VCO is running at twice (868 MHz and 928 MHz bands) or four times (313 MHz and 434 MHz bands) the chosen frequency bands.

Setting bit VCO_BAND selects the VCO's appropriate operating mode. This bit must be set to logic 1 at RF frequency bands below 400 MHz, or set to logic 0 for all other bands.

7.14.6 PLL loop bandwidth setting

It is recommended that the PLL loop bandwidth is set to just above 150 kHz (-3 dB closed loop bandwidth) as this gives the best trade off between noise behavior and locking time. The loop bandwidth can be set by PLL_ICP[4:0] to the recommended value ICP = 2.

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7.14.7 Delta-sigma modulator for fractional-N synthesis

The operating frequency is set by the content of frequency control registers FC0 to FC3, which each have a width of 20 bits. The 'active' frequency control register is selected directly by the RX command; see .
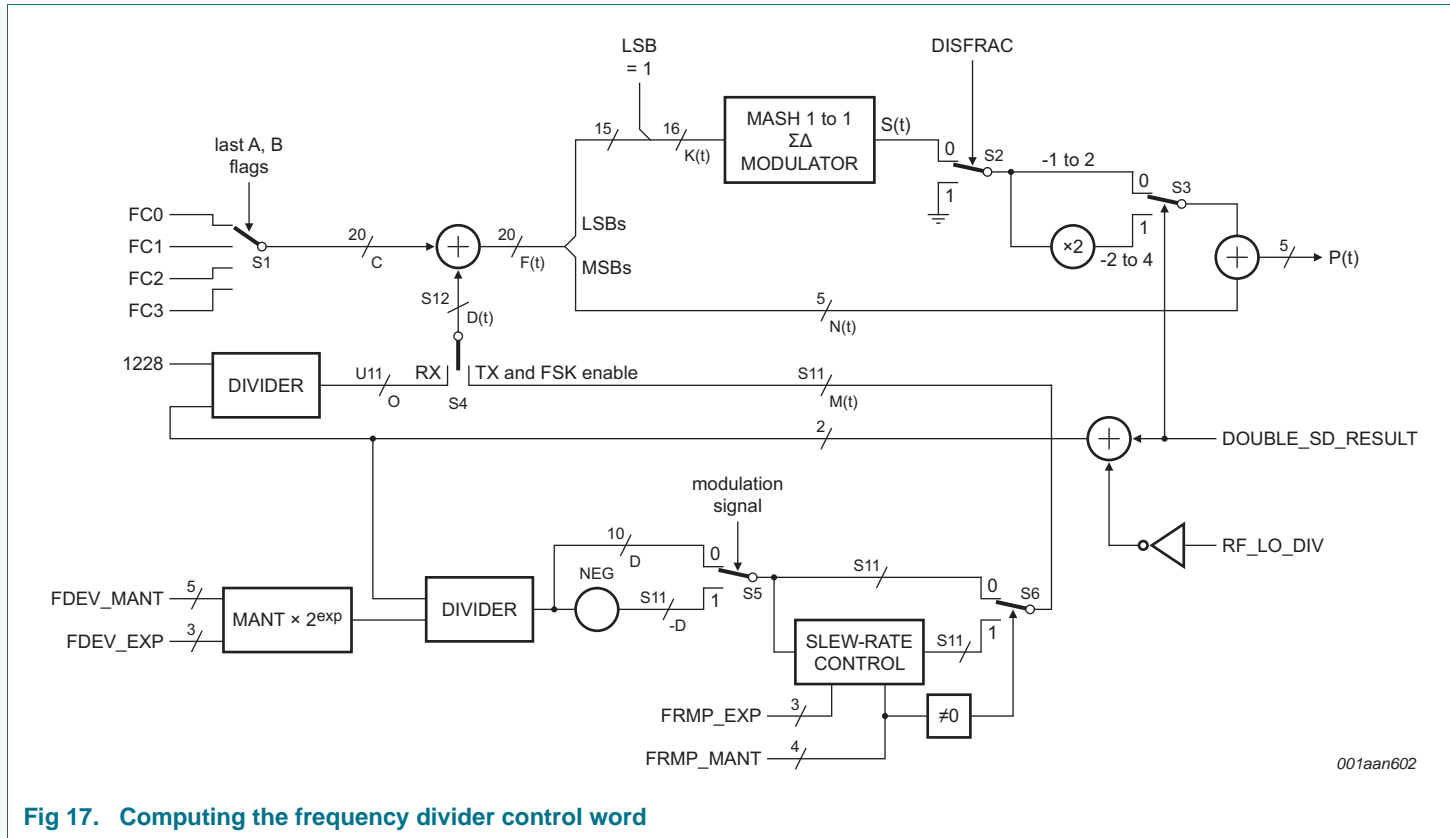

Fig 17.   Computing the frequency divider control word

7.14.7.1 PLL operating frequency f0

In Figure 17, the integer (Nt) is forwarded directly to the adder which produces the relevant control word (Pt) for the PLL. The remaining fractional values cannot be handled by the frequency divider directly and are therefore converted into a pseudo-random sequence of integers. This conversion is implemented by the sigma delta modulator. It produces numbers in the range from −1 to +2, whose average over time equals the given fractional part.

The spectral purity of the resulting RF signal is highly dependent on the randomness of the sequence generated by the fractional part. If this contained short repetitive patterns unwanted spurious signals may occur in the RF spectrum. To guarantee the produced sequences are always of maximal length, we append a constant 1-bit to the given fractional part, which resolves the issue. The weight of this 16th bit is 1 / 216 = 1 / 65536, which is very low. It creates a tiny frequency offset which can be taken into account when calculating the centre frequency control value FCx for a given centre frequency.

When the fractional part approaches 0 or 1 the low frequency noise components in the pseudo-random sequence become more dominant and can no longer be sufficiently suppressed by the PLL's transfer function. The visible effect is an increase of the phase noise in the RF output near the carrier. To counteract this effect, the OL2311 uses bit DOUBLE_SD_RESULT (Double Sigma Delta Result). If this bit is set, the fractional contribution to the PLL control word is doubled. So when the frequency control value F(t) is increased linearly, each RF output frequency is produced twice; once with a fractional value that is closer to zero or one (between 0 and 1 / 4 or between 3 / 4 and 1) and a second time with a fractional value which is closer to the mid-value 1 / 2 (between 1 / 4 and 3 / 4). The latter value produces a good pseudo-random sequence.

The frequency control value's fractional part is processed differently depending on bit DOUBLE_SD_RESULT, and the center frequency changes accordingly. Therefore the formulae, which convert between a given Frequency Control (FC) value and the RF center frequency, change with the state of bit DOUBLE_SD_RESULT.

In normal mode the expression is straightforward as shown in Equation 4.

$$f_{RF} = f_{ref} \times \left(64 + 2 \times \frac{2 \times FCx + 1}{65536} \right) \times \frac{1}{2 + 2 \times \text{RF\_LO\_DIV}} \tag{4}$$

- The expression's left side shows the reference frequency. The output frequency varies proportionally with the reference.
- The parenthesized expression (64 + 2 ×…) is the characteristics of the PLL frequency divider.
- The right term in the parenthesized expression accounts for the number interpretation of C and F(t) and the constant 1 LSB, which is added to guarantee maximum length sequences from the sigma-delta modulator
- The fraction at the right is the output division ratio, which is either 1 / 2 or 1 / 4, depending on the setting of bit RF_LO_DIV.

After simplifying the expression further we get the results shown in Equation 5.

$$f_{RF} = f_{ref} \times \left(32 + \frac{2 \times FCx + 1}{65536} \right) \times \frac{1}{1 + \text{RF\_LO\_DIV}} \tag{5}$$

For the inverse we solve the above expression for FCx and then we round the result to the nearest integer number as shown in Equation 6.

$$FCx = round\left\{ \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 \right\} \times 32768 - 0.5 \right\} \tag{6}$$

Using the floor function this becomes as shown in Equation 7.

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$$FCx = \left\lfloor \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 \right\} \times 32768 \right\rfloor \qquad (7)$$

Remark: Equation 7 is an important equation.

If bit DOUBLE_SD_RESULT is set, the integer part and the fractional part of the centre frequency setting must be considered separately. In this case the expression for the output frequency is shown in Equation 8.

$$f_{RF} = f_{ref} \times \left\{ 64 + 2 \times \left(FCx[19:15] + 2 \times \frac{2 \times FCx[14:0] + 1}{65536} \right) \right\} \times \frac{1}{2 + 2 \times \text{RF\_LO\_DIV}} \qquad (8)$$

In the inner parenthesized expression the integer part is taken as is, where the term which contains the fractional part has an additional factor of 2. After cancelling certain factors of 2 we get result shown in Equation 9.

$$f_{RF} = f_{ref} \times \left\{ 32 + FCx[19:15] + \frac{2 \times FCx[14:0] + 1}{32768} \right\} \times \frac{1}{1 + \text{RF\_LO\_DIV}} \qquad (9)$$

The inverse of this function is problematic, because the function for the output frequency is not monotonous. But we know that each output frequency is produced exactly twice and we know also that we want the solution where the average of the sigma-delta output S(t) is closest to 1 / 2. Let us convert Equation 9 such that the integer part of the frequency control value has no factor and the term containing the fractional part of the frequency control value becomes isolated on one side of the equation as shown in Equation 10.

$$\frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - FCx[19:15] = \frac{2 \times FCx[14:0] + 1}{32768} = 2 \times fract \qquad (10)$$

Now we ask for the integer part for which the fractional part becomes a value in the range from 0.25 to 0.75, which is equivalent to twice the fractional part, and lies between 0.5 and 1.5 as shown in Equation 11 and Equation 12.

$$\frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - FCx[19:15] \geq 0.5 \qquad (11)$$

$$\frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - FCx[19:15] < 1.5 \qquad (12)$$

Now we can isolate the integer part from both inequalities so that the right sides are the same as shown in Equation 13 and Equation 14.

$$FCx[19:15] \leq \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - 0.5 \qquad (13)$$

$$FCx[19:15] + 1 > \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - 0.5 \qquad (14)$$

These inequalities can be combined into a single expression to calculate the integer control value for the PLL as shown in Equation 15.

$$FCx[19:15] = \left\lfloor \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32.5 \right\rfloor \tag{15}$$

Remark: Equation 15 is an important equation.

The integer part which we have just found can be entered in Equation 9 and then we can solve for the fractional part. We get the result for the settings after rounding it to the nearest integer number shown in Equation 16.

$$FCx[14:0] = round\left\{ \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - FCx[19:15] \right\} \times 16384 - 0.5 \right\} \tag{16}$$

When using the floor function this becomes as shown in Equation 17.

$$FCx[14:0] = \left\lfloor \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + \text{RF\_LO\_DIV}) - 32 - FCx[19:15] \right\} \times 16384 \right\rfloor \tag{17}$$

Remark: Equation 17 is an important equation.

From Equation 4 and Equation 9 we can also see which frequency resolution can be achieved in which mode. If bit DOUBLE_SD_RESULT is set to logic 0, we have Equation 18.

$$f_{RF,res(0)} = f_{ref} \times 2 \times \frac{2}{65536} \times \frac{1}{2 + 2 \times \text{RF\_LO\_DIV}} = \frac{f_{ref}}{32768} \times \frac{1}{1 + \text{RF\_LO\_DIV}} \tag{18}$$

If bit DOUBLE_SD_RESULT is set to logic 1, the resolution becomes as shown in Equation 19.

$$f_{RF,res(1)} = f_{ref} \times 2 \times \frac{2}{65536} \times \frac{1}{2 + 2 \times \text{RF\_LO\_DIV}} = \frac{f_{ref}}{16384} \times \frac{1}{1 + \text{RF\_LO\_DIV}} \tag{19}$$

Taking bit DOUBLE_SD_RESULT into the formula, Equation 18 and Equation 19 can be combined into

$$f_{RF,res} = \frac{f_{ref}}{32768} \times \frac{1 + \text{DOUBLE\_SD\_RESULT}}{1 + \text{RF\_LO\_DIV}} \tag{20}$$

Remark: Equation 20 is an important equation.

7.14.8 RX frequency offset

Because the OL2311 receiver implements a superheterodyne architecture with an intermediate frequency of 300 kHz, the local oscillator is automatically tuned to 300 kHz above the wanted RX centre frequency in RX mode.

This is accomplished by adding an offset value O to the centre frequency setting C; see Figure 17 "Computing the frequency divider control word" on page 29. This offset value is automatically adjusted so that it matches the LO frequency resolution, which changes with the settings of bits RF_LO_DIV and DOUBLE_SD_RESULT.

Table 54 "RX frequency offset" on page 92 shows that the resulting RX frequency offset is independent of the RF_LO_DIV and DOUBLE_SD_RESULT settings. It is always 195 Hz below the nominal IF of 300 kHz, which is accurate enough in all cases.

7.14.9 PLL lock detection

A lock detection circuit is implemented to support the shortest PLL power-on time. The lock-detection circuit monitors the phase and frequency differences of the PLL and the reference clock. If the phase-difference of the two clock signals is settled within a defined window, an internal LOCK_DETECT signal is triggered. After a specified time, set by bit LOCK_DET_TIME[1:0] in register EXPERT1, status bit LO_RDY is set in register DEVSTATUS. Since the lock detect circuit consumes additional power, it is only enabled during the PLL's start-up phase and whenever a different sub-band setting is applied. The lock detect circuit can be manually controlled by bit LOCK_DET_ON in register LOCON; see Section 8.2.1.3 "Local oscillator control register LOCON" on page 82.

7.14.10 VCO auto-calibration

VCO calibration is performed every time the VCO's centre frequency is changed. The following internal sequences are started:

1. Start VCO calibration and turn on PLL lock detection. The output of the lock detection must be gated LOW when the calibration is running.

2. With the next clock cycle: turn on phase frequency detector (bit PFD_ON), prescaler (bit PRESC_ON), clock for PLL (bit CLK_PLL_ON) and PLL lock detection.

3. Perform VCO calibration (select best possible sub-band for desired frequency setting).

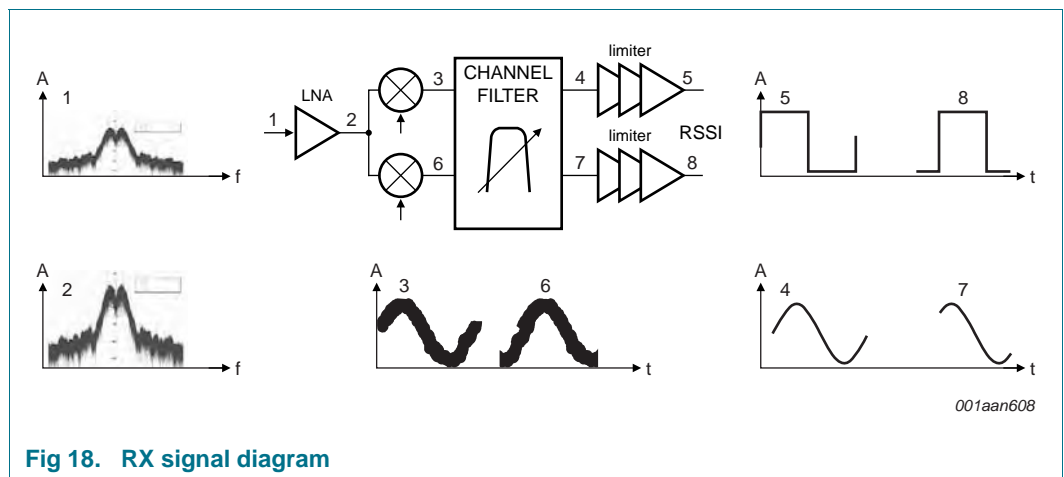4. Check PLL lock detection plus lock detect time.

7.15 RX operation

Fig 18. RX signal diagram

Figure 18 visualizes internal signal shapes inside the RX block. Signal 1 represents the signal input spectrum, sketched in the frequency domain. The frequency spectrum is centred to the desired RX frequency. Signal 2 represents the amplified spectrum of the input signal (signal 1). Signal 2 is mixed with the LO frequency (must be set to 300 kHz above the RX frequency) down from the RX input frequency with the I and the Q mixer to the IF (300 kHz). Signal 3 and signal 6 represent the IF signals of the I and the Q channel

(90 ° phase difference) in the time domain. Signals 4 and 7 represent the I and Q signals after the channel filter. Signals 5 and 8 are the amplified and limited I and Q signals at the output of the limiter. It is possible to switch some of these internal analog signals to pins TEST1, TEST2 via bits ANA_TEST_SEL[2:0] in register TEST1. The digital IQ signals of the limiter output, and other digital baseband signals can be accessed via the alternative port functions of P11C and P12C with the appropriate setting of bits DIG_TEST_SEL[2:0] in register TEST0; see Table 103 "Register TEST0 - (address 35h) bit description" on page 110 for more details.

7.15.1 General operation

The RX block consists of a fully analog front-end including an analog channel filter. The mixer and channel filter demodulates only one sideband to the IF. The LO frequency (RF VCO frequency) must be set 300 kHz above the expected frequency of the RX signal. The receiver mixes down the RX signal's lower side-band. The LNA gain settings and the channel filter are adjustable to achieve a high dynamic operating range. Field strength detection, automatic gain selection and AM demodulation are implemented via the RSSI information. The RSSI is derived from a limiter. Automatic gain selection is explained in Section 7.19.

Data demodulation is performed in the digital part of the RX chain. The circuit is capable of demodulating ASK and FSK signals. FSK demodulation is applied directly with the analog IF signal from the channel filter. This signal is directly fed into the digital FM demodulator where it is processed further. ASK demodulation employs the RSSI signal which is decoded in the digital part and then further processed. The Data slicer and clock recovery mechanisms regenerate the bit stream for both, ASK and FSK signals.

The OL2311 is able to cope with a 1 % data rate tolerance enabling it to operate correctly with standard XTAL cutting and temperature inaccuracies.

7.16 LNA

The feed from the single-ended antenna is converted to a differential signal at the input of the mixer. The intrinsic voltage gain (from input pin RX to the unloaded LNA) is adjustable to typically 4 dB, 17 dB, 23 dB or 25.5 dB. Two gain settings can be programmed to meet the dynamic range requirements of the receiver chain. In parallel to the LNA gain, the channel filter gain can also be adjusted. The selection of the appropriate gain setting (Hi-gain or Lo-gain) is executed automatically by the gain control loop. The individual gain setting is programmed by the control bits located in the RXGAIN register; see Section 7.19.

7.17 Mixer

The mixer is effectively an active I/Q mixer. It mixes down the amplified signal from the LNA to the 300 kHz IF frequency.

7.18 Channel filter

Channel filter gain and bandwidth can be selected independently with control bits. A well-defined filter bandwidth is achieved using auto-calibration features. The filter bandwidth can be configured by setting bits CF_BW[2:0] in register RXBW. The different

adjustable bandwidth settings of the IF channel filter can be found in Table 57 on page 92. The best noise performance is achieved by setting the channel filter's bandwidth as close as possible to the bandwidth occupied by the modulated RX signal.

7.18.1 Channel filter auto-calibration

The channel filter auto-calibration is implemented to achieve a well-centered filter roll-off characteristic in the filter pass-band. This feature can compensate for process and temperature dependent parameter mismatches. Filter auto-calibration is performed automatically before every RX operation.

The calibration can be blocked by setting bit SKIP_CF_RC_CAL, and can be forced at any time by setting bit FORCE_CF_RC_CAL both in register TEST4.

Channel filter calibration status information can be accessed by reading the CFRCCAL register. All CFRCCAL register bits are read-only.

After starting channel filter calibration, bit CF_RC_CAL_RUNNING in register CFRCCAL can be probed. This bit is set to logic 1 when the RC calibration algorithm is running.

Status bit CF_RC_CAL_OK is set to logic 1 when a channel-filter calibration has been correctly performed. This indicates that the data of CF_RC_CAL_RES[3:0] are valid. CF_RC_CAL_RES[3:0] indicate the channel RC calibration result. These bits are applied directly to the internal RC components of the channel filter.

Channel filter auto-calibration can be manually overridden by special register TEST4. Control bits CF_RC_ADJUSTCAL[1:0] allow the accuracy of the channel filter auto-calibration routine to be cross-checked.

Setting bit SKIP_CF_RC_CAL by-passes the on-chip RC-calibration. Setting bit FORCE_CF_RC_CAL triggers an RC auto-calibration. The corresponding RC calibration values set in CF_RC_CAL_RES[3:0] in register CFRCCAL after auto-calibration, have to be entered in MAN_CF_RC_CALVAL[3:0] in register TEST4.

The CF_RC_ADJUSTCAL[1:0] control bits can be used to evaluate the on-chip channel filter RC calibration block accuracy. The R part of the RC reference is trimmed by changing the value of these two bits. By knowing the adjusted R variation we can verify that the output of the CF_RC_CAL_RES[3:0] control bits is changing accordingly. This enables the complete RC measurement mechanism to be validated.
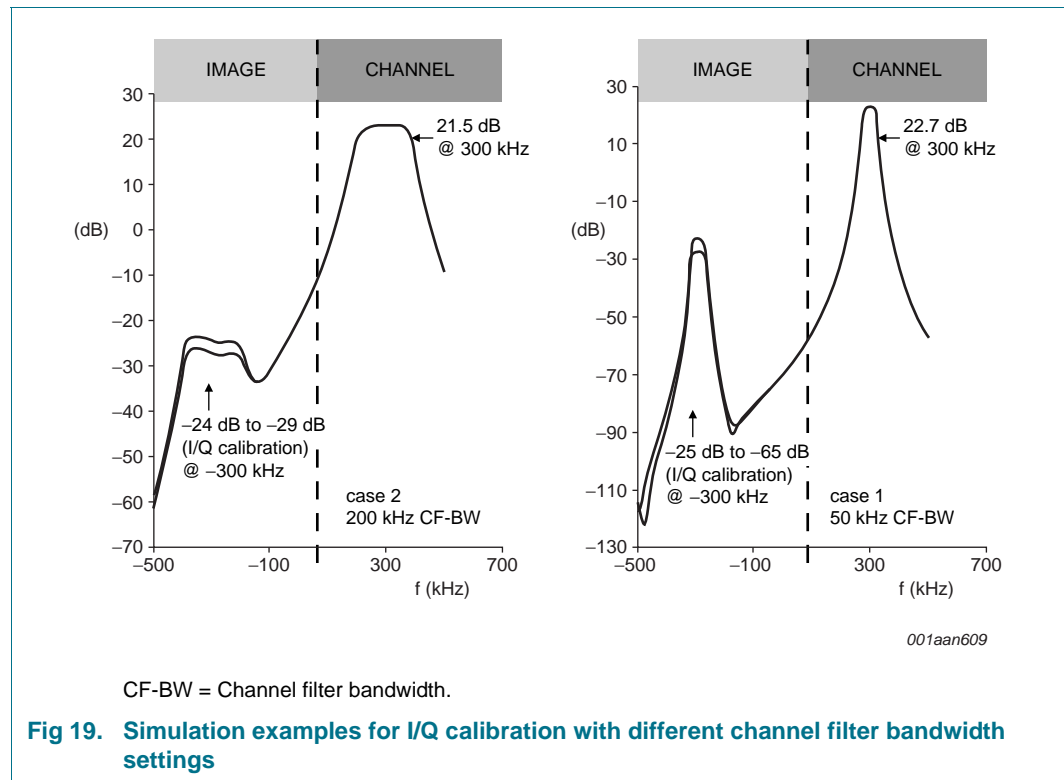
7.18.2 Channel I/Q calibration

An I/Q calibration is implemented to achieve a high image frequency rejection. This calibration is intended to be used once during production of the final application PCB as part of an end-of-line test. It requires an external signal at the image frequency of the desired RX frequency to be applied to pin RX. The I/Q calibration routine automatically calculates the best I/Q trimming configuration for the optimum image rejection of >50 dBc. This result must be read and stored by the external microcontroller. The calibration value is valid for the whole frequency band over all supply voltages and temperatures.

Perform the I/Q calibration as follows:

Apply a signal at the RX image frequency. The signal level must be chosen so that the RSSI is still able to measure the damped image; for example, an input of −40 dBm gives an image at −90 dBm, which is still a sufficient RSSI operating margin.

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The I/Q calibration is enabled by setting bit START_CF_IQ_CAL in register CFIQCAL. Status bit CF_IQ_CAL_RUNNING indicates an active calibration cycle. All possible I/Q offset combinations are run sequentially at every combination an RSSI measurement is performed. The combination with the minimum RSSI reading is stored in CF_IQ_CALVAL[6:0]. This information must be stored by the external microcontroller. Initialize this register with the stored values each time. Set CF_IQ_CALVAL[6:0] to logic 0 if no IQ calibration is required.

Figure 19 shows the effect of a simulated I/Q calibration. With this calibration an image rejection of 50 dB is achievable.

CF-BW = Channel filter bandwidth.

Fig 19. Simulation examples for I/Q calibration with different channel filter bandwidth settings

7.19 LNA and channel filter gain settings

Table 4 gives the intrinsic voltage gain of the LNA circuit. LNA voltage gain is programmable and this table indicates the incremental I_{CC} steps impacting RX front-end current consumption.

Table 4.   Channel filter gain settings

Channel filter gain 1	Channel filter gain 0	Voltage gain (dB)
0	0	−2
0	1	17
1	0	22
1	1	27

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Table 5.   RX gain control

LNA gain 1	LNA gain 0	Gain (dB)	LNA input stage typical current (mA)
0	0	4[1]	0.55
0	1	17	0.55
1	0	23	1.1
1	1	25.5	1.65

[1]   LNA low gain stage.

Voltage gain induced by an impedance transformation network (from antenna to input pin RX) needs to be added to the values in Table 4 (such as 6 dB extra gain in case of ideal 50 Ω to 200 Ω impedance transformation) to compute the overall RX front-end voltage gain.

The RX analog chain voltage gain (before limiter) can be performed by adding these values to those of the channel filter given in Table 4.

Figure 20 and Figure 21 show the field-strength as a function of gain switching.

Fig 20.   20 dB difference between Hi-gain and Lo-gain setting

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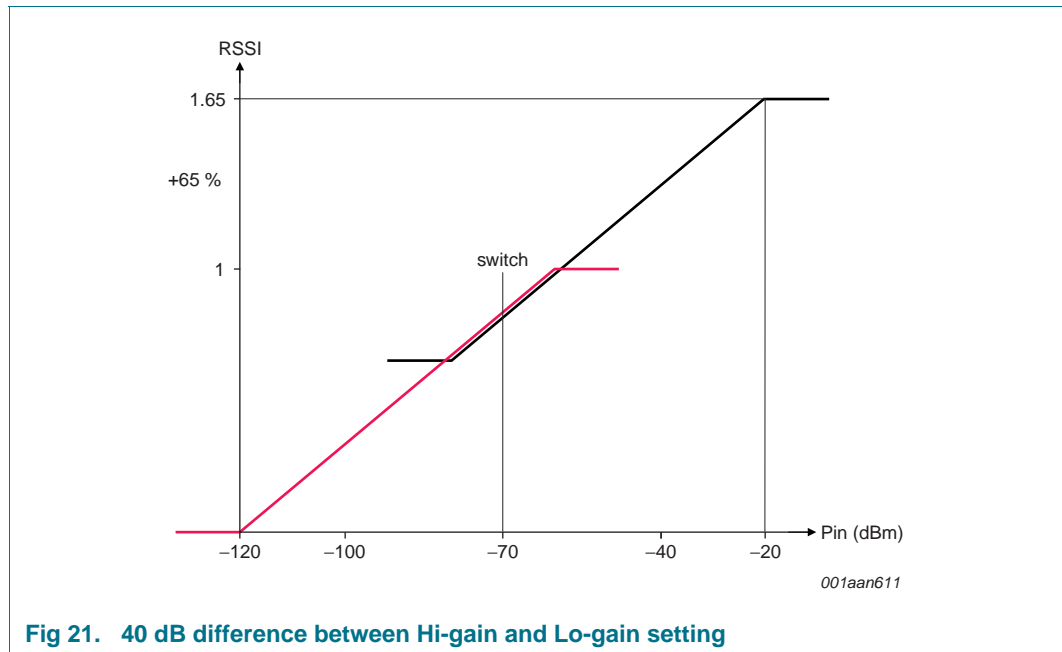All information provided in this document is subject to legal disclaimers.
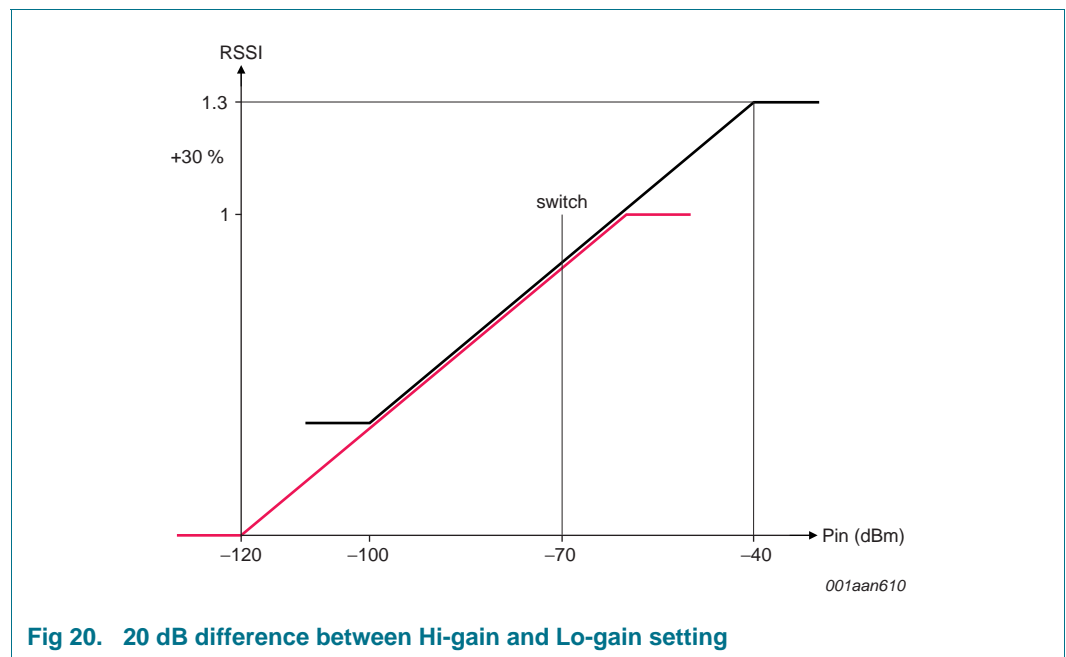
**Fig 21. 40 dB difference between Hi-gain and Lo-gain setting**

7.20 Limiter

The function of the limiter is to amplify or limit the input signal so that the output voltage of the last stage of the limiter is always constant. This applies to both very small signals at the sensitivity limit and very large input signals. The limiter block consists of 5 gain stages for each channel (I and Q). The limiter output signal of the last stage can be seen as a rail-to-rail square signal. Two limiter chains are implemented. One chain limits the I-signal, the other is used to limit the Q-signal. These square wave signals are used for FM demodulation in the baseband signal processing section. Therefore the limiter can be interpreted as a one-bit ADC directly connected to the digital section. The analog output signal levels of the individual limiter stages are used in conjunction with the RSSI block to measure the RX signal strength on a logarithmic scale.

7.21 Limiter block filter cut-off frequency

The following cut-off frequencies are selected after allowing for the IF frequency of 300 kHz, and a maximum bandwidth of 300 kHz:

- high-pass cut-off frequency < 100 kHz
- low-pass cut-off frequency > 500 kHz

Fig 22. Signal level plan
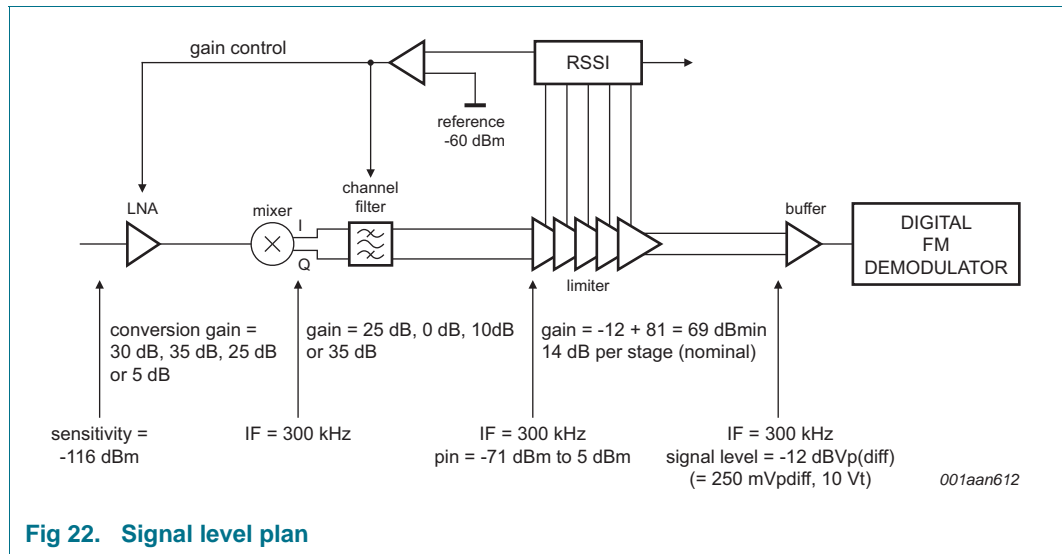
7.22 RSSI

The RSSI function is implemented by adding tail currents used in the individual limiter stages. This does not apply to levels higher than the compression point. In this case the gain of the LNA and channel filter is reduced to increase the linearity and the dynamic range of the RSSI.

Remark: As the RSSI is proportional to the input voltage level having a frequency of 300 kHz, it must be filtered to ensure a stable result as the input voltage. The RSSI frequency is 600 kHz due to the nature of the RSSI detector principle.

7.22.1 Dynamic range and operation

The RSSI's dynamic operation is required for ASK demodulation and carrier detection. An overall dynamic range of 130 dB is required, −120 dBm minimum sensitivity up to +10 dBm maximum signal strength. The front-end gain can be switched. An overlap of the dynamic ranges of 20 dB is recommended to guarantee continuous ASK demodulation. This results in a single range of 70 dB.

7.22.2 Resolution

The resolution is set to ±2 dB in all conditions. A 6-bit converter is implemented to allow for process and temperature variations.
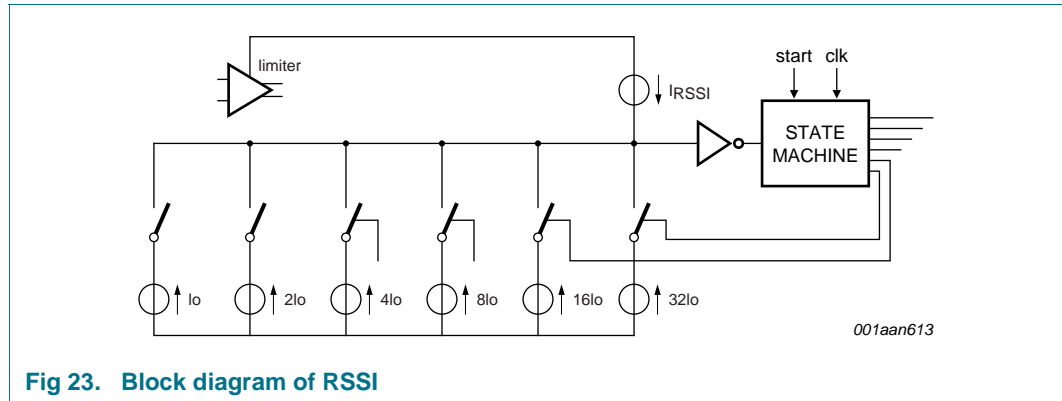
Fig 23. Block diagram of RSSI

7.22.2.1 RSSI low-pass filtering

The filter integration time-constant of the analog RSSI signal can be adapted to achieve a more stable digital RSSI reading (RSSI raw value) as an input to the digital filtering and interpolation. The RC-type analog filter is used in addition to the digital filters implemented in the baseband digital signal processing unit. This first order low-pass filter is applied directly to the summed output of the limiter tail-currents. The limiter gain bandwidth characteristics are not affected.

7.22.2.2 RSSI digital filtering

The raw RSSI value is fed to a digital filtering and interpolation circuit. The output of the digital circuit is the digitised RSSI value. The digital RSSI filter cut-off frequency can be selected by bits RSSI_FILTER_FC[3:0] in register RXBW.

The first-order low-pass filter previously mentioned cut-off frequency can be calculated according to the Equation 21.

$$f_c = \frac{f_{ref}}{2\pi \times 2^{5+\text{RSSI\_FILTER\_FC}}} \tag{21}$$

Where f_{ref} is the reference frequency and RSSI_FILTER_FC[3:0] is a 4 bit value in register RXBW; see Section 8.2.1.18 "Channel filter bandwidth and RSSI filter settings register RXBW" on page 92.

7.22.2.3 Low-level signal detection

The RSSI is used to detect the start of a communication sequence. Carriers at a sensitivity level as low as −110 dBm are detected properly.

7.22.3 RSSI gain control

The automatic front-end gain selection switching threshold is controlled by the RSSI's output signal. This principle decreases the gain of the front-end and, if necessary, the channel filter when the input level is significantly greater than the reference sensitivity level. This gain switching increases the linearity of the overall chain and the robustness for large signal behavior and also increases the RSSI's dynamic range.

Register HIGAINLIM contains control word HI_GAIN_LIMIT[7:0]; see Section 8.2.1.20 "Register HIGAINLIM" on page 93. At power-up the front-end gain is always set to the value of RX_HI_GAIN[4:0] in register RXGAIN, so that the RSSI operates in its most sensitive mode; see Section 8.2.1.17 "Receiver gain control register RXGAIN" on page

92. If the gain switching is enabled during wakeup-search, the gain is reduced to the RX_LO_GAIN[3:0] setting provided the RSSI threshold set by HI_GAIN_LIMIT[7:0] is exceeded. The RSSI reading is performed automatically during the wakeup-search detection.

Remark: If the input signal level is above the switching threshold and the gain-switching is initiated, two bits are lost due to the switching event. The length of the wakeup and the preamble must be chosen accordingly to guarantee safe operation. The minimum length of preamble must be 8 bits; the bit time of two bits is necessary to start the receiver and to perform the necessary RSSI measurement. Two bits may be lost due to RSSI switching, and a minimum of 4 bits are required to detect the preamble correctly and to synchronize the clock recovery. This is true only when using the edge slicer, more time may be required when using the level-sensitive slicer.

The result of the RSSI conversion can be retrieved in status register RSSILEVEL; see Section 8.2.2.12 "Register RSSILEVEL" on page 106.

A compensation value can be set in the GAINSTEP register to achieve a continuous RSSI reading when the front-end gain is changed; see Section 8.2.1.19 "Register GAINSTEP" on page 93. RSSI_GAIN_STEP_ADJ[6:0] in register GAINSTEP represents the difference between the gain values set in RX_HI_GAIN[4:0] and RX_LO_GAIN[3:0] for the corresponding RSSI read value. The RSSI_GAIN_STEP_ADJ[6:0] value is added to the RSSI conversion result when RX_LO_GAIN[3:0] is activated. This yields an RSSI overall dynamic range of more than 120 dB.

7.23 Receive mode

7.23.1 Preparation for RX mode

The device initiates RX mode upon the correct setting of DEV_MODE[1:0] in register PWRMODE. This, in turn, sets internal enable bits PLLEN and RXEN.
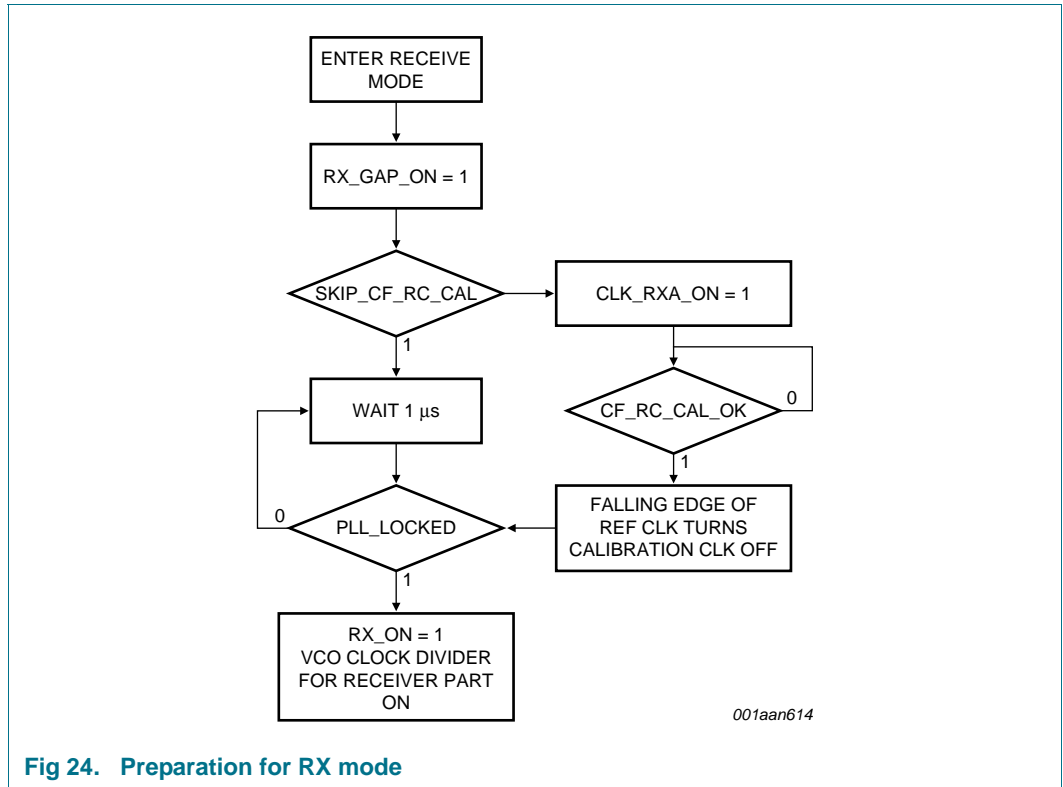
Fig 24. Preparation for RX mode

1. Turn on the bandgap reference circuit for the receiver section (bit RX_GAP_ON) and the clock for the channel filter RC calibration (CLK_RXA_ON) with the negative edge of the reference clock. The latter is done only if the channel filter RC calibration is not skipped (bit SKIP_CF_RC_CAL). Then wait 1 µs until the bandgap stabilizes.

2. If the channel filter RC calibration is enabled, start it and then wait until it ends. Then turn off the clock for the RC calibration at the next falling edge of the reference clock.

3. Wait until the PLL control-state machine reaches the state PLL_LOCKED and then turn the receiver on (bit RX_ON), which also turns on the VCO clock divider in the receiver section.

This sequence ends with the channel filter RC calibration, if enabled. When this ends, the receiver is turned on.

7.23.2 Receive command

The device features a RX command. The command includes the six command bits RA, RB, RC, RD, RE and RF:

- RA, RB: RX frequency selection bits
- RC, RD: sub-command bits
- RE, RF: gain step/switch selection bits

Table 6. Receive command packet

D0	D1	D2	D3	D4	D5	D6	D7
1	0	RA	RB	RC	RD	RE	RF

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Table 7.   Frequency selection (bits RA, RB)

Bit RA	Bit RB	Selected frequency band
0	0	FC0L, FC0M, FC0H
0	1	FC1L, FC1M, FC1H
1	0	FC2L, FC2M, FC2H
1	1	FC3L, FC3M, FC3H

Remark: In RX mode a frequency offset of +300 kHz is automatically added to the resulting center frequency to account for the necessary LO frequency offset. Whenever these flags change from one RX command to another, an LO sub-band calibration (VCO calibration) is initiated.

Table 8.   Sub-command selection bits RC, RD

Bit RC	Bit RD	Selected RX sub-command
0	0	CONT (continue)
0	1	WUPS (wakeup search)
1	0	PRDA (preamble detection followed by data reception)
1	1	DATA (data reception without preamble detection)

With a CONT RX command, the microcontroller can continue with any previously initiated WUPS, DATA or PRDA command. If the frequency selection bits RA and RB are the same as in the previous RX command and if the flags RE and RF are both logic 0, then, with the next rising edge of SCLK, only the RX clock and the RX data lines are switched to the SPI SCLK and D(I)O pins, respectively. This provides the microcontroller with the possibility to interlace SPI Read and Write commands with RX data, provided that the SPI communication rate is much faster than the data reception rate. If no RX operation is in progress, no initiation occurs, and the CONT RX command only switches the SPI lines with the next SPI clock edge, and delivers the internal RX result. The RX result can be the recovered chip clock and the transparent slicer signal or just a constant level, depending on the current RX output configuration and depending on the RX state.

A WUPS RX command initiates a wakeup search operation. This command's restart characteristics enable it to interrupt any RX operation. During this command the RXDCON0 configuration is applied as the dynamic configuration for the slicer and signal classification and detection; the RX clock and data result can be observed with the SPI lines producing a constant HIGH on the clock line and a constant LOW on the data line in digitised mode. This output (not the wakeup search operation itself) can be interrupted with Read and Write commands and can be continued with a CONT RX command. The WUPS command ends after either a WAKEUP_FOUND or a WAKEUP_NOT_FOUND decision. In both cases the status of the detection method is sampled. When the WUPS command ends, the WUPS_FOLLOWUP configuration dictates how the device operates; see .

A PRDA RX command initiates a preamble detection. This command's restart characteristics enable it to interrupt any other RX operation. During this command the RXDCON1 configuration is applied as the dynamic configuration for the slicer and signal classification and detection method; the RX clock and data result can be observed with the SPI lines producing a constant HIGH on the clock line and a constant HIGH on the data line during preamble detection in digitised mode. This output (not the preamble

detection operation itself) can be interrupted with Read and Write commands and can be continued with a CONT RX command. When the correct preamble is detected, the receiver switches automatically into data reception mode. This switch does not influence the signal processing section of the receiver, which means that there is a seamless transition from the preamble detection mode to the data reception mode. What changes with the switch is the dynamic part of the configuration and the state of the signal detection and classification means. The dynamic configuration for the signal detection and classification method is switched to the RXDCON2 set and the detection methods are restarted.

If the preamble detection ends with a PREAMBLE_NOT_FOUND status (after running into a timeout), the PREA_FOLLOWUP configuration automatically decides if and how the receiver operates; see . Regardless of the outcome of the preamble detection phase (found or timeout) the status of the detection method is sampled when the preamble detection ends.

If the digitised RX output format is selected for the RX clock and data, both are held constant while the preamble detection is in progress. When the preamble is detected, the RX clock starts and the associated RX data bits are delivered with each RX clock pulse. In transparent mode the output signals are always available.
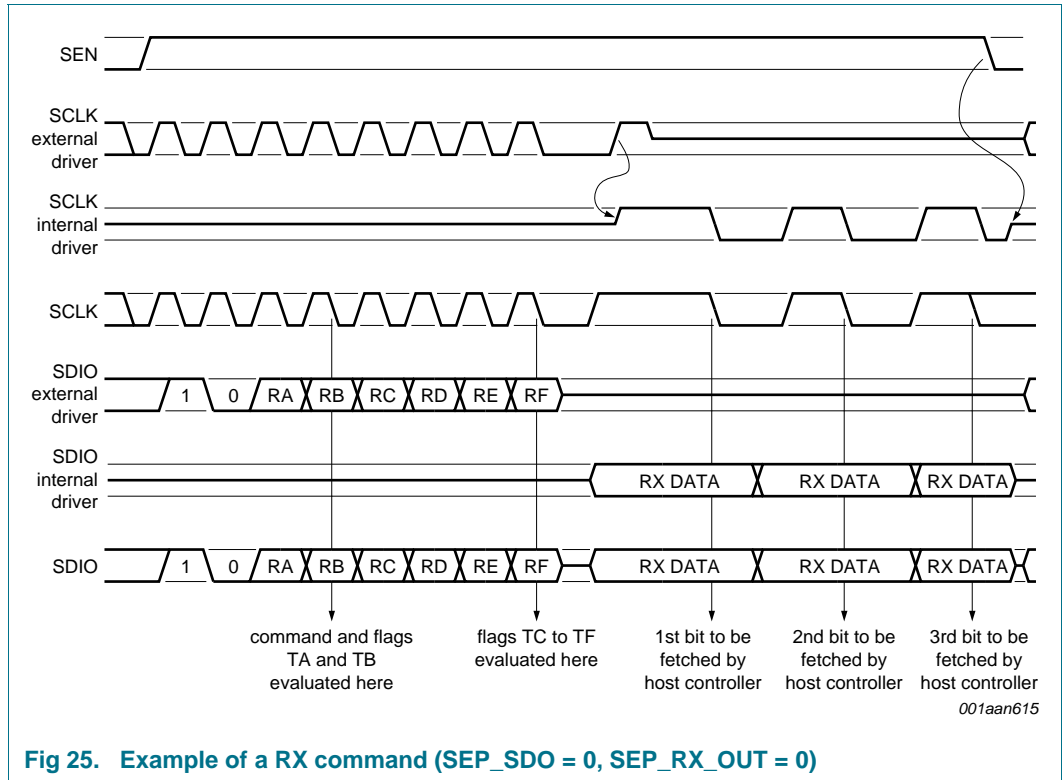
A DATA RX command initiates the reception of frame data and skipping the preamble detection phase. This command always uses the RXDCON2 set as the dynamic configuration for the slicer and the signal detection and classification methods. After initializing the slicer it behaves similar to the PRDA command after successful preamble detection.

Both the PRDA command in data reception mode and the DATA command do not end automatically on any selectable criteria. They can be terminated with another restarting RX command, or by turning the receiver off.

Table 9.   Gain switch selection (bits RE, RF)

Bit RE	Bit RF	Selected gain step/switch configuration
0	0	keep RX gain as is
0	1	gain switch (WUPS sub-command only), same as logic 00 for other sub-commands
1	0	use low gain settings
1	1	use high gain settings

The combination logic 01 (gain switch) is only applicable with the wakeup search (WUPS) RX command. If this is chosen, the wakeup search starts with the high gain settings. If the received RF signal strength is always below the limit given by the HI_GAIN_LIMIT settings, then the low gain settings are used throughout the whole wakeup search. But if the RF amplitude exceeds this limit, the receiver automatically switches to the low gain settings and continues with the wakeup search. Note that the wakeup search timer is not influenced by the gain switch.
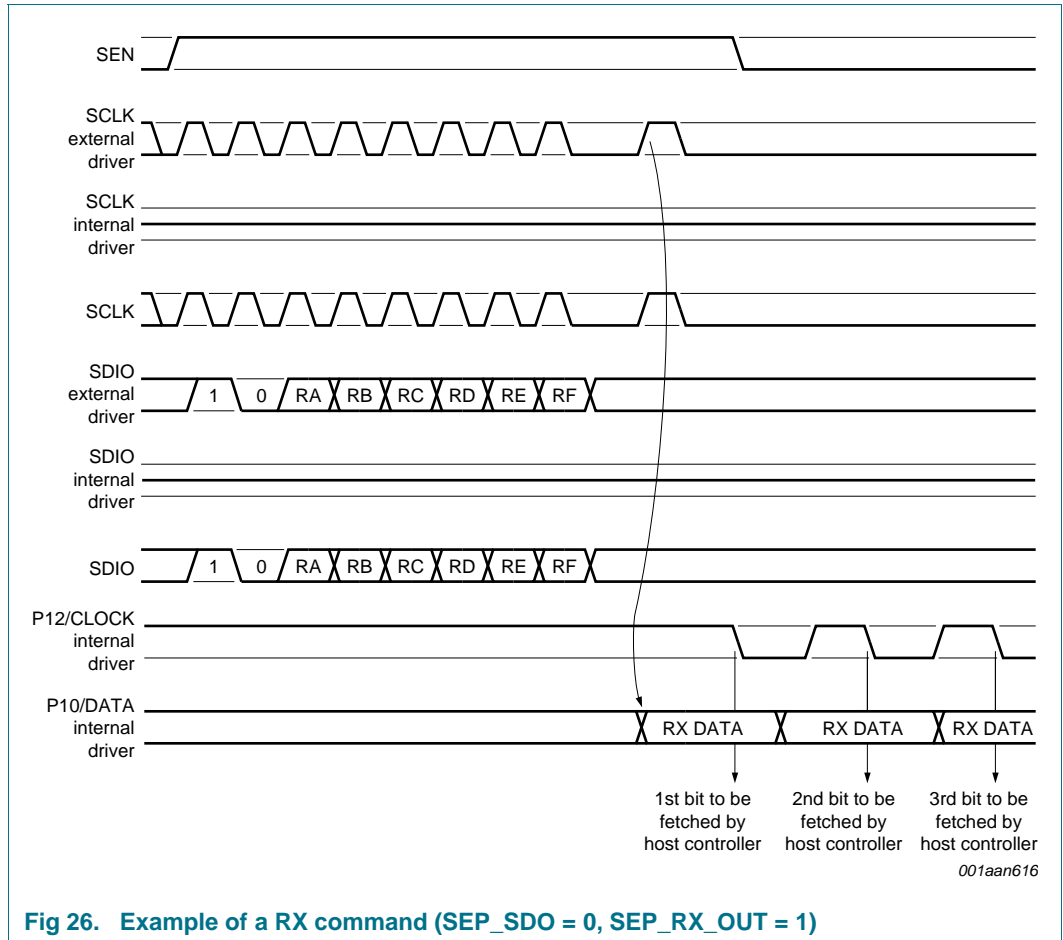
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Fig 25. Example of a RX command (SEP_SDO = 0, SEP_RX_OUT = 0)

Fig 26. **Example of a RX command (SEP_SDO = 0, SEP_RX_OUT = 1)**

From a sequence and timing point of view the RX command behaves as follows:

The DEV_MODE is set to logic 10 (RX mode) on the falling edge of the SPI clock after receiving the 4th bit (flag bit RB) of the command. The new frequency setting is applied according to the flag bits RA and RB. The LO is initialized at this frequency and the receiver remains switched on even if the RX command is aborted. A 4-bit command can be used to turn the receiver on and to switch the LO frequency. A new calibration of the VCO sub-band, provided it is enabled, and a new PLL lock-in occurs under the following conditions.

- upon receipt of the first RX command
- the first RX command after powering up the device
- the frequency settings are changed with respect to a previous RX command

The next relevant action occurs upon receiving the 8th bit (flag bit RF) of the command on the SPI clock's falling edge. This latches the remaining flags (RC to RF) into the RX flag register. Please note that the receiver state machine is still not influenced after receiving the full command byte. This gives the microcontroller the chance to wait until the analog section of the receiver settles fully before executing the command from a sequence point of view.

The command is initiated on the next rising edge of the SPI clock. In the case of a WUPS, a PRDA or a DATA RX command, this brings the receiver state machine to the respective starting point of the sub-command. If a CONT RX command is issued, the receiver state machine is not influenced. The SPI clock's rising edge also switches the RX clock onto the SCLK line after a programmable delay (CLK2SCLK_DELAY[4:0]) and the RX data output is immediately switched onto the SD(I)O line. This delay takes effect when switching the SPI line SCLK with a RX command into the mode, where it changes its direction to output. In this mode it delivers the RX clock, respectively. The delay starts with the next positive edge of the reference clock following the 9th edge of SCLK (activation edge). After the delay the output driver of SCLK is activated.

The delay value is (CLK2SCLK_DELAY + 1) / f_{ref}, where CLK2SCLK_DELAY[4:0] can be set to a value in the range 0 to 15. So if the 9th edge of SCLK occurs just before the positive edge of the reference clock and if CLK2SCLK_DELAY[4:0] is set to logic 0, the minimum delay is 1 reference clock cycle (62.5 ns at 16 MHz). If the 9th edge of SCLK occurs just after the positive edge of the reference clock and if CLK2SCLK_DELAY[4:0] is set to 15, the maximum delay is 17 reference clock cycles (1062.5 ns at 16 MHz); see Section 8.2.1.3 "Local oscillator control register LOCON" on page 82.

If digitised RX output mode is configured, the clock output delivers a constant HIGH state during wakeup search and during preamble detection. The output starts toggling during data reception according to the recovered RX clock. The data output behaves in a similar way to digitised mode, the only difference is that it is in LOW state during wakeup search operations.

If transparent RX output is configured (see register RXCON), the clock and data output always delivers the recovered chip clock and the deglitched slicer output, respectively.

7.23.2.1 Dynamic receiver configuration

It is not always appropriate to have a fixed setting for all aspects of the receiver configuration for a given protocol. This is illustrated in the following two examples:

- If the transmitter sends its frames continuously without RF interruption, then it makes sense to initialize the slicer at the start of the wakeup search but to skip the slicer initialization at the start of the preamble detection in order to save time.

- If Manchester encoded data is to be received then the modulation amplitude detection must be configured to allow single signal gaps which occur at data bit transitions (01 or 10). But if the wakeup pattern is a constant Manchester encoded 000… or 111… pattern, allowing no signal gaps increases discrimination precision.

To be able to manage these scenarios whilst minimizing the loading of the external microcontroller, a so-called dynamic device configuration can be implemented. This dynamic device configuration is controlled with the following control bytes.

Table 10. RXDCON registers

Register	Nomenclature
RXDCON0	wakeup search settings
RXDCON1	preamble-detection settings
RXDCON2	data reception settings

The relevant register is automatically selected depending on whether the receiver is in wakeup search mode, preamble detection mode or in data reception mode. The settings of SLICERINITSEL[1:0] and INIT_ACQ_BITS[1:0] make two individual alternative configuration sets available because only one slicer initialization is necessary for the combined preamble detection and data reception operation.

It is possible to chain all these device modes together, employing individual device configuration settings automatically. This is especially useful when the first command is initiated from a polling timer event where the receiver can work in parallel to the wakeup of the microcontroller.

Table 11.   RX operating mode transitions

First operation	After wakeup search				After preamble detection			
Initiated by	polling timer		command		polling timer		command	
Success(+)/fail(−)	+	−	+	−	+	−	+	−
Power-down	-	[1]	-	[1]	-	[1]	-	[1]
Stop	[1][2]	[1][2]	[1]	[1]	-	[1][2]	-	[1]
DATA	[1][2]	-	[1]	-	[1][2]	-	[1]	-
PRDA	[1]	-	[1]	-	-	-	-	-
Bit (field) name	WUPS_FU_TS	WUPS_FU_TF	WUPS_FU_CS	WUPS_FU_CF	-	PREA_FU_TF	-	PREA_FU_CF
follow-up configuration name	WUPS_FOLLOWUP				PREA_FOLLOWUP			

[1] A possible operating mode transition.

[2] A non-maskable interrupt is generated.

Table 11 can be used to determine the configuration of the RXFOLLOWUP register; see Section 8.2.2.9 "Register RXFOLLOWUP" on page 103. Note that an interrupt may be generated when a wakeup search or a preamble detection ends. All other interrupts can be enabled with the interrupt enable register.

7.24 Signal signature recognition unit

The signal signature recognition unit provides a user-friendly and easy method to support quick and configurable RX tools. The basic challenge in RX mode is to distinguish noise or unwanted disturbers from the wanted RX signal. This signal quality decision must be taken within the shortest time possible to save system power consumption. The RX process must start after successful signal quality detection. The RX process basically consists of data and clock regeneration. To make the system even more robust to ambient noise and/or disturbers, the data and clock recovery can be gated by additional methods. If the baud rate and the coding of the RX signal is known, a wakeup pattern matching unit can be activated. Table 12 gives a comprehensive overview of the various available units. All units are individually selected and configured.

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Table 12.   Overview of the signal signature recognition unit

Recognition unit	Block name	Signal process	Started by	Purpose
RSSI level classification	RSSI level classification	digitised RSSI	-	determine correct signal strength; upper and lower limit can be defined
Modulation amplitude classification	modulation amplitude classification	demodulated baseband	start of wakeup search	determine correct FSK/ASK modulation amplitude
Data classification	slicer	demodulated baseband	start of wakeup search, only if initial acquisition is enabled	enable selection for different data slicer behavior (fast settling, long averaging, hold of previously acquired levels)
	chip timing verification and code checker	slicer output	slicer output valid after start of wakeup search	decode and search for correct Manchester coding and special coding sequences
	baud-rate checker	slicer output	FIRST_SYNC or RESYNC of the timing verification after start of wakeup search	check for correct baud rate
	preamble checker	slicer output	end of wakeup search	configurable 1-to-32 bit preamble pattern matching
Wakeup search timer	wakeup search timer	-	start of wakeup search	start/end of recognition sequence

7.24.1 RSSI level classification

The RSSI circuit is used for ASK demodulation, for determining the front-end gain switch threshold and for signal level detection. Two different application scenarios can be supported by a level detection circuit.

- Check for a carrier signal strength within a given threshold, i.e. above a minimum level or below a maximum level or between minimum and maximum
- Check for a carrier signal strength outside a given threshold, i.e. below a minimum level or above a maximum level

The first scenario can be used to determine the presence of a carrier as a precondition for other demodulation or classification measures. The second scenario is useful to quickly check for occupied channels in a multi-channel system.

The RSSI classification unit is a window comparator with programmable threshold values.

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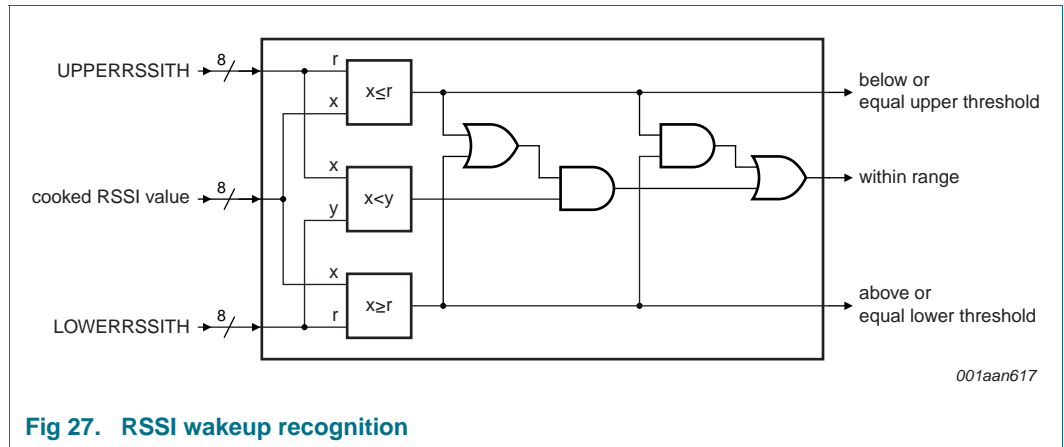
7.24.1.1 Functional block diagram

Fig 27. RSSI wakeup recognition

Input signals:

- 8-bit digitised RSSI value
- 8-bit upper limit of the desired RSSI range
- 8-bit lower limit of the desired RSSI range

Output signals:

Two individual signals, which indicate whether the input signal is above or below the respective threshold; these two indicators are provided as (latched) status information.

The logic combination of the two output signals indicates that the RSSI signal is within the range defined by the two thresholds. The definition of what is intended by the phrase 'within the range' depends on whether the value of the upper limit is greater or less than the lower limit. This is illustrated in Figure 28.
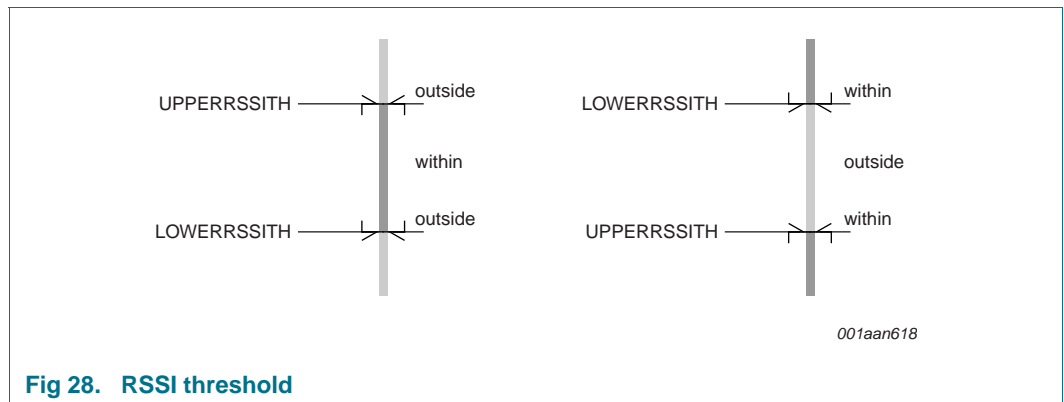

Fig 28. RSSI threshold

If a single minimum threshold is desired, the UPPERRSSITH[7:0] value must be set to 255 (0xFF). To achieve a single maximum threshold, the LOWERRSSITH[7:0] register must be set to logic 0.

7.24.2 Modulation amplitude classification

This block consists of two sub-blocks, the first of which is the amplitude measurement, which is followed by a threshold comparison and the decision logic.

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7.24.2.1 Method to determine the modulation amplitude

The modulation amplitude classification block measures the magnitude of the signal transitions within one chip interval. The baseband signal is delayed by one chip interval using an oversampling ratio of 4 samples per chip interval. A raw amplitude measurement is computed for each sample by subtracting the delayed sample and taking the absolute value of the difference. Then for each chip interval the maximum of the four adjacent raw values is determined.
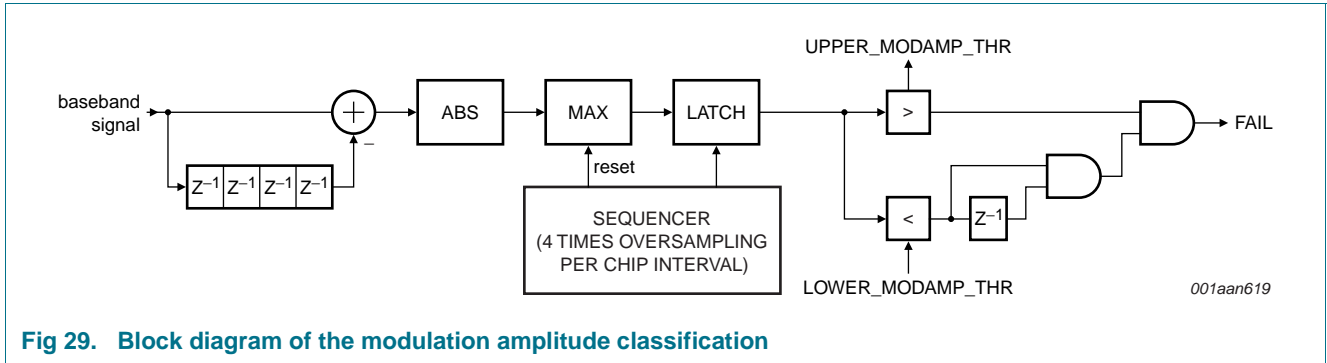

Fig 29. Block diagram of the modulation amplitude classification

If there is a transition in the chip interval, the output of this measurement is valid. If there is no transition in the interval the output from the measurement can be much lower than the nominal amplitude. This appears as a gap in the sequence of measurements. If we consider a Manchester coded signal having at least one transition within each two-chip interval, we have to accept (and ignore) at most one gap between valid measurements. The modulation amplitude is compared against the threshold defined with register LMODAMPTH and if it is lower than the threshold for a duration greater than NUM_MODAMP_GAPS_x[1:0] $\times$ (chip duration), then a 'modulation amplitude too low' error is reported in bit 0 of register SIGMONERROR.

4 $\times$ oversampling.
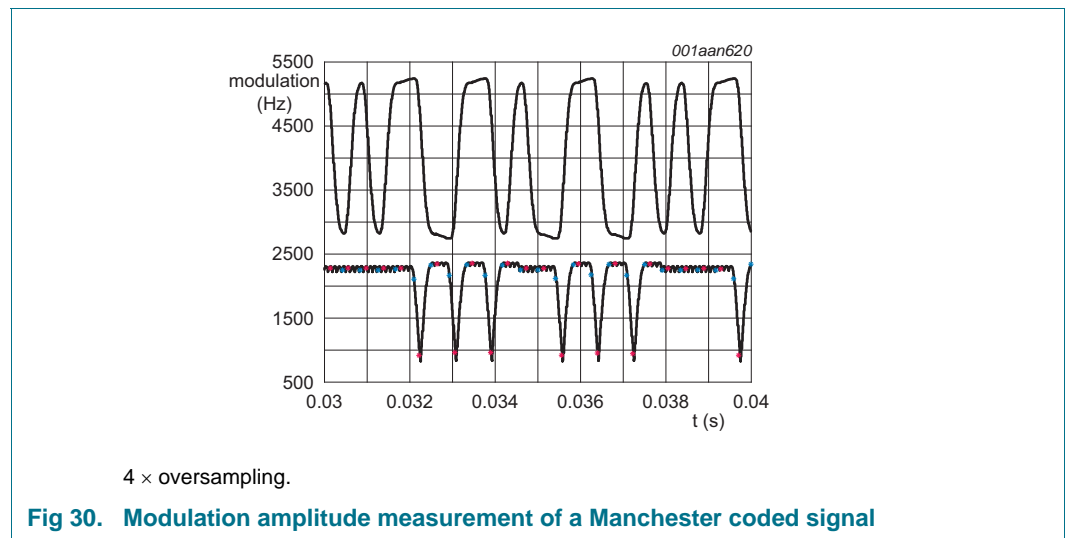
Fig 30. Modulation amplitude measurement of a Manchester coded signal

Figure 30 shows an example of the amplitude measurement when measuring a noise-free Manchester encoded baseband signal. The top waveform is the baseband signal. Note that this signal can have an arbitrary offset. The lower waveform shows the output of the amplitude measurement. The red dots show the actual values (oversampling rate of 4 versus the chip-clock) used for computation.

Due to the ripple in the output signal (lower trace) and the discrete sampling time, the sampled signal can be lower than the theoretical maximum value. Worst case input signals for this algorithm produce a maximum amplitude error of 8 % of the maximum theoretical value.
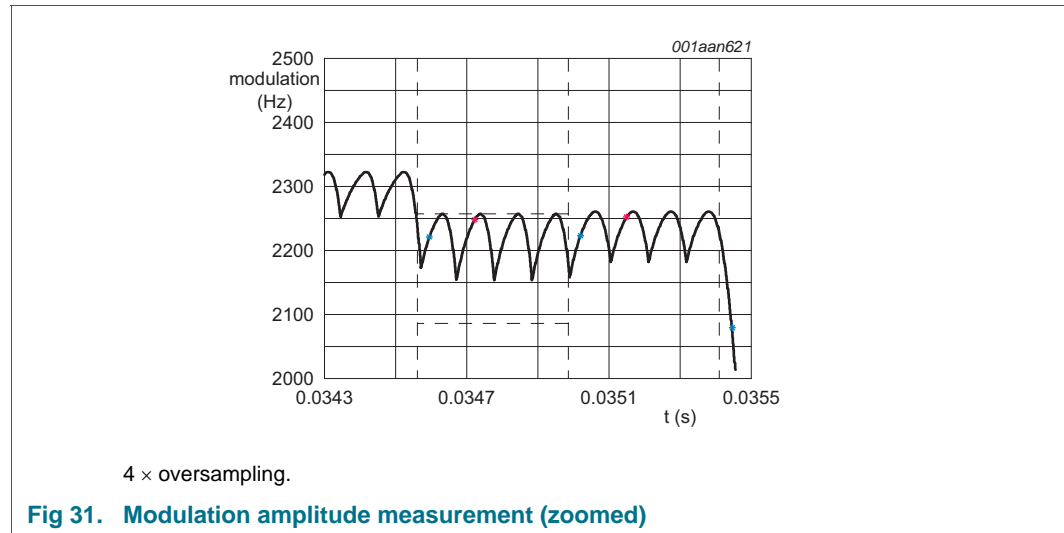

4 × oversampling.

Fig 31. Modulation amplitude measurement (zoomed)

In this example the upper horizontal dashed line corresponds to the actual amplitude A_{act}. The lower horizontal dashed line corresponds to A_{act} −8 % = 0.92 A_{act}. Consider this when calculating the lower and upper limit for the modulation amplitude detection. The higher limit can be set close to the expected value, the lower limit must be at least 8 % lower than the expected value.

The amplitude measurement for each chip interval is compared with two programmable thresholds. If the measured amplitude is above the upper threshold, the result is immediately classed as a FAIL. If the measured amplitude is below the lower threshold, this can be either a low amplitude condition or a gap. The outcome is a FAIL if two successive amplitude measurements deliver a value which is below the lower threshold; there must be no more than one gap between valid measurements.

The lower and upper thresholds can be independently selected with the 8 bit registers LOWER_MODAMP_TH and UPPER_MODAMP_TH, respectively. The actual threshold value is defined by the associated register settings according to Equation 22.

$$\text{xxxThresholdValue} \ = \ min(2^{\text{xxx\_MODAMP\_TH[7:4]}} \times \text{xxx\_MODAMP\_TH[3:0]}, \text{7FFFh}) \tag{22}$$

Where xxx stands for LOWER_ or UPPER_.

Example: FSK signal Manchester coded, 2 kbit/s respectively 4 kchip/s, modulation deviation: ±1.5 kHz.

The FSK signal must be mapped to the output range of the FSK demodulator. The output signal range is 0 to 32256. This range equates to a frequency deviation of 200 kHz respectively 600 kHz, depending on bit LARGE_FM_DEM_RANGE in register EXPERT2. The expected peak-to-peak modulation amplitude is 1.5 / 200 × 32256 = 242.

The UPPER_MODAMP_TH is set to at least the expected value: $16 \times 2^4 = 256$.

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UPPER_MODAMP_TH_MANT[3:0] = 15d = 1111b

UPPER_MODAMP_TH_EXP[7:4] = 4d = 0100b.

The LOWER_MODAMP_TH should be set to 92 % of the maximum expected value: $242 \times 0.92 = 222$.

The closest programmable value not exceeding this is $13 \times 24 = 208$. Therefore, the LOWER_MODAMP_TH should be programmed as follows:

LOWER _MODAMP_TH_MANT[3:0] = 13d = 1101b

LOWER _MODAMP_TH_EXP[7:4] = 4d = 0100b

The lower and the upper thresholds can be disabled. The lower threshold is disabled by setting LOWER_MODAMP_TH to 0d and the higher threshold is disabled by any value: UPPER_MODAMP_TH $\geq 2^{15}$.

7.25 Data classification

The data slicer is used for the timing, code and baud rate classification modules.

7.25.1 Data slicer

The device features a versatile collection of different data slicers with different initialisation and adaptation mechanisms, including:

- an edge-sensitive slicer with minimum latency: used in applications where fast data slicer settling times are crucial
- a level-sensitive slicer: more robust to noise, appropriate when a longer settling time is acceptable

7.25.1.1 Number of corrupted bits in RX mode

The number of corrupted bits during the start of RX mode depends on the selected slicer method and the associated settings. The edge slicer provides the fastest possible settling time, only 1 chip period (1 / 2 bit) is lost. The loss of level-sensitive slicer bits depends on its initialization setting. If the initialization sequence is selected, 4 chips (2 bits) or 16 chips (8 bits) can be lost. It is possible to recover all bits, provided the level sensitive slicer is pre-initialized to the correct threshold.

7.25.1.2 Slicer description

The level-sensitive slicer is configured by the RXDCONx registers; see Section 8.2.1.26 "Register RXDCON0" on page 96. The level slicer threshold can also be initialized with a desired value by programming registers SLICERINITL and SLICERINITH. This could be used to improve level slicer settling time. The actual level slicer threshold currently used can be read from these registers at any time.
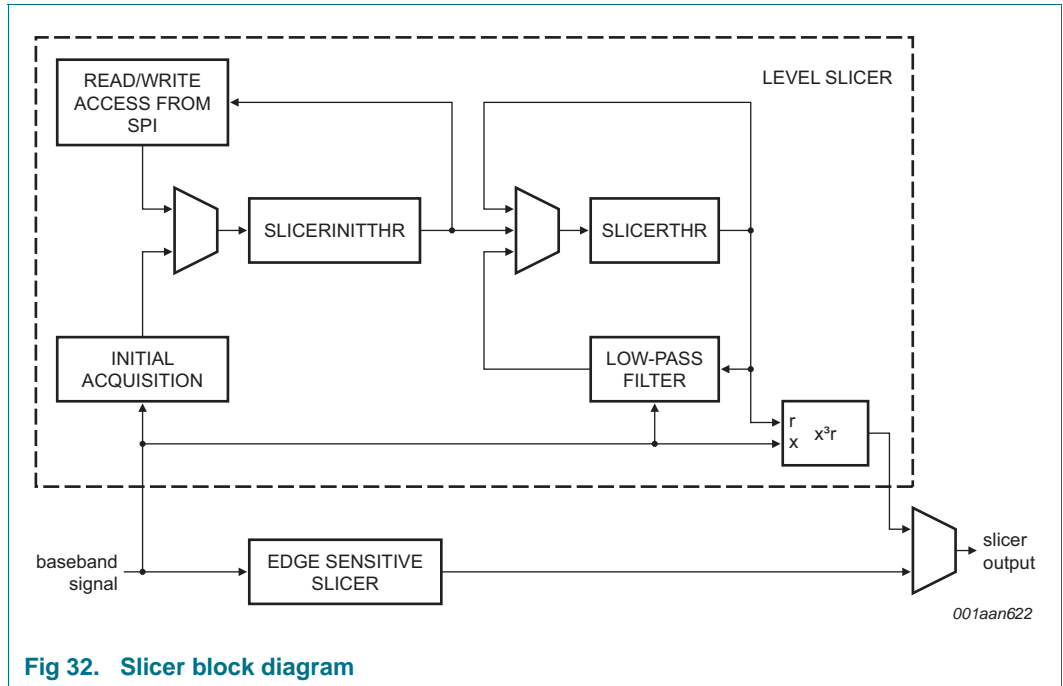
Fig 32. Slicer block diagram

The edge-sensitive slicer will not make use of these two registers. The EDGE_MODAMP_TH contains the expected peak modulation amplitude with which the edge slicer is initialized. The expected peak modulation value is provided by the EDGE_MODAMP_TH[7:0] register; see Section 8.2.1.25 "Register EMODAMPTH" on page 95. The EDGE_MODAMP_TH is calculated by:

$$\text{ThresholdValue} = 2^{\text{EDGE\_MODAMP\_TH}[7:4]} \times \text{EDGE\_MODAMP\_TH}[3:0] \tag{23}$$

7.25.2 Edge slicer

The edge slicer operates as a differentiating slicer in combination with a fixed-level slicer. The time-constant is automatically adjusted in accordance with the selected chip rate of the baud-rate generator unit. This slicer is also capable of demodulating NRZ code with long constant bit sequences provided the expected peak modulation amplitude initializes correctly. The basic principle of the edge slicer is explained in Figure 33.
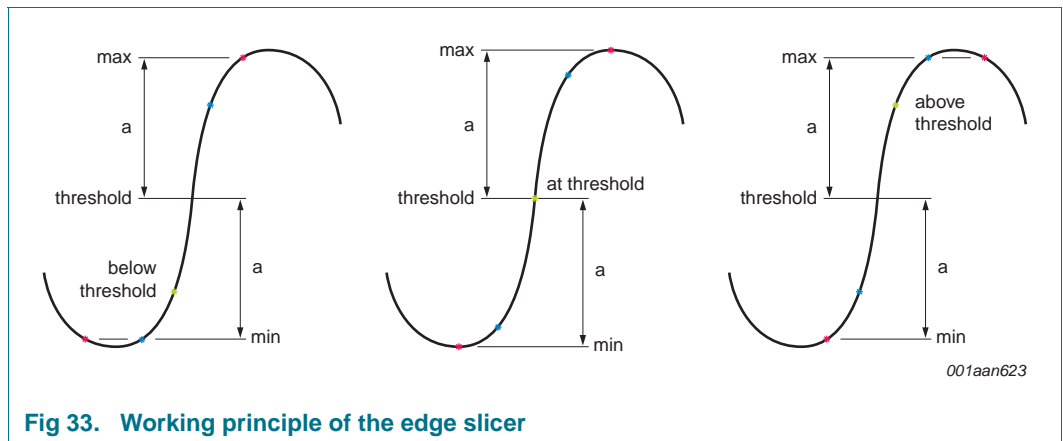

Fig 33. Working principle of the edge slicer

The slicer operating mode slicer is selected by the slicer selection bits SLICERSEL_W[1:0]; see Table 66 "SLICERSEL_W bit functions" on page 96.

The edge slicer takes five adjacent samples at intervals equivalent to ¼ of the chip width. The four outermost samples (red and blue dots in Figure 33) are used to make up a dynamic threshold and the middle sample (green dot) is compared against this. The threshold value is the average of the maximum and minimum of the four outermost points.

The exact description of the algorithm for the edge slicer is:

1. Consider 5 consecutive samples taken at a distance a ¼ of the chip period width.
2. Compute the minimum and the maximum of all samples except the middle one.
3. Take the average of the maximum and the minimum as the slicer threshold.
4. Compute the maximum and the minimum of the two neighbors of the middle sample.
5. Take the difference of the maximum and the minimum as the amplitude measurement.
6. Compare the measured amplitude against the peak value of the signal which is provided by register EMODAMPTH; see Section 8.2.1.25 "Register EMODAMPTH" on page 95.
7. If the amplitude is above the threshold, set the slicer output according to the comparison of the signal (middle sample) with respect to the slicer threshold.
8. If the amplitude is below the threshold, keep the current state of the slicer output.

The following list summarizes the properties of the edge slicer algorithm:

- Because the input signal needs to be fed through a delay line and because of the necessary linear interpolation the slicer has a delay of about one chip interval.
- Since the slicer acts only on valid signal edges and since it ignores what is between these edges, it can handle arbitrary coded signals, including NRZ.
- The slicer output is valid after the first signal edge and the slicer delay.
- Due to its differentiating function, the edge slicer is more susceptible to noise than slicer threshold generation methods which average over the signal (level-sensitive slicer).

The slicer needs to know the expected amplitude of the baseband signal for amplitude classification, this can be easily provided for FSK signals.

The following configuration settings must be initialized when the edge slicer is used.

Expected peak modulation value: must be provided by the EDGE_MODAMP_TH[7:0] register; see Section 8.2.1.25 "Register EMODAMPTH" on page 95. The EDGE_MODAMP_TH[7:0] value must be calculated using the following procedure:

$$\mathrm{ThresholdValue} \ = \ 2^{\mathrm{EDGE\_MODAMP\_TH[7:4]}} \times \mathrm{EDGE\_MODAMP\_TH[3:0]} \tag{24}$$

Example: FSK signal Manchester coded, 2 kbit/s respectively, 4 kchip/s, modulation deviation: ±1.5 kHz.

The FSK signal must be mapped to the output range of the FSK demodulator. The output signal range is from 0 to 32256. This range equates to a frequency deviation of 200 kHz to 600 kHz depending on bit LARGE_FM_DEM_RANGE in register EXPERT2. The expected peak modulation amplitude is $1.5 / 200 \times 32256 = 242$. The EDGE_MODAMP_TH is set as close as possible to the expected value: $15 \times 2^4 = 240$.

EDGE_MODAMP_TH_MANT[3:0] = 15d = 1111b

EDGE_MODAMP_TH[7:4] = 4d = 0100b

7.25.2.1 Edge slicer signal monitor setting

The lower and upper thresholds for the peak-to-peak amplitude of the baseband signal (FSK modulation) are simply the TX peak-to-peak frequency deviation plus and minus a guard band tolerance (factor of 3 / 4 or 5 / 4) mapped to the output range of the FSK demodulator. They can be calculated with the following equations:

Register LMODAMPTH = $3000 \times (32256 / 200000) \times (3 / 4) = 362$.

Register UMODAMPTH = $3000 \times (32256 / 200000) \times (5 / 4) = 605$.

Register UMODAMPTH must be set to a value higher than 605 ($10 \times 2^6 = 640$).

UMODAMPTH[3:0] = 10d = 1010b

UMODAMPTH[7:4] = 6d = 0110b

Register LMODAMPTH must be set to a value lower than 362 ($11 \times 2^5 = 352$).

LMODAMPTH[3:0] = 11d = 1011b

LMODAMPTH[7:4] = 5d = 0101b

Remark: the amplitude threshold must be set to the expected peak amplitude value.

7.25.3 Level-sensitive slicer

The level-sensitive slicer offers various features which can be configured to improve noise immunity or to reduce latency; see Section 8.2.1.26 "Register RXDCON0" on page 96.

These include:

- User-definable initialisation value
- Initial acquisition of the threshold by averaging the baseband signal over 2, 4, and 8 bits
- Continuously variable threshold configured according to output from 1st-order low-pass filter

The slicer operating mode is selected with slicer selection bits SLICERSEL_x[1:0] according to Table 66 "SLICERSEL_W bit functions" on page 96.

The time-constant for the low-pass filter is derived from the baud-rate generator settings. It is assumed that a Manchester encoded single bit comprises two chips.

The various level slicer initialisation mechanisms are controlled by bits SLICERINITSEL_x[1:0]. If the slicer is initialized, its output becomes invalid for at least one cycle, which restarts the deglitcher and the edge detector. The output remains valid even when the slicer threshold is updated after the initial acquisition refines its threshold value (after 4 and 8 bits).

7.25.3.1 Level-sensitive slicer initial acquisition

The initial acquisition generates a first estimate of the threshold by averaging the RX baseband signal over a fixed time interval of two bits. If a constant 0 or 1 sequence or an alternating 01 sequence is received, the expected value of the error is exactly zero. If a Manchester encoded signal is being received, the maximum error can be ¼ of the whole swing, which is sufficient for an initial estimation. After having calculated this average, the slicer output changes from UNKNOWN to VALID.

The following samples from the baseband signal are used to improve the initially found threshold. After processing an additional 2-bit interval (4 bits in total), a new average is computed having less uncertainty as the initial value (by a factor $\sqrt{2}$). This is used as the new slicer threshold. Once an additional 4-bit interval is accumulated, having processed 8 bits in total, the final, more accurate estimate for the threshold can be calculated. This threshold value can be read via register SLICERINITH. Register SLICERINITL is automatically updated every time a new initial slicer threshold is available.

It is possible that the 2-bit interval period used for the initial estimate lies in a time period where there is either no RF, RF with only CW (no modulation) or the frame start containing Manchester code violations. In this case the slicer output may have no edges for a long time interval, which may indicate an incorrectly chosen threshold value. If the timing verification block detects a timeout (time interval between edges > 3.5 chip width) it makes sense to reset the threshold estimation in order to get a better initial threshold value. The slicer's output is again UNKNOWN after the reset for the next 2-bit interval. The slicer's output becomes VALID again and the classification of its output edges may provide successful data reception. If the RX signal is not usable the slicer may be reset several times until the selected RX operation is aborted.

If the initial acquisition is not used during the wakeup search, it might be useful to disable the auto-reset feature mentioned above. This can be accomplished by a dedicated setting in register SLICERINITSEL.

The initial acquisition operation always inhibits the use of the slicer output (status UNKNOWN) during the calculation of the first two bits, regardless of whether the initial acquisition was triggered for the first time (by an RX event) or if it was re-triggered from a bit timeout.

The initial acquisition updates the slicer initialisation register and the slicer register after the calculation of 2, 4, and 8 bits (selected by INIT_ACQ_BITS) provided the RX event was not interrupted by the higher-level state machine. In these circumstances the initial acquisition is stopped to avoid unwanted data corrupting the calculation of the threshold.

Access register SLICERINITH only via the SPI if the initial acquisition is not active. Failure to comply with this may result in the reading of unstable values and the content of register SLICERINITH may become undefined.

7.25.4 Deglitcher and edge detector

The purpose of the deglitcher is to suppress multiple signal transitions when a noisy baseband signal crosses the slicer threshold. The deglitcher operates as follows: if a signal transition is detected, the deglitcher passes the transition to its output and then it locks this output for a certain time period, which can be selected by DEGLITCHER_WINDOW_LEN[1:0] according to Table 61 "DEGLITCHER_WINDOW_LEN bit functions" on page 94.

The lock timer is held in its reset state while the slicer output is invalid. This means that the deglitcher can only enter its locking state when the edge detector produces an output event.

The edge detector locates the edges in the deglitched slicer output and supplies the blocks which measure and classify time intervals between edges. The edge detector produces edges only after the slicer output is valid. If the slicer produces a transition at the same time as its output becomes valid, it is suppressed by the edge detector. The deglitcher lock window is also suppressed by the edge detector and only becomes active when the edge detector produces an output event.
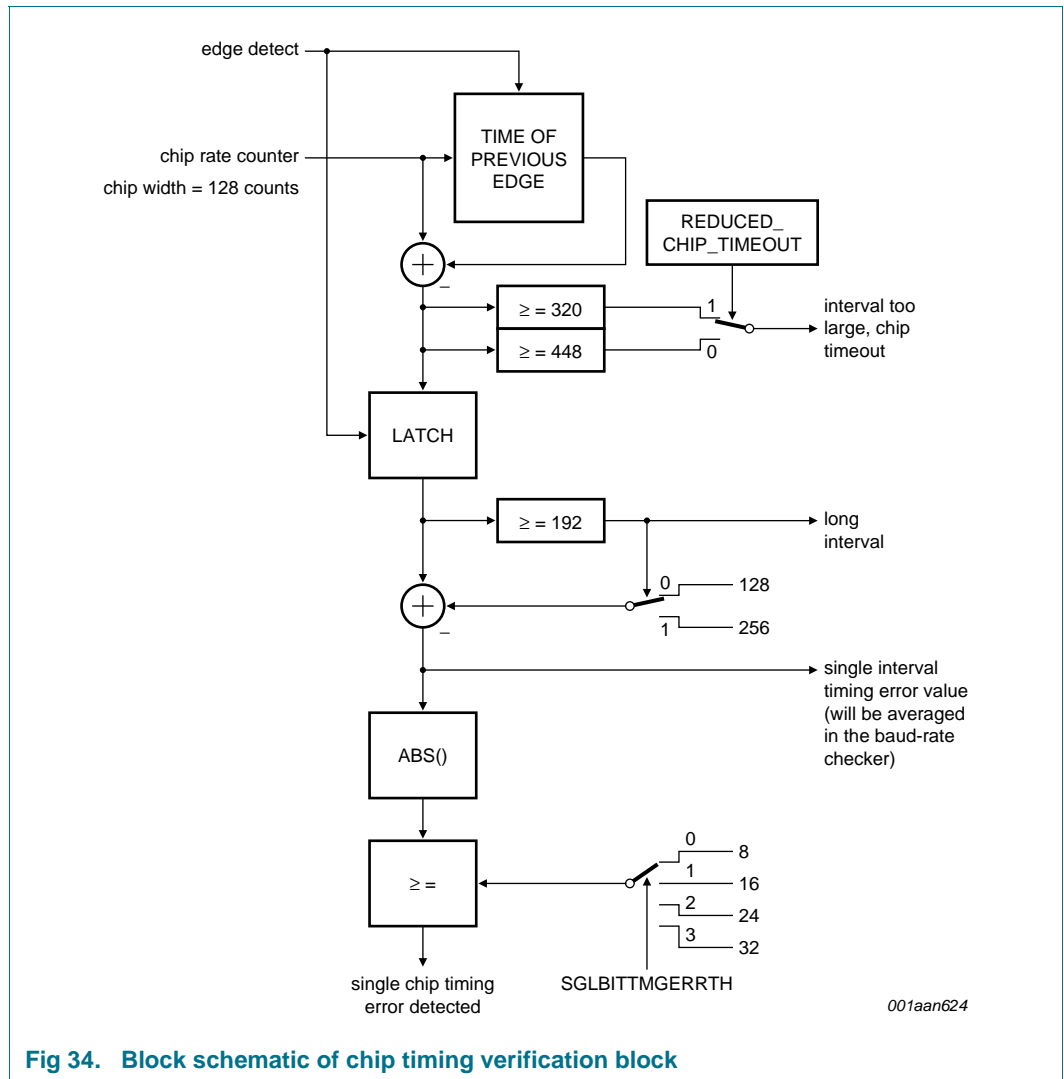
7.26 Timing classification block

The purpose of this module is to classify the time intervals between the transitions from the slicer and to determine whether the RX signal is a Manchester coded signal. Certain additional conditions can be selected.

The property of a Manchester coded signal, used as the main classification criteria in this block, is that there are only two different time intervals, namely one chip width or two chip widths between two transitions.

7.26.1 Chip timing verification

In the proposed implementation, the signal is oversampled with an OSR of 128, giving a time measurement resolution that is better than 1 %. The time interval between each pair of transitions is measured. If the measured time interval is $< 1.5 \times$ chip width, then it is assumed that the associated nominal width is $1 \times$ chip width and so $1 \times$ chip width is subtracted from the measurement to calculate the timing error. If the measured time interval is $> 1.5 \times$ chip width then it is assumed that the associated nominal width is $2 \times$ chip width and so $2 \times$ chip width is subtracted from the measurement to calculate the timing error. This measurement includes a timeout such that widths greater than $3.5 \times$ chip width are always rejected. The absolute value of the timing error is calculated and compared to a limit which can be chosen from the 16, 24, 32, or 48 counts of the oversampling clock according to the setting of bits SGLBITTMGERRTH[1:0]; see Section 8.2.2.7 "Register TIMINGCHK" on page 101. The time interval is accepted if its absolute value is below the limit. This corresponds to timing errors which are less than 12.5 %, 18.75 %, 25 % and 37.5 % of a nominal chip width, respectively. The single-chip timing verification block is a powerful means to classify signals with a given baud rate. The edges of these signals are assumed to emerge at a virtual chip grid. Therefore, the same absolute error limit is applied for short and long intervals to allow a specified range of edge jitter.

The chip timeout value can be changed with an expert bit. The standard value is $3.5 \times T_{CHIP}$. This value can be reduced to $2.5 \times T_{CHIP}$ if bit REDUCED_CHIP_TIMEOUT is set; see Section 8.2.4.3 "Register EXPERT2" on page 109.

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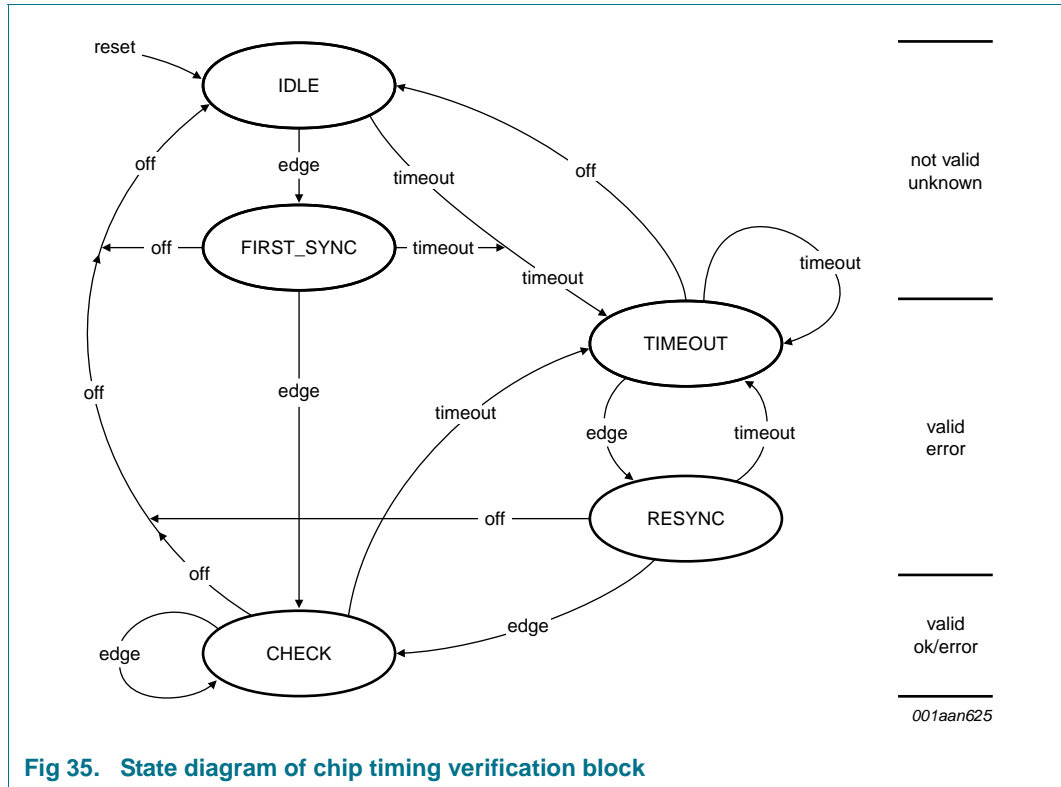**Fig 34. Block schematic of chip timing verification block**

Fig 35. State diagram of chip timing verification block

After the first synchronisation (reception of two edges) the chip timing verification block becomes VALID and the chip timing CHECK begins. The last chip timing step is directly used as the ERROR criteria when in this state.

If a timeout occurs, the state machine signals an ERROR. Upon reception of two consecutive edges, the timing verification block can be re-synchronised, the state machine then again entering the CHECK state.

Remark: a single chip timing error will not change the state of the state machine unless it is a timeout.

7.26.2 Code checker

Typical wakeup patterns consist either of a constant 0 sequence, a constant 1 sequence, or an alternating 01 sequence. In these cases the pattern only contains a single time interval length. It is therefore possible to apply further restrictions on the accepted time intervals.

Correct chip timing is a pre-requisite for the code checker. A single bit timing error always causes a code checker error. Changing the setting of CODINGRESTR_W[1:0], while the code checker is running is not recommended; see Section 8.2.1.28 "Register RXDCON2" on page 97. This can cause a false error indication. A false error indication may arise at a later stage if Manchester code checking is newly selected. The Manchester MANCHESTER START state is not necessarily executed immediately.

CodeViolation = Edge × [SingleBitTimingError or (CODINGRESTR = 1) × LongInterval or (CODINGRESTR = 2) × ShortInterval].

CodeOK = Edge × [(CODINGRESTR = 0) or (CODINGRESTR = 1) × ShortInterval or (CODINGRESTR = 2) × LongInterval].

ManchesterLong = Edge × (CODINGRESTR = 3) × LongInterval.

ManchesterShort = Edge × (CODINGRESTR = 3) × ShortInterval.

Fig 36. Code checker state diagram
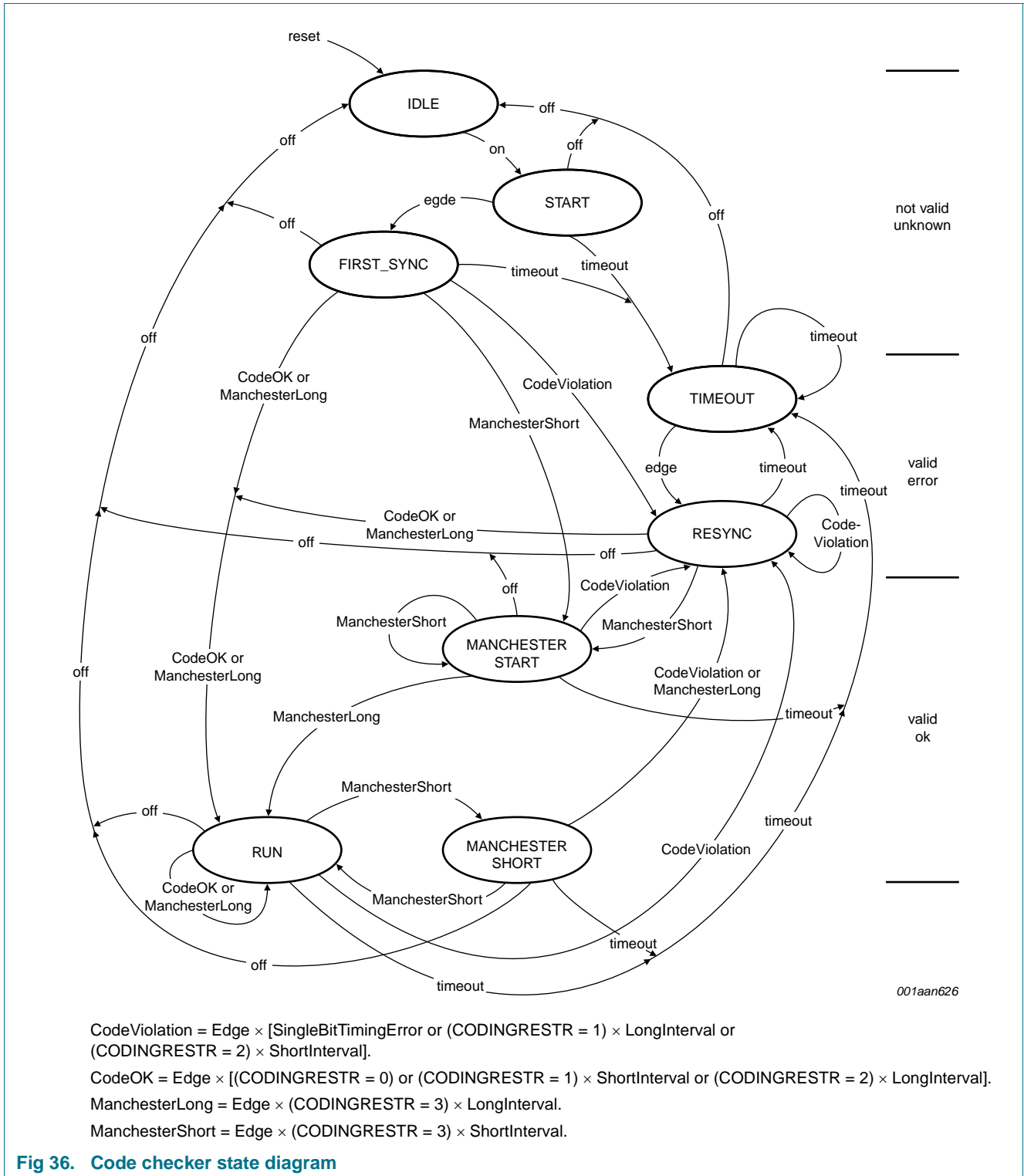
The timeout is derived from the chip timing verification block, i.e. a timeout is generated if a bit exceeds a length of 3.5 × chip width.

The OK/ERROR information is directly derived from the state machine. The RESYNC state is initiated after a code violation is recognized by any of the other states, unlike the chip timing verification block which only enters the RESYNC state after the occurrence of a timeout.

If CODINGRESTR_W[1:0] is set, it is only possible to differentiate between a run of zeros or a run of ones (short time intervals) if the first long time interval is received, thus determining if the data represents a 01 or a 10 transition. Once the long time interval is received, the remaining sequence can be checked against Manchester coding rules. After a long interval is detected, short intervals must always be in pairs; the following sequence is illegal: SSSSSLLSSLSSSSL**SSS**L.

7.26.3 Baud-rate checker

An averaging facility is implemented to increase the accuracy of the single time interval check and baud-rate detection by a factor of 4. This averaging is performed on blocks of 8 bits, where the first block starts whenever the chip timing block reaches either FIRST_SYNC state or RESYNC state. Correct timing of a single bit is a prerequisite for the baud-rate checker, therefore averaging is restarted even if a single bit timing error occurs.

The baud-rate checker has no information about the coding of the signal. Thus it is possible that a sequence of 8 bits comprises 17 instead of 16 chips, e.g. if 15 short intervals followed by one long interval are to be examined. If a sequence of several 8-bit blocks is assessed, the accumulated timing uncertainty is never more than 1 chip.

Averaging over 16 chips requires dividing the sum of the individual timing errors by 16, thus causing an unnecessary loss of precision. Therefore the division is omitted and only the timing errors are summed during an 8-bit block. The product of the 8 bits is compared against a limit which can be selected by SUMBITTMGERRTH[2:0] according to Table 82 "SUMBITTMGERRTH bit functions" on page 101.

This block can be easily extended to allow the number of observed bits to be adjusted to either 8, 16, 24 or 32 bits according to the baud rate observation length setting BROBSLENGTH[1:0]; see Table 81 "BROBSLENGTH bit functions" on page 101.

The output of the baud-rate checker is only VALID after the absolute value of the sum of the received 8 bits is checked against the limit. The output immediately signals an ERROR if the limit is violated. If the sum value is within the limit, the measurement proceeds until either a limit violation is detected or the requested number of bits are observed. In the latter case the output becomes VALID and signals OK.

The baud-rate checker continues checking on an 8-bit basis after the requested number of bits was checked successfully. The ERROR signal is updated at the end of every 8-bit sequence. It stays VALID and OK if the baud rate is within the limit. If the baud rate is outside the limit, an ERROR is signalled and the baud-rate checker restarts. The ERROR signal is retained as long as no 8-bit sequence is within the limit. If the selected observation length is greater than 8 bits, the baud-rate checker enters the NOT VALID state as soon as the first correct 8-bit sequence is received and finally signals VALID and OK after successful reception of the selected observation length. This mechanism assures that the baud-rate checker can only signal VALID and OK once the selected number of consecutive bits are received with the correct baud rate.

On the occurrence of a timeout or a single bit timing error, the baud-rate checker resets immediately, NOT VALID is signalled instantaneously and the baud-rate checker restarts.

7.26.4 Timeout timer for the wakeup search

The control logic includes a timeout timer for the wakeup search operation. When used, this timer generates a negative wakeup detection output provided a positive wakeup detection is not generated prior to the timer expiration. When this timer is disabled, the output of the wakeup search operation is instantly negative upon a failure signal from any of the detection operations.
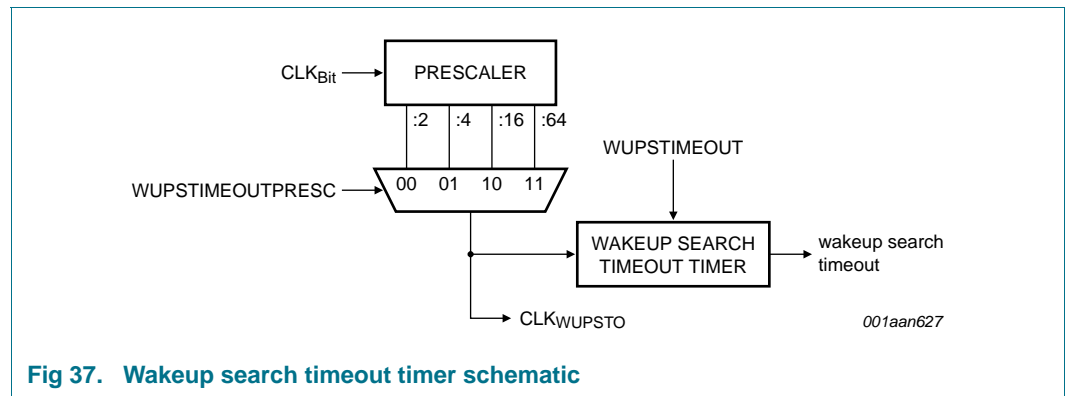

Fig 37. Wakeup search timeout timer schematic

The wakeup search timer consists of a prescaler and a timer register. The clock is derived from the mainscaler clock and is therefore associated with the selected baud rate.

The timeout can be selected by WUPSTIMEOUT[5:0] and is calculated as WUPSTIMEOUT5:0] $\times$ T$_{WUPSTO}$ for WUPSTIMEOUT[5:0] = 1 to 63d.

The value WUPSTIMEOUT[5:0] = 0 disables the timeout timer and selects an infinite timeout.

The generated timeout has an uncertainty of −2 to 0 T$_{BIT}$ regardless of the setting of WUPSTIMEOUTPRESC[1:0] and WUPSTIMEOUT[5:0].

Timeout timer resolution and range:

- The fastest bit rate of 50 kbit/s requires the timeout to be adjusted in a range of 40 μs up to 80 ms with a resolution of 40 μs, 80 μs, 320 μs, and 1.28 ms respectively.

- A bit rate of 1 kbit/s requires the timeout to be adjusted in a range of 2 ms up to 4 s with a resolution of 2 ms, 4 ms, 16 ms, and 64 ms respectively; see Section 8.2.2.4 "Register WUPSTO" on page 100.

7.27 Wakeup search logic

A summary of the signal monitoring conditions which can be used as wakeup criteria are shown in Table 13.

Table 13. Overview of signal monitoring methods

Block name	Processes the signal	Started by	Output is valid after	Can be started by
RSSI level classification	digitised RSSI	-	input is valid	-
Modulation amplitude classification	demodulated baseband	start of wakeup search	2 chips	-
Slicer		start of wakeup search only if initial acquisition is enabled	2 bits if initial acquisition, otherwise immediately	timeout from chip timing verification, only if enabled and in mode 2
Chip timing verification and code checker	slicer output	slicer output valid after start of wakeup search	0 < t <5 chips (2 chip time-outs)	in mode 2 by the slicer, only if initial acquisition is enabled
Baud-rate checker		FIRST_SYNC or RESYNC of the timing verification after start of wakeup search	8 bits ≤ t ≤ configured observation length (8, 16, 24 or 32 bits)	in mode 2 by the chip timing verification with another FIRST_SYNC or RESYNC
Wakeup search timer	-	start of wakeup search	FAIL after configured timeout	-

At the start of a wakeup search the following blocks are reset:

- wakeup search timer
- modulation amplitude classification
- chip timing verification and code checker
- baud-rate checker
- the slicer (conditionally)

The slicer is only reset if configured to acquire the value from the slicer initialisation register (SLICERINITSEL_x[1:0] not equal to 00b). If slicer initial acquisition is selected, the chip timing verification, code checker block and baud-rate checker are held in the reset state for the duration of the slicer initial acquisition mode.

Register SIGMON_EN_W[5:0] provides enable bits which determine signal monitors that are considered for the overall wakeup detection decision; see Section 8.2.2.1 "Signal monitoring register SIGMON0" on page 98. All signal monitors operate regardless of these enable bits and, after the wakeup search ends, their results are available in the corresponding status bits. Section 7.27.1 and Section 7.27.2 describe how the individual results from several signal monitors can be combined to achieve an overall wakeup decision.

Each of the signal monitors can have an invalid period caused by an initialisation or resynchronisation during which the output result is not considered. The logic depicted in Figure 38 shows how this information is translated into the PASS/FAIL condition used by the wakeup search logic. If a signal monitor is in its invalid state, neither a PASS or FAIL condition is generated. If a signal monitor is not selected for the wakeup search, the FAIL is always zero and the PASS always one. The PASS and FAIL signals are exclusively used for the wakeup search logic and they must not be confused with the actual state of the corresponding signal monitor (signals VALID and ERROR) which can be observed in registers SIGMONSTATUS and SIGMONERROR; see Section 8.2.2.10 "Register SIGMONSTATUS" on page 105.
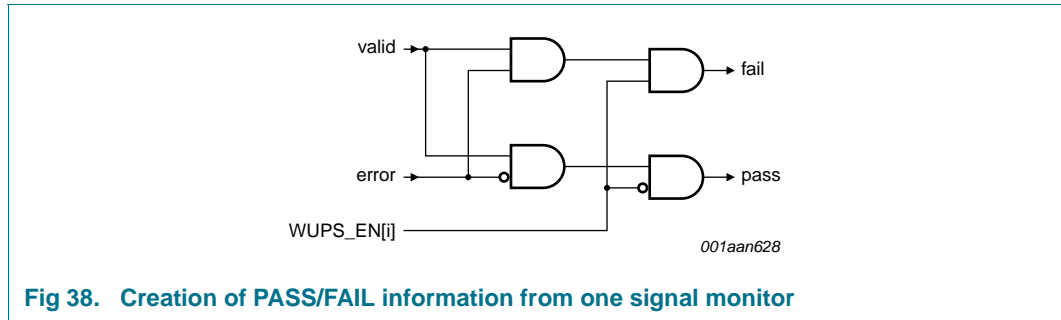
Fig 38. Creation of PASS/FAIL information from one signal monitor

Two different mechanisms are provided for the wakeup search:

- 'pessimistic wakeup search' or mode 1
- 'optimistic wakeup search' or mode 2

In the pessimistic wakeup search (mode 1) the wakeup search timer has no meaning and therefore will not influence the result. In the optimistic wakeup search (mode 2) the wakeup search timer is always active.
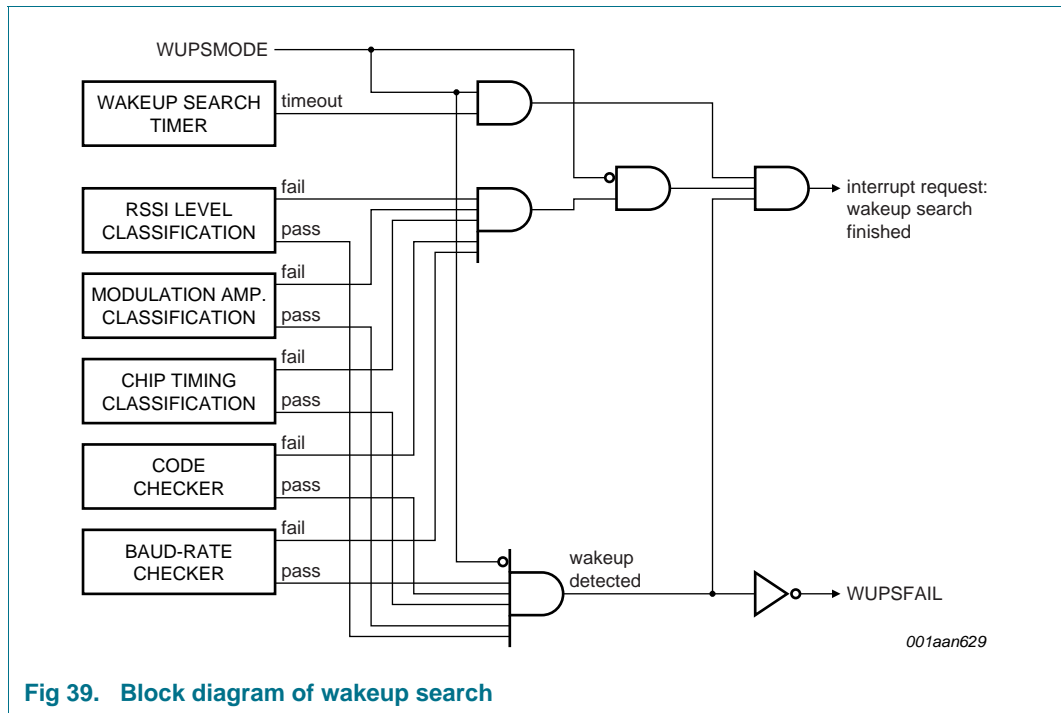
Fig 39. Block diagram of wakeup search

At the end of the wakeup search an interrupt request is generated and the result is stored in bit WUPSFAIL. If this bit is set, it signals that the wakeup criteria was not met. Otherwise it is cleared. The content of this bit is undefined prior to first use of the wakeup search.

The polarity of bit WUPSFAIL is chosen so that register SIGMONSTATUS can be used as a mask for register SIGMONERROR when the host controller is interested in retrieving the cause of an unsuccessful wakeup detection. If the wakeup search was successful (bit WUPSFAIL is cleared) the content of register SIGMONERROR is not required to be considered as all relevant bits are cleared.

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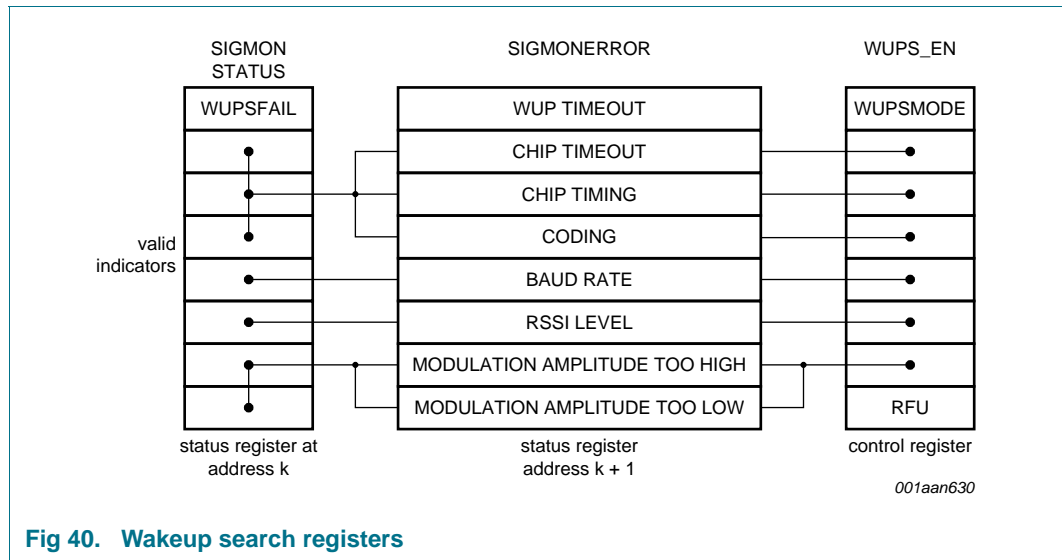
Fig 40. Wakeup search registers

7.27.1 Sampling the signal monitoring status

Since the information from the OL2311's signal monitoring method is made up of more than 8 bits, it is desirable to provide a mechanism which ensures that the controller can always retrieve a consistent set of status information. Therefore the OL2311 provides three status registers: SIGMONSTATUS, SIGMONERROR and RSSILEVEL into which the status is simultaneously transferred, whenever it is either actively requested by the controller or automatically saved by the wakeup search logic; see Section 8.2.2.12 "Register RSSILEVEL" on page 106.

There are two cases in which the status is sampled:

- after a read command, regardless of the address that follows, but only if bit STATAUTOSAMPLE is set; see Section 8.2.2.8 "Register RXCON" on page 102
- always at the end of a wakeup search

Bit STATAUTOSAMPLE either allows software to control the sampling of the status information with each read command (logic 1) or allows the status to be unaffected by any read command (logic 0). This allows consistent read and write command status information to be read as shown by the examples given in Table 14 and Table 15.

Table 14. Example 1: Using single byte reads

Command	Description
Write (STATAUTOSAMPLE, 1)	enable status sampling with the next read
Read (SIGMONSTATUS)	this samples the consistent status
Write (STATAUTOSAMPLE, 0)	disable status sampling with the next reads
Read (SIGMONERROR)	consistent with line 2
Read (RSSILEVEL)	consistent with line 2
Read (SIGMONSTATUS)	reads the same as line 2
Read (RSSILEVEL)	reads the same as line 5
Read (SIGMONERROR)	reads the same as line 4

The status of SIGMONSTATUS, SIGMONERROR and RSSILEVEL is only sampled in line 2. Single byte read commands (lines 4 and 5) only transfer the previously sampled status once bit STATAUTOSAMPLE is set back to logic 0. Lines 4 to 8 do not change the contents of the registers because status sampling is already disabled.

Table 15.   Example 2: Using read command auto-increment address

Command	Description
Write (STATAUTOSAMPLE, 1)	enable status sampling with the next read
Read (SIGMONSTATUS, SIGMONERROR, RSSILEVEL)	using the address auto-increment feature, the status is sampled at the start of the read command and then, since the status registers occupy adjacent addresses, the continuous reading of these bytes transfers the consistent status to the controller

Bit STATAUTOSAMPLE is automatically set to logic 0 at the end of a wakeup search. This guarantees that the important wakeup search results are retained until they are transferred to the controller. It can also be automatically set to logic 1 whenever the status register RSSILEVEL is transferred to the controller, provided bit AUTOSAMPLEMANUAL is cleared; see Section 8.2.2.8 "Register RXCON" on page 102. This allows the scenario following a wakeup search: the status information is automatically sampled and stored in the status registers until the last status register (RSSILEVEL) is read. The controller now continues polling the signal monitors without switching the status into 'live' mode, because reading register RSSILEVEL automatically sets bit STATAUTOSAMPLE. Note that further consistent status polling requires the address auto-increment feature to continue being used.

If automatic entry to 'live' mode is undesired, bit AUTOSAMPLEMANUAL can be set to keep bit STATAUTOSAMPLE under software control. Note that bit STATAUTOSAMPLE is always cleared after completing a wakeup search. This is necessary to guarantee that the wakeup search results are unconditionally sampled and saved until the controller acquires them.

7.27.2 Evaluating the wakeup search result

The bits in register SIGMONSTATUS provide the VALID information for the signal monitors. If a VALID flag is zero, the corresponding bit in register SIGMONERROR is also zero. Bit SIGMONERROR is set if an error occurs. The failing signal monitor can be identified by reading register SIGMONERROR. Calculating the expression SIGMONSTATUS & ~SIGMONERROR indicates which signal monitors provided a pass result; see Table 89 "Signal monitor states set by registers SIGMONSTATUS and SIGMONERROR" on page 105.

7.28 Data reception

7.28.1 Preamble detection

A preamble detection can be issued upon completion of a wakeup search or at any time when expecting a frame. The preamble pattern can be configured with a length between 1 and 32 chips. The preamble length is set with the PREA_LEN[4:0] control bits. If PREA_LEN4:0] is set to logic 0 a length of 32 chips is used. The bit error rate of the preamble can be configured with register PREA_TOL; see Section 8.2.2.13 "Register PREACON" on page 106.

7.29 RX data decoding

After a wakeup search, if configured, a preamble detection and data reception follows seamlessly. After successful completion of the wakeup search and the preamble detection, the RX data is switched to the corresponding port pins, dependent on the device configuration. The data pin is kept LOW during wakeup search and HIGH during preamble detection. Data reception can be interleaved with SPI commands. Details are given in Section 7.23.2 "Receive command" on page 42. The device has a Manchester code recovery feature which enables inversion of the RX data. The precondition of this code recovery unit is the full reception of a Manchester data stream with at least one polarity change within the code. The accumulated sum of data changes within a chip can be found in the MANCHESTER_COUNT[3:0] field in register EXTRXSTATUS; see Section 8.2.3.1 "Register EXTRXSTATUS" on page 107. This is a 4-bit signed number which is applicable only when receiving data through the Manchester decoder. It is not needed if the frame start is properly synchronised with a preamble detection. If data reception is initiated with the DATA sub-command (without preamble detection), the Manchester decoding starts at the first chip it gets, without knowing whether this is the left or the right bit half. The RX data line can deliver the data correctly or inverted. If the signal contains any bit transitions, this counter counts up if the transition occurs at the assumed bit boundary (i.e. when it is correct) and it counts down if the transition occurs in the middle of the assumed bit grid (i.e. when it is incorrect). The result is that bit 3 of this counter is logic 0 if the data is decoded properly and it is logic 1 if the data is delivered inverted. The whole counter stays at zero if the RX signal contains no bit transitions, in which case it is not possible to tell whether the RX data is a long run of only zeros or a run of ones. If the sum is negative, the RX code must be treated as inverted, if the sum is positive, the data reception was correct. It is possible to invert the RX data stream by setting bit INV_RX_DATA; see Section 7.13.1 "Clock recovery for RX mode" on page 26.

If the receiver is configured transparently (see register RXCON), the data pin is directly switched to the selected data slicer and mapped to the corresponding port pin after the RX command is issued.

7.30 RX clock generation

After a wakeup search, if configured, a preamble detection and clock recovery operate in parallel. Allow sufficient settling time from the start of data reception to the successful recovery of a stable clock. The run-in time (wakeup time and length of preamble) must be longer than the programmed settling time without code timing violations in-between the different phases to ensure correct operation. After successful completion of the wakeup search and the preamble detection, the bit or chip clock is switched to the corresponding port pin, depending on the device configuration. During wakeup search and preamble detection, the clock pin is kept at a constant HIGH. Data reception can be interleaved by SPI commands. Details are given in Section 7.23.2 "Receive command" on page 42.

If bit RX_MANCHESTER is set, the clock rate is set to the bit rate so that every second chip is sampled at the correct time; see Section 8.2.2.8 "Register RXCON" on page 102. This enables the microcontroller to directly decode the Manchester bit stream by sampling the RX data with the negative clock edges.

If the receiver is configured in a transparent mode, the clock pin is directly switched to clock recovery and mapped to the corresponding port pin after the RX command is issued.

7.31 RX digital signal processing

7.31.1 AM demodulator

AM demodulation requires bit DEMOD_ASK in register RXBW to be set; see Section 8.2.1.18 "Channel filter bandwidth and RSSI filter settings register RXBW" on page 92. In this case, the data from ASK demodulator output will be connected to the digital baseband filter input.

7.31.2 FM demodulator

The FM demodulator consists of a discrete delay line and an XOR gate. This principle is used because it features perfect linearity over the full input frequency range. The FM demodulator takes the limited IF I signal and optionally also the Q signal as its input and produces a square-wave type output signal whose time varying average – the low frequency component – is directly proportional to the input frequency. Figure 41 shows a detailed block diagram of the FM demodulator.
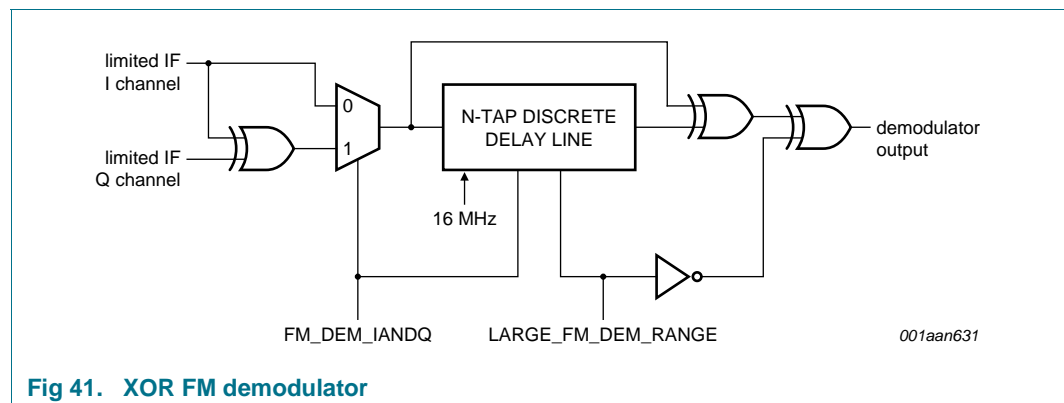
Fig 41. XOR FM demodulator

If bit FM_DEM_IANDQ is set to logic 0, only the limited I channel IF input is used for demodulation. In this case the demodulator is set to a centre frequency of 300 kHz. If bit FM_DEM_IANDQ is set to logic 1, the I and the Q signals, which have a phase difference of 90 °, are combined with an XOR gate. In these circumstances the demodulator is set to a centre frequency of 600 kHz as the I and Q combination effectively doubles the frequency.

If the input frequency is within the specified range, the average value of the second XOR's output is a perfectly linear function of the input frequency.

If bit LARGE_FM_DEM_RANGE is cleared, the input frequency range of the FM demodulator is 200 kHz to 400 kHz. This is the appropriate setting for frequency deviations up to ± 100 kHz. If this bit is set to logic 1, the input frequency range is extended to between 0 Hz and 600 kHz, allowing for process frequency deviations, which are only limited by the analog channel filter. The demodulator output noise increases by the same factor (3) as the frequency range in these circumstances.

Switching to the large input frequency range is achieved by cutting the length of the delay line into one third of its original value. However, this also changes the slope of the output characteristics from positive to negative thereby inverting the demodulator output. The third XOR compensates for this inversion.

Table 16.   FM demodulator configurations
See register EXPERT2 bit descriptions in Table 99 on page 109.

D7	D6	Center frequency (kHz)	Input frequency range (kHz)	Maximum frequency deviation (kHz)	Number of delay elements
0	0	300	200 to 400	±100	40
0	1	300	0 to 600	±300	13
1	0	600	200 to 400	±100	20
1	1	600	0 to 600	±300	7

7.31.3 Baseband filter

The baseband filter serves the following purposes:

- suppresses the high frequency (square-wave) components from the FM demodulator, leaving only the time-varying average, or baseband component of the demodulated signal

- suppresses spectral portions of the quantization noise from the demodulator and the demodulated noise coming from the RF input which do not fall into the baseband signal's bandwidth

- helps achieve a suitable sampling rate for further processing of the baseband signal

The baseband filter is a 3rd-order IIR filter topology that is optimized such that it features a step response with almost no ringing as shown in Figure 43.

7.31.3.1 RX baseband configuration

The filter is split into a 1st-order and a 2nd-order section to minimize the internal quantization noise. Figure 42 shows the baseband filter distributed over two filter blocks.
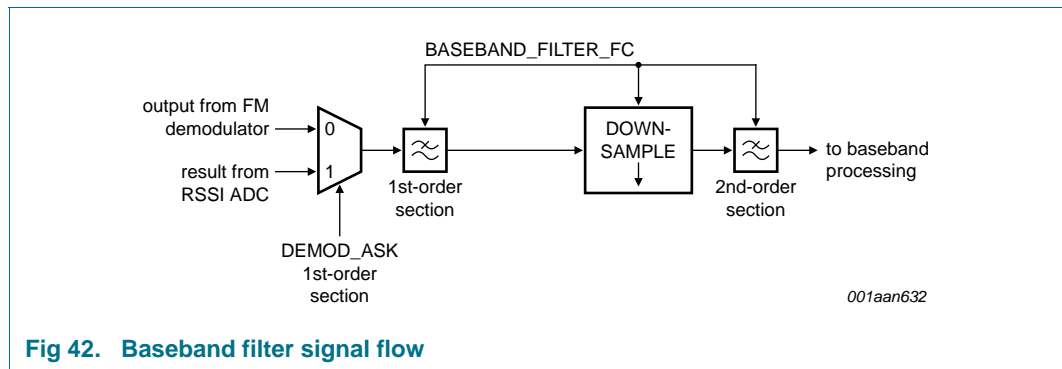
Fig 42.   Baseband filter signal flow

The 1st and 2nd-order sections combine to make the 3rd-order baseband filter for ASK or FSK. The filter cut-off frequency is controlled by register BASEBAND_FILTER_FC control bits; see Section 8.2.1.22 "Register RXBBCON" on page 93. The 1st-order section filters the RSSI information which is sampled with the ADC in the limiter/RSSI analog circuitry. Its cut-off frequency can be controlled separately by register RSSI_FILTER_FC; see Section 8.2.1.18 "Channel filter bandwidth and RSSI filter settings register RXBW" on page 92.

Note that the baseband filter and the RSSI filter are two separate filters.

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Figure 43 and Figure 44 show the step response and the frequency response of the baseband filter, respectively. Figure 43 shows that the step response has an undershoot (negative overshoot) of approximately 3 % and an almost unnoticeable overshoot. This demonstrates a characteristic close to that of an analog Bessel filter. Figure 44 contains one frequency response curve for each of the ten implemented cut-off frequency control values (0 to 9).
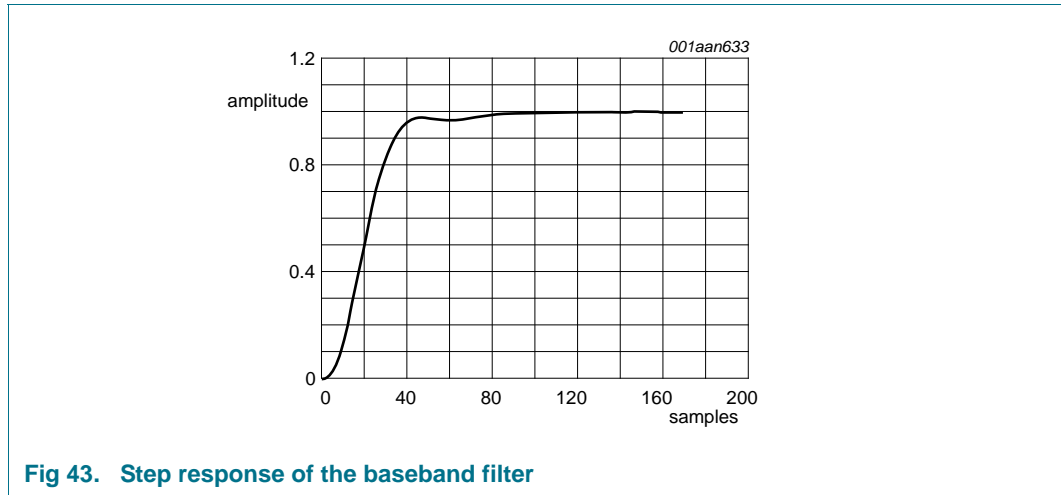
Fig 43. Step response of the baseband filter
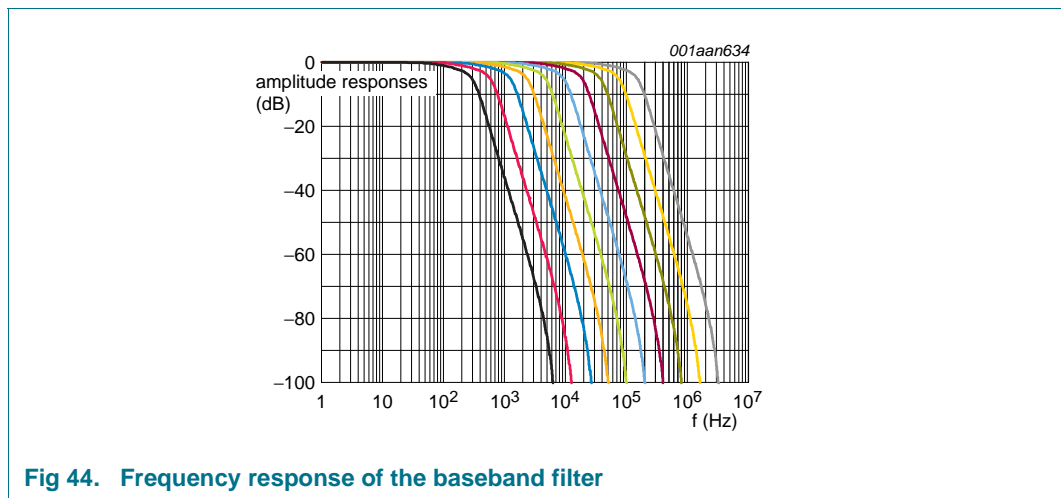
Fig 44. Frequency response of the baseband filter

The accurate output sampling frequency of the data filter can be calculated. The frequency is divided by a factor of 2 when the cut-off frequency control setting is incremented by 1. The relevant formula is:

$$f_c = \frac{114 \text{ kHz}}{2^{\text{FskFilterFc}}}$$

(25)

It can be seen that each increment in the cut-off frequency control setting divides the corner frequency of the filter by approximately a factor of 2.

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Table 17. BASEBAND_FILTER_FC definition

D3	D2	D1	D0	Cut-off frequency (f_c)	Down-sampling factor	Output sampling rate
0	0	0	0	115.45 kHz	2	8 MHz
0	0	0	1	57.174 kHz	4	4 MHz
0	0	1	0	28.405 kHz	8	2 MHz
0	0	1	1	14.204 kHz	16	1 MHz
0	1	0	0	7.0795 kHz	32	500 kHz
0	1	0	1	3.5400 kHz	64	250 kHz
0	1	1	0	1.7701 kHz	128	125 kHz
0	1	1	1	885.12 Hz	256	62.5 kHz
1	0	0	0	442.59 Hz	512	31.25 kHz
1	0	0	1	221.31 Hz	1024	15625 Hz
-	-	-	-	undefined	undefined	undefined

7.32 RX debug interface

If the digital scan test and the channel filter multi-tone test are both not active
(CF_MULTITONE_EN = 0), setting RXD_DBG_SEL[3:0] to a non-zero value switches
ports P10/DATA/TEST4, P11/INT/TEST5 and P12/CLOCK into RX digital debug mode;
see Section 8.2.5.1 "Register TEST0" on page 110. In this mode the normal function of
these pins is overwritten with the function of a fast 3-wire synchronous serial transmission,
where:

- P12/CLOCK outputs the 16 MHz serial clock

- P10/DATA/TEST4 outputs the serial data. This data changes with the 16 MHz clock
  rising edge and it is stable at the clock falling edge. Each data word consists of
  16 bits. Words are transmitted starting with the MSB and ending with the LSB.

- P11/INT/TEST5 outputs a synchronization pulse for each serial 16-bit data word. This
  line goes HIGH during transmission of bit 0, which is the last bit of each word. After
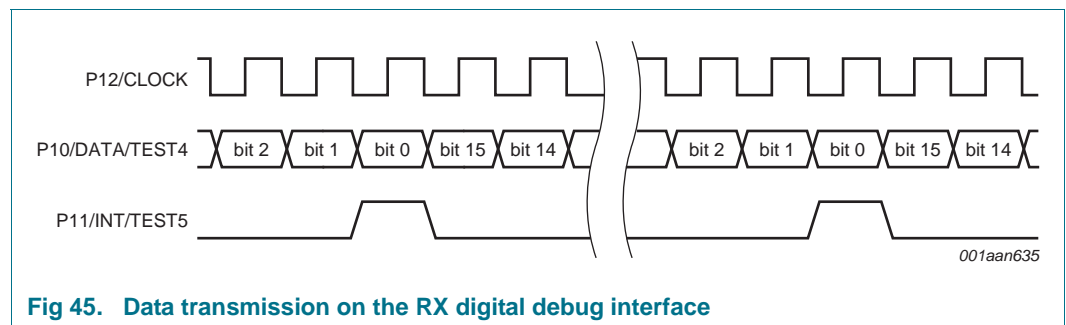 the pulse, transmission continues with the MSB of the next 16-bit word.

Fig 45. Data transmission on the RX digital debug interface

RXD_DBG_SEL[3:0] determines which 16-bit signal vector is sampled in parallel at
1 Msamples/s and output as a serial data stream as shown in Figure 45. The available
debug signal vectors are given in Table 18.

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Table 18.   Available RX debug signal vectors

RXD_DBG_SEL	Bit range	Signal name	Signal description
1	[15:8]	w8RssiLevelOut	digitised RSSI result as it can be retrieved through the status register RSSI_LEVEL
1	[7]	wIFSettledIn	indicates when the 300 kHz IF signal is declared stable
1	[6]	wRssiSettled	indicates when the RSSI result is declared stable
1	[5:0]	r6RawRssiAdcValOut	raw RSSI ADC readings
2	[15:4]	w12FiltdRssi	RSSI signal after the 1st order low-pass filter
2	[3]	rFrontEndGainLoOut	indicates which of the front-end gain settings are applied. 0: RX_HI_GAIN, 1: RX_LO_GAIN
2	[2]	wRssiGtUpperTh	indicates when the RSSI result is greater than the threshold set with UPPERRSSITH
2	[1]	wRssiLtLowerTh	indicates when the RSSI result is less than the threshold set with LOWERRSSITH
2	[0]	wRssiOutsideLimitsOut	indicates when the RSSI is outside the limits defined with both LOWERRSSITH and UPPERRSSITH.
3	[15:4]	w12DataFilter1Res	baseband signal after the 1st-order section of the baseband filter
3	[3]	wLimIfIIn	digital IF input from the I channel limiter
3	[2]	wLimIfQIn	digital IF input from the Q channel limiter
3	[1]	wRawXorFmDemod	raw, unfiltered output from the XOR FM demodulator
3	[0]	wIFSettled	indicates when the 300 kHz IF signal is declared stable
4	[15:1]	w15BasebandSig	filtered and interpolated baseband signal
4	[0]	wBasebandValid	indicates when the baseband signal is declared valid
5	[15:1]	w15SlicerInitThrRegOut	contents of the initial slicer threshold register. This is the same as it is available through registers SLICERINITL and SLICERINITH.
5	[0]	wLoadInitSlicerThr	indicates when the initial threshold register is re-loaded. At chip rates > 7812 chip/s this pulse is shorter than the sampling interval and so pulses may be missed
6	[15:1]	w15SlicerThr	threshold of the level slicer.
6	[0]	wLoadSlicerThr	indicates when the threshold is re-loaded. At chip rates > 7812 chip/s this pulse is shorter than the sampling interval and so pulses may be missed.
7	[15:8]	ws8ClkRcvPllPhaseError	signed clock recovery phase error measurement value in offset binary format.
7	[7:0]	-	always zero (Reserved)
8	[15]	wRxFrame	indicates when data is being received
8	[14]	wRxData	RX data sampled with wRxClock and optionally Manchester decoded
8	[13]	wRxClock	Recovered bit clock
8	[12]	wPatternMatch	raw pattern match indicator from the preamble detection block
8	[11]	wChipClock	raw chip clock from clock recovery PLL
8	[10]	wEdgeDetected	edge detector output from deglitcher, pulses are shorter than the sampling interval for chip rates > 7812 chip/s so some pulses may be missed

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Table 18. **Available RX debug signal vectors** *…continued*

RXD_DBG_SEL	Bit range	Signal name	Signal description
8	[9]	wDeglitchedLevel	output from deglitcher block
8	[8]	wDeglitchedLevelValid	indicates when deglitcher output and edge detector output are valid
8	[7]	wSlicerResult	selected slicer result
8	[6]	wSlicerReady	indicates when selected slicer is ready to deliver a valid signal
8	[5]	wSlicerValid	indicates when selected slicer actually delivers a valid signal
8	[4]	wBasebandValid	indicates when baseband signal is declared valid
8	[3]	wRxRdyOut	indicates when RX hardware is ready and baseband signal is stable, same as bit RX_RDY in register DEVICE_STATUS
8	[2]	wIfSigSettledTo2ndOrderFilt	indicates when IF signal is declared stable, signal principally the same as the next but is longer for processing with slower clock
8	[1]	wIfSigSettled	indicates when IF signal is declared stable
8	[0]	wRxAnaRdy	indicates when analog RX hardware is ready (powered up and calibrated)
9	[15]	wCmdTimeout	indicates when a timeout occurs during a wakeup search or preamble detection
9	[14]	wSigMonFail	logic 1 if enabled signal monitors indicate a fail condition
9	[13]	wSigMonPass	logic 1 if signal monitors indicate a pass condition
9	[12]	wCmdTimeoutEn	indicates when command timeout counter is active
9	[11]	wCTVTimeout	indicates a chip timing verification timeout (no edges for more than (3.5 − REDUCED_CHIP_TIMEOUT) times the chip duration)
9	[10]	wSingleBitTmgError	single chip timing error (interval between two edges exceeds limits defined by SGLBITTMGERRTH[1:0])
9	[9]	wCodeCheckerError	indicates code checker detected an error
9	[8]	wCTVValid	valid signal for chip timing verification block, indicates validity of chip timeout, single chip timing error and code checker
9	[7]	wBaudrateCheckerError	indicates baud-rate checker error
9	[6]	wBaudrateCheckerValid	baud-rate checker result is valid signal
9	[5]	wRssiOutsideLimits	indicates current RSSI result is outside limits defined by registers UPPERRSSITH and LOWERRSSITH
9	[4]	wRssiSettledOut	indicates when RSSI result is declared stable
9	[3]	wSigAmpTooHigh	indicates baseband amplitude (modulation amplitude) is greater than limit defined by register UPPER_MODAMP_TH
9	[2]	wSigAmpTooHighValid	valid indicator for signal wSigAmpTooHigh
9	[1]	wSigAmpTooLow	indicates baseband amplitude (modulation amplitude) smaller than limit defined by register LOWER_MODAMP_TH
9	[0]	wSigAmpTooLowValid	valid indicator for signal wSigAmpTooLowValid
9	-	-	always zero (reserved)

8. Special function registers

8.1 Overview

A map of the Special Function Registers (SFR) is shown in Table 19.

The SFRs are arranged into two banks: bank 0 and bank 1. Bank 0 or bank 1 can be selected by setting bit BANK_SEL in register BANKSEL, visible in both banks, accordingly.

Bytes 0 to 2Dh and 3Fh can always be accessed, independent of the setting of bit BANK_SEL in register BANKSEL (3Fh). Clearing bit BANK_SEL enables bytes 2Eh to 3Eh in bank 0; the contents of bank 1 remain unchanged. Setting register BANKSEL activates bytes 2Eh to 3Eh in bank 1.

Reading from a status register returns the current status of the device. Writing to a status register is ignored by the device. Status bits are identified by [4] in Table 19.

All control registers can be accessed via the SPI interface. If a control register contains less than 8 bits, writing to a non-existent bit has no effect and reading from a non-existent bit always returns a zero. All registers are control registers (Write only) unless otherwise indicated.

Some register bits provide information about the implemented state-machines. These additional status bits can change independently of SPI transmission. These bits are also identified by [4] in Table 19, other bits such as VCO_SUBBAND[5:0] can also change.

The control registers remain stable during power-down. When a Power-on reset occurs, evaluated by reading bit IF_POR in register IFLAG), register bits identified by [1] in Table 19 are preset to their default values.

Bits denoted by RFU are reserved. These bits are Read/Write but do not effect the device.

Table 19. Register map table

Register	Addr	Bank	Bit								Default value [7]
			7 (MSB)	6	5	4	3	2	1	0 (LSB)	
FC0L	00h	01	FC0L[1]				0	0	0	0	0000 0000
FC0M	01h	01	FC0M[1]								0000 0000
FC0H	02h	01	FC0H[1]								1011 0001
FC1L	03h	01	FC1L[2]				0	0	0	0	XXXX XXXX
FC1M	04h	01	FC1M[2]								XXXX XXXX
FC1H	05h	01	FC1H[2]								XXXX XXXX
FC2L	06h	01	FC2L[2]				0	0	0	0	XXXX XXXX
FC2M	07h	01	FC2M[2]								XXXX XXXX
FC2H	08h	01	FC2H[2]								XXXX XXXX
FC3L	09h	01	FC3L[2]				0	0	0	0	XXXX XXXX
FC3M	0Ah	01	FC3M[2]								XXXX XXXX
FC3H	0Bh	01	FC3H[2]								XXXX XXXX
VCOCON	0Ch	01	FORCE_VCO_CAL[3]	VCO_CAL_RUNNING[4]	VCO_SUBBAND[2]						0SXX XXXX
LOCON	0Dh	01	CLK2SCLK_DELAY[1]				SKIP_VCO CAL[1]	LOCK_DET ON[1]	VCO_BAND[1]	RF_LO_DIV [1]	0000 0001
TIMING0	0Eh	01	MAINSCL[1]								0000 0000
TIMING1	0Fh	01	WATCHDOG_TIME[1]		PRESC[1]			MAINSCH[1]			0110 0000
PORTCON0	10h	01	P11C[1]			P11INV[1]	P10C[1]			P10INV[1]	0010 1000
PORTCON1	11h	01	P13C[1]			P13INV[1]	P12C[1]			P12INV[1]	0000 1110
PORTCON2	12h	01	SEP_SDO[1]	SEP_RX_OUT[1]	RFU[1]	RFU[1]	RFU[1]	P14C[1]		P14INV[1]	0000 0000
PWRMODE	13h	01	0	0	0	POLLTIM_EN[1]	DEV_MODE[5]		PD[3]	RESET[3]	000S 0000
IEN	14h	01	IE_RX_RDY[1]	IE_EOF[1]	IE_PREA[1]	IE_WUPS[1]	IE_POLLTIM[1]	IE_WATCHD OG[1]	IE_BROWN OUT[1]	0	0000 0000
IFLAG	15h	01	IF_RX_RDY[1]	IF_EOF[1]	IF_PREA[1]	IF_WUPS[1]	IF_POLLTIM[1]	IF_WATCHD OG[1]	IF_BROWN OUT[1]	IF_POR[1]	0000 0001
POLLWUPTIME	16h	01	POLLWUPTIME[1]								1111 1111
POLLACTION	17h	01	POLL_MODE[1]		RX_FREQ[2]		RX_CMD[2]	RX_GAIN[2]		SET_RX_FLAGS[2]	00XX XXXX
CLOCKCON	18h	01	MANUALPT CAL[3]	PTCAL RUNNING[4]	EXTPOLL TIMRNG[1]	CLKSOURCESEL[1]			EXT_CLK_BUF_EN[1]	XODIS[1]	0S00 0100

Table 19. Register map table …continued

Register	Addr	Bank	Bit								Default value [7]
			7 (MSB)	6	5	4	3	2	1	0 (LSB)	
DEVSTATUS	19h	01	0	PA_ON[4]	PA_PWR_RDY[4]	LO-PWR_RDY[4]	RX_RDY[4]	RFU	LO_RDY[4]	REFCLK_RDY[4]	0SSS SSSS
RXGAIN	21h	01	RX_HI_GAIN[1]				RX_LOW_GAIN[1]				1111 0000
RXBW	22h	01	DEMOD_ASK[2]	CF_BW[1]			RSSI_FILTER_FC[2]				X000 XXXX
GAINSTEP	23h	01	0	RSSI_GAIN_STEP_ADJ[2]							0XXX XXXX
HIGAINLIM	24h	01	HI_GAIN_LIMIT[2]								XXXX XXXX
UPPERRSSITH	25h	01	UPPERRSSITH[2]								XXXX XXXX
LOWERRSSITH	26h	01	LOWERRSSITH[2]								XXXX XXXX
RXBBCON	27h	01	DEGLITCHER_WINDOW_LEN[2]		BASEBAND_SETTL_TIME[2]		BASEBAND_FILTER_FC[2]				XXXX XXXX
UMODAMPTH	28h	01	UPPER_MODAMP_TH_EXP[2]				UPPER_MODAMP_TH_MANT[2]				XXXX XXXX
LMODAMPTH	29h	01	LOWER_MODAMP_TH_EXP[2]				LOWER_MODAMP_TH_MANT[2]				XXXX XXXX
EMODAMPTH	2Ah	01	EDGE_MODAMP_TH_EXP[2]				EDGE_MODAMP_TH_MANT[2]				XXXX XXXX
RXDCON0	2Bh	01	NUM_MODAMP_GAPS_W[2]		SLICERSEL_W[2]		SLICER_INITSEL_W[2]		INIT_ACQ_BITS_W[2]		XXXX XXXX
RXDCON1	2Ch	01	NUM_MODAMP_GAPS_P[2]		SLICERSEL_P[2]		SLICER_INITSEL_PD[2]		INIT_ACQ_BITS_PD[2]		XXXX XXXX
RXDCON2	2Dh	01	NUM_MODAMP_GAPS_D[2]		SLICERSEL_D[2]		CODINGRESTR_W[2]		CODING RESTR_P[2]	CODING RESTR_D[2]	XXXX XXXX
SIGMON0	2Eh	0	WUPS MODE[2]	SIGMON_EN_W[2]						0	XXXX XXX0
SIGMON1	2Fh	0	EN_PREADET_TIMEOUT[2]	SIGMON_EN_P[2]						ACCU_SIG FAILS_P[2]	0XXX XXXX
SIGMON2	30h	0	0	SIGMON_EN_D[2]						ACCU_SIG FAILS_D[2]	XXXX XXXX
WUPSTO	31h	0	WUPSTIMEOUTPRESC[2]			WUPSTIMEOUT[2]					XXXX XXXX
SLICERINITL	32h	0	SLICERINITTHR_LO[2]								XXXX XXXX
SLICERINITH	33h	0	0	SLICERINITTHR_HI[2]							0XXX XXXX
TIMINGCHK	34h	0	RFU[2]	BROBSLENGTH[2]		SUBMITTMGERRTH[2]			SGLBITTMGERRTH[2]		XXXX XXXX
RXCON	35h	0	STATAUTOSAMPLE[2]	AUTO SAMPLE MANUAL[2]	INV_RX_DATA[2]	CLOCK_RECOV_TC[2]		RX_MANCHESTER[2]	RX_CLOCK TRANSP[2]	RX_DATA_TRANSP[2]	XXXX XXXX

Table 19.   Register map table …continued

Register	Addr	Bank	7 (MSB)	6	5	4	3	2	1	0 (LSB)	Default value [7]
RXFOLLOWUP	36h	0	PREA_FU_TF[1]	PREA_FU_CF[1]	WUPS_FU_TS[1]		WUPS_FU_TF[1]	WUPS_FU_CS[1]		WUPS_FU_CF[1]	1000 1000
SIGMONSTATUS	37h	0	SIGMONSTATUS[4]								SSSS SSSS
SIGMONERROR	38h	0	SIGMONERROR[4]								SSSS SSSS
RSSILEVEL	39h	0	RSSI_LEVEL[4]								SSSS SSSS
PREACON	3Ah	0	RFU[2]	PREA_TOL[2]		PREA_LEN[2]					XXXX XXXX
PREA0	3Bh	0	PREA0[2]								XXXX XXXX
PREA1	3Ch	0	PREA1[2]								XXXX XXXX
PREA2	3Dh	0	PREA2[2]								XXXX XXXX
PREA3	3Eh	0	PREA3[2]								XXXX XXXX
EXTRXSTATUS	2Eh	1	RX_HI_GAIN[4]	LIVE_STATUS[4]	RXCMD[4]		MANCHESTER_COUNT[4]				SSSS SSSS
CFRCCAL	2Fh	1	CF_IQ_CAL_RUNNING[4]	CF_RC_CAL_RUNNING[4]	0	0	CF_RC_CAL_RES[4]				SS00 SSSS
CFIQCAL	30h	1	START_CF_IQ_CAL[3]	CF_IQ_CALVAL[1]							0000 0000
EXPERT0	31h	1	RED_VCO_SWING[1]	LARGE_PLL_RST_DELAY[1]	FASTCFFILTSETTL[1]	PLL_ICP[1]					0000 0100
EXPERT1	32h	1	XOSTARTUPDELAY[1]		ASKRSTBBMID[1]	RFU[1]	RFU[1]	DISFRAC[1]	LOCK_DET_TIME[1]		0100 1001
EXPERT2	33h	1	FM_DEM_IANDQ[1]	LARGE_FM_DEM_RANGE[1]	WIDE_AMPL_WINDOW[1]	REDUCED_CHIP_TIME[1]	TWORSSIMSBITSSLOW[1]	FASTRSSIFILTSETTL[1]	CAP_RSSI[1]		0000 0010
EXPERT3	34h	1	0	0	0	0	RFU[1]	ALLOWREGSWITCH[6]	LTDIQPHASECAL[1]	DONOTDISTURBPTCAP[1]	0000 0000
TEST0	35h	1	CF_MULTITONE_EN[6]	DIG_TEST_SEL[6]			RXD_DBG_SEL[6]				0110 0000
TEST1	36h	1	IQ_TEST_LV[6]	ANA_TEST_SEL[6]			REG_DIG_DIS[6]	PLL_CTRL[6]		VCO_TEST_ON[6]	0000 0000

Table 19.   Register map table *…continued*

Register	Addr	Bank	Bit								Default value [7]
			7 (MSB)	6	5	4	3	2	1	0 (LSB)	
TEST2	37h	1	REG_VCO_ON[6]	REG_PLL_ON[6]	REG_PA_ON[6]	FORCE_REG_VCO_RDY[5]	FORCE_REG_PLL_RDY[5]	FORCE_REG_PA_RDY[5]	FORCE_LOCK_DETECTED[5]	FORCE_XO_RDY[1]	0000 0000
TEST3	38h	1	VCO_ON[6]	PRESC_ON[6]	PFD_ON[6]	CLK_PLL_ON[6]	RFU	RX_GAP_ON[6]	RX_ON[6]	PA_STEP_TEST[6]	0000 0000
TEST4	39h	1	FORCE_CF_RC_CAL[3]	SKIP_CF_RC_CAL[6]	CF_RC_ADJUSTCAL[6]		MAN_CF_RC_CALVAL[2]				0000 XXXX
TEST5	3Ah	1	XO_IOFFS[2]			XO_IOFFSSINK_EN[2]	XO_IOFFSEN[6]	XO_KICK_DIS[6]	XO_DET_DIS[6]	XO_BIAS_DIS[6]	XXXX 0000
RFU	3Bh	1	-[1]								0000 0000
TCBEN0	3Ch	1	-[3]								0000 0000
TCBR	3Dh	1	-				IDDQ1[1]	IDDQ0[1]	ASYNCSCAN[1]	SCANEN[1]	0000 0000
TCBEN1	3Eh	1	-[3]								0000 0000
BANKSEL	3Fh	01	0	0	0	0	0	0	0	BANK_SEL[5]	0000 0000

[1]   Bits/field preset at power-on.

[2]   Bits cannot be preset.

[3]   Command bits.

[4]   Status bit (Read only) and indicated by 'S' in the Default value column. Their values are undefined because they depend on the device status after a reset.

[5]   Bits/field reset in power-down mode.

[6]   Test bits.

[7]   'X' denotes the bit is undefined after a device reset; the value is completely random and independent of the device status.

8.2 Register descriptions

The SFRs are arranged into two banks: bank 0 and bank 1. Bank 0 or bank 1 can be selected by setting bit BANK_SEL in register BANKSEL, visible in both banks, accordingly.

8.2.1 Registers visible in both bank 0 and bank 1

8.2.1.1 Frequency control registers

The frequency control registers contain the PLL frequency control information. Four values can be stored to provide four independent frequency settings available for RX purposes. The frequency values have 20 bits. These 20 bits are divided into 4 least significant bits (L) a medium significant byte (M) and a high significant byte (H).

Table 20. Frequency control register FC0L - (address 00h) bit description
Reset value = 00h.

Bit	Symbol	Value	Description
7	FC0L	0	lower 4 bits of 15-bit fractional part of operating frequency value FCx
6		0	
5		0	
4		0	
3	-	0	-
2		0	
1		0	
0		0	

Table 21. Frequency control register FC0M - (address 01h) bit description
Reset value = 00h.

Bit	Symbol	Value	Description
7	FC0M	0	middle 8 bits of 15-bit fractional part of operating frequency value FCx
6		0	
5		0	
4		0	
3		0	
2		0	
1		0	
0		0	

Table 22. Frequency control register FC0H - (address 02h) bit description
Reset value = B1h.

Bit	Symbol	Value	Description
7	FC0H	0	5 integer bits of operating frequency value FCx
6		0	
5		0	
4		0	
3		0	

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Table 22.   Frequency control register FC0H - (address 02h) bit description *…continued*
Reset value = B1h.

Bit	Symbol	Value	Description
2	FCxH	1	high 3 bits of 15-bit fractional part of operating frequency value FCx
1		1	
0		0	

Frequency control register FC1L (address 03h); same bit description as FC0L, but reset value = XXh.

Frequency control register FC1M (address 04h); same bit description as FC0M, but reset value = XXh.

Frequency control register FC1H (address 05h); same bit description as FC0H, but reset value = XXh.

Frequency control register FC2L (address 06h); same bit description as FC0L, but reset value = XXh.

Frequency control register FC2M (address 07h); same bit description as FC0M, but reset value = XXh.

Frequency control register FC2H (address 08h); same bit description as FC0H, but reset value = XXh.

Frequency control register FC3L (address 09h); same bit description as FC0L, but reset value = XXh.

Frequency control register FC3M (address 0Ah); same bit description as FC0M, but reset value = XXh.

Frequency control register FC3H (address 0Bh); same bit description as FC0H, but reset value = XXh.

8.2.1.2   VCO control register VCOCON

Table 23.   VCO control register VCOCON - (address OCh) bit description

Bit	Symbol	Value	Description
7	FORCE_VCO _CAL	0	starts a VCO calibration unconditionally when requested by microcontroller. 1 = calibration starts.
6	VCO_CAL_ RUNNING	S	status bit indicates the VCO calibration is requested or is in progress. 0 = sub-band value, which can be read from this register, is valid and stable.
5	VCO_ SUBBAND	X	resulting sub-band settings from the automatic VCO calibration, value can be overwritten at any time by the microcontroller. If the value is written during an ongoing calibration, the result is undefined. 0 = maximum frequency, and 63h to the minimum frequency.
4		X	
3		X	
2		X	
1		X	
0		X	

8.2.1.3 Local oscillator control register LOCON

Table 24.   Local oscillator control register LOCON - (address ODh) bit description

Bit	Symbol	Value	Description
7	CLK2SCLK_DELAY	0	delay from the 9th SCLK edge in a RX command until the device starts driving the SCLK line. Only applicable if bit SEP_RX_OUT is logic 0 when sending an RX command.
6		0	
5		0	
4		0	
3	SKIP_VCO_CAL	0	automatic VCO calibration performed under the following circumstances: • if the active FCxH, VCO_BAND, RF_LO_DIV, DOUBLE_SD_RESULT, DISFRAC changes • if the device mode switches from/to RX mode • if frequency selection flags A, B change • if the PLL is started from idle mode calibration under the first three conditions can be suppressed by setting this bit. Calibration is always executed on the last condition: PLL start up.
2	LOCK_DET_ON	0	1 = lock detector continuously monitors the PLL during operation. When logic 0, the lock detector only monitors the PLL for a short time after VCO calibration.
1	VCO_BAND	0	must be set to 1 for RF frequency bands below 400 MHz. Must be set to logic 0 for all other bands.
0	RF_LO_DIV	1	0 = VCO frequency is divided by 2 to achieve an RX frequency above 500 MHz. 1 = VCO frequency is divided by 4 to achieve an RX frequency below 500 MHz.

8.2.1.4 Timing register TIMING0

Register TIMING0 (address OEh), MAINSCL[6:0]: main scaler lower byte of baud-rate generator; see Table 25 for description.

8.2.1.5 Timing register TIMING1

Table 25.   Timing register TIMING1 - (address 0Fh) bit description

Bit	Symbol	Value	Description
7	WATCHDOG_TIME	0	programmable watchdog timeout:
6		1	$$\text{watchdog timeout} = \frac{2^{15+\text{WATCHDOG\_TIME}}}{CLK_{ref}}$$
5	PRESC	1	baud-rate prescaler setting
4		0	generator. Baud rate is calculated:
3		0	$$\text{baud rate} = \frac{CLK_{ref}}{2^{PRESC}} \times \frac{2^{11} + MAINSC}{2^{12}} \times \frac{1}{128} \text{ where}$$ CLK_{REF} = 16 MHz, PRESC is an exponent in the range 0 to 7 and 2^{11} + MAINSC is the mantissa in the range 2048 to 4095. The resulting baud-rate clock can jitter by one prescaler clock cycle CLK_{PSC}.

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Table 25. Timing register TIMING1 - (address 0Fh) bit description *…continued*

Bit	Symbol	Value	Description
2	MAINSCH	0	3 highest bits of baud-rate generator's main scaler
1		0	
0		0	

8.2.1.6 Port control registers PORTCON0 to PORTCON2

Registers PORTCON0 to PORTCON2 define the function of Port pins P10, P11, P12, P13 and P14. Test functions can be enabled in combination with register TEST0. Register PORTCON2 defines the general SPI mode.

8.2.1.7 Port control register PORTCON0

Table 26. Port control register PORTCON0 - (address 10h) bit description

Bit	Symbol	Value	Description
7	P11C	0	configures P11/INT; see Table 28
6		0	
5		1	
4		0	
3	P11INV	1	inverts the pin polarity
2	P10C	0	configures P10/DATA; see Table 27
1		0	
0	P10INV	0	logic 1 inverts the pin polarity

Table 27. P10C port control data functions

D2	D1	Function
0	0	3-state
0	1	constant LOW
1	0	PRNG output
1	1	reserved

Table 28. P11C port control data functions

D7	D6	D5	D4	Function
0	0	0	0	3-state
0	0	0	1	always zero
0	0	1	0	interrupt request
0	0	1	1	clock output from clock generation according to CLKSOURCESEL[2:0] settings
0	1	0	0	CF_IQ_CAL_RUNNING
0	1	0	1	LO_RDY flag
0	1	1	0	RX_RDY flag
0	1	1	1	reserved
1	0	0	0	reserved
1	0	0	1	reserved

Table 28.   P11C port control data functions *…continued*

D7	D6	D5	D4	Function
1	0	1	0	reserved signal; always 0
1	0	1	1	
1	1	0	0	
1	1	0	1	
1	1	1	0	test signals controlled by DIG_TEST_SEL[2:0]; see Table 29 and Table 30
1	1	1	1	

The test signals shown in Table 29 are available if register PORTCON0 bits D7 = 1, D6 = 1, D5 = 1, D4 = 0 and if DIG_TEST_SEL[2:0] in register TEST0 (address 35h), are set according to this table.

Table 29.   Test signal I

D6	D5	D4	Function
0	0	0	digital regulator enable
0	0	1	VCO regulator enable
0	1	0	PLL regulator enable
0	1	1	reserved
1	0	0	XO enable
1	0	1	
1	1	0	
1	1	1	XO startup signal kick A

The test signals shown in Table 30 are available if register PORTCON0 bits D7 = 1, D6 = 1, D5 = 1, D4 = 1 and if DIG_TEST_SET[2:0] in register TEST0 (address 35h), are set according to this table.

Table 30.   Test signal II

D6	D5	D4	Function
0	0	0	I signal from limiter
0	0	1	channel filter RC calibration enable
0	1	0	polling timer enable
0	1	1	RSSI DAC value LSB
1	0	0	PLL lock detector enable
1	0	1	
1	1	0	reserved
1	1	1	

8.2.1.8 Port control register PORTCON1

Table 31.   Port control register PORTCON1 - (address 11h) bit description

Bit	Symbol	Value	Description
7	P13C	0	configures P13/SDO
6		0	
5		0	
4	P13INV	0	1= inverts the pin polarity

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Table 31. Port control register PORTCON1 - (address 11h) bit description …continued

Bit	Symbol	Value	Description
3	P12C	0	configures P12/CLOCK; see Table 32
2		1	
1		1	
0	P12INV	0	1 = inverts the pin polarity

Table 32. P12C port control data functions

D3	D2	D1	Function
0	0	0	3-state
0	0	1	always zero
0	1	0	RX clock output; if bit SEP_RX_OUT = 1 and RX is activated.
0	1	1	clock generated output according to CLKSOURCESEL[2:0]
1	0	0	PLL feedback clock
1	0	1	uncalibrated polling timer clock
1	1	0	test signals controlled by DIG_TEST_SEL[2:0]; see Table 33 and Table 34
1	1	1	

The test signals shown in Table 33 are available if register PORTCON1 bits D3 = 1, D2 = 1, D1 = 0 and if DIG_TEST_SET[2:0] in register TEST0 (address 35h), are set according to this table.

Table 33. Test signal III

D6	D5	D4	Function
0	0	0	digital regulator brown-out detection
0	0	1	VCO regulator brown-out detection
0	1	0	PLL regulator brown-out detection
0	1	1	reserved
1	0	0	XO_RDY
1	0	1	XO startup signal kick A
1	1	0	XO startup signal kick C
1	1	1	

The test signals shown in Table 34 are available if register PORTCON1 bits D3 = 1, D2 = 1, D1 = 1 and if DIG_TEST_SET[2:0] in register TEST0 (address 35h), are set according to this table.

Table 34. Test signal IIII

D6	D5	D4	Function
0	0	0	Q signal from limiter
0	0	1	CF_RC_CAL_RUNNING flag
0	1	0	uncalibrated polling timer clock
0	1	1	RSSI ADC comparator output
1	0	0	PLL lock detector signal (raw)

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Table 34. Test signal IIII *…continued*

D6	D5	D4	Function
1	0	1	PLL lock detector signal (digitally filtered)
1	1	0	continuous 1 MHz clock
1	1	1	constant LOW (reserved)

Table 35. P13C port control data functions

D3	D2	D1	Function
0	0	0	3-state
0	0	1	always zero
0	1	0	reserved
0	1	1	RX_RDY
1	0	0	REFCLK_RDY
1	0	1	LO_RDY
1	1	0	RX_RDY
1	1	1	reserved

8.2.1.9 Port control register PORTCON2

Table 36. Port control register PORTCON2 - (address 12h) bit description

Bit	Symbol	Value	Description
7	SEP_SDO	0	1 = P13 is 3-state or SPI data output and has priority over the normal function of P13 [1]
6	SEP_RX_OUT	0	if set to 1 and a RX command is active, P10 is always (independent of P10C settings) used as RX data and P12 conditionally used as RX clock output, depending on P12C configuration, see Table 37 [1]
5	RFU	0	reserved
4	RFU	0	reserved
3	RFU	0	reserved
2	P14C	0	configures P14/PIND; see Table 38
1		0	
0	P14INV	0	1 = inverts the pin polarity

[1] SEP_xxx bits override all other P13 port settings. P10C configured functions are overridden if bit SEP_RX_OUT = 1 and RX is activated.

Table 37. SEP_RX_OUT data functions

SEP_RX_OUT	RX data output	RX clock output
0	SDIO or SDO, depending on SEP_SDO	SCLK
1	P10/DATA	P12/CLOCK (optional, only if P12C = 010b)

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Table 38.   P14C port control data functions

D2	D1	Function
0	0	3-state
0	1	constant LOW
1	0	0 = RX_MODE or 3-state
1	1	0 = RX_MODE or 3-state

8.2.1.10   General power mode register PWRMODE

Table 39.   General power mode register PWRMODE - (address 13h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6		0	
5		0	
4	POLLTIM_EN	S	polling timer enable bit. Initialization occurs on every (power-on) reset. Bit POLLTIM_EN is set to the inverse of pin RSTDIS. Therefore this pin controls polling timer initial condition. 1 = polling initially disabled; see Table 40 and Table 41
3	DEV_MODE	0	device mode control bits; see Table 42
2		0	
1	PD	1	power-down bit: logic 1 puts device into standby mode where it consumes much less power. All analog RX circuitry and the XTAL oscillator are turned off. All dynamic digital activity is stopped except SPI and polling timer, if enabled.[1]
0	RESET	0	reset bit: logic 1puts the device into power-on state, the same state reached after powering up the device. If set logic 1 with a Write command, all other bits, simultaneously written to register PWRMODE, are ignored as the register is forced to the power-on state.

[1]   Bit PD can also be set automatically at Power-on reset or setting bit RESET, watchdog timer timeout, or receive state machine request. A logic 1 cannot be read because the SPI Read command causes the OL2311 to exit Power-down mode.

Table 40.   POLLTIM_EN data functions

D4	Function
0	polling timer off and no current is drawn
1	polling timer on

Table 41.   Polling timer status after master reset

Pin RSTDIS	Status after master reset
LOW	POLLTIM_EN = 1: polling timer is activated with the settings of register POLLWUPTIME = 255 and EXTPOLLTIMRNG = 0.
HIGH	POLLTIM_EN = 0: polling timer off

Table 42.   DEV_MODE[1:0] device mode control functions

D3	D2	Function
0	0	crystal oscillator or external clock buffer is enabled and after crystal oscillator stabilization (if selected) the device is supplied with the reference clock
0	1	PLL controlled local oscillator (LO) enabled. LO power-up procedure includes VCO sub-band calibration (unconditionally) and PLL lock-in detection
1	0	prepare and enable RX operation. LO enabled and after PLL acquires lock, RX is switched on and enabled
1	1	reserved

8.2.1.11   Interrupt enable register IEN

Table 43.   Interrupt enable register IEN - (address 14h) bit description

Bit	Symbol	Value	Description
7	IE_RX_RDY	0	triggered if RX mode is successfully reached after automatic start-up sequences issued [1]
6	IE_EOF	0	EOF is generated in data reception mode if an enabled signal monitor detects an unsatisfactory RX signal condition. This is the case when data reception mode is reached either automatically after a successful preamble detection or upon receipt of a DATA RX command.
5	IE_PREA	0	triggered on every completion of a preamble detection regardless of whether it was successful or not
4	IE_WUPS	0	triggered on every completion of a wakeup search regardless of whether it was successful or not
3	IE_POLTIM	0	triggered when a polling timer event takes place
2	IE_WATCHDOG	0	triggered when a watchdog overflow takes place
1	IE_BROWNOUT	0	triggered on brown-out detection of the voltage regulators (undervoltage detection)
0	0	0	0

[1]   Issuing another RX command will not trigger this interrupt when the device is already in RX mode, respectively. An interrupt is only generated when the ready state is reached.

8.2.1.12   Interrupt flag register IFLAG

The IFLAG bits indicate if an interrupt source is triggered since this register was last read. The register bits are always set to logic 0 after being read.

Table 44.   Interrupt flag register IFLAG - (address 15h) bit description

Bit	Symbol	Value	Description
7	IF_RX_RDY	0	set after completion of automatic start-up sequences
6	IF_EOF	0	
5	IF_PREA	0	successful preamble detection (non-maskable)
4	IF_WUPS	0	successful wakeup search (non-maskable)
3	IF_POLLTIM	0	polling timer event (non-maskable)

Table 44.   Interrupt flag register IFLAG - (address 15h) bit description *…continued*

Bit	Symbol	Value	Description
2	IF_WATCHDOG	0	watchdog overflow
1	IF_BROWNOUT	0	undervoltage detection
0	IF_POR	1	first battery power-on reset (battery insertion detection). Setting bit RESET also sets the IF_POR flag.

8.2.1.13 Polling timer control register POLLWUPTIME

Table 45.   Polling timer control register POLLWUPTIME - (address 16h) bit description

Bit	Symbol	Value	Description
7	POLLWUPTIME	1	sets polling timer wakeup time. Wakeup time is calculated by:
6		1	
5		1	$$T_{WUP} = (POLLWUPTIME + 1)T_{WUPTICK}$$
4		1	where $T_{WUPTICK}$ is either 1 ms or 16 ms depending on bit EXTPOLLTIMRNG (extended polling timer range).
3		1	
2		1	
1		1	
0		1	

8.2.1.14 Polling action register POLLACTION

Table 46.   Polling action register POLLACTION - (address 17h) bit description

Bit	Symbol	Value	Description
7	POLL_MODE	0	defines the operating mode the device enters after a polling timer event, see Table 47
6		0	
5	RX_FREQ	X	RX_FREQ[1:0] means the same as RX flags RA and RB (frequency selection)
4		X	
3	RX_CMD	X	bit RX_CMD means the same as RX flag RC. It allows a choice between a WUPS (logic 0) and a PRDA (logic 1) command.
2	RX_GAIN	X	RX_GAIN[1:0] means the same as RX flags RE and RF (gain step/switch selection bits)
1		X	
0	SET_RX_FLAGS	X	defines whether the current contents of RX flag register is used for the automatically initiated RX command (if logic 0) or whether RX flags RA, RB, RC, RE and RF are overwritten with the contents of RX_FREQ[1:0], RX_CMD and RX_GAIN[1:0] settings of this register, respectively, before the command is actually launched (if logic 1). If the flags are overwritten, the RX flag RD is set to logic 1 to make the sub-command either a WUPS or a PRDA command.

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Table 47.   POLL_MODE[1:0] device mode control functions

D7	D6	Function
0	0	after signalling the polling timer interrupt, which is unmaskable, the device remains in Power-down mode
0	1	after signalling the polling timer interrupt, which is unmaskable, the device leaves Power-down mode, which turns the crystal oscillator or the external clock buffer on
1	0	device is fully powered up to RX mode. If the polling timer interrupt is enabled, an interrupt occurs, either with the polling timer event or when the receiver is ready
1	1	device is fully powered up to RX mode. After RX settles, an RX command is automatically initiated as configured by the remaining bits of this register. It is guaranteed that at least one interrupt will occur in the command sequence.

8.2.1.15   Clock connection register CLOCKCON

Table 48.   Clock connection register CLOCKCON - (address 18h) bit description

Bit	Symbol	Value	Description
7	MANUALPTCAL	0	manual start of polling timer calibration. Reading bit MANUALPTCAL always yields zero. Manual calibration is only executed if polling timer and crystal oscillator are running. Otherwise the request is ignored.
6	PTCALRUNNING	S	status bit set when polling timer calibration is running
5	EXTPOLLTIMRNG	0	extended polling timer range calculated by: $T_{WUPTICK} = 1 + 15 \times EXTPOLLTIMRNG$ ms; see Table 49
4	CLKSOURCESEL	0	clock selection for selected port pin; see Table 50
3		0	
2		1	
1	EXT_CLK_BUF_EN	0	external clock buffer enable bit is used to turn on clock buffer for external clock. The effect of this bit also depends on bit XODIS; see Table 51
0	XODIS	0	

Table 49.   EXTPOLLTIMRNG bit functions

EXTPOLLTIMRNG	Wakeup counter resolution $T_{WUPTICK}$	Selectable wakeup times T_{WUP}
0	1 ms	1 ms to 256 ms
1	16 ms	16 ms to 4096 ms

Table 50.   CLKSOURCESEL bit functions

D4	D3	D2	Port pin
0	0	0	reference clock (16 MHz)
0	0	1	reference clock / 2 (8 MHz)
0	1	0	reference clock / 4 (4 MHz)
0	1	1	reference clock / 8 (2 MHz)
1	0	0	4 × chip clock

Table 50. CLKSOURCESEL bit functions *…continued*

D4	D3	D2	Port pin
1	0	1	2 × chip clock
1	1	0	chip clock
1	1	1	bit clock

Table 51. EXT_CLK_BUF_EN / XODIS bit functions

D1	D0	Function
0	0	crystal oscillator enabled. Digital reference clock disabled during oscillator start-up.
0	1	crystal oscillator and external clock buffer disabled
1	0	crystal oscillator enabled. Digital reference clock permanently enabled and during oscillator start-up.
1	1	crystal oscillator disabled and external clock buffer enabled. Digital reference clock permanently enabled.

8.2.1.16 Device status register DEVSTATUS

Table 52. Device status register DEVSTATUS - (address 19h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	RFU	0	reserved
5	RFU	0	reserved
4	LO_PWR_RDY	0	logic 1 indicates VCO and PLL regulators are delivering power to these LO sections
3	RX_RDY	S	status bit: automated RX mode preparation sequence ready, device ready for RX
2	RFU	S	reserved
1	LO_RDY	S	status bit: VCO running, PLL settled and locked
0	REFCLK_RDY	S	status bit: XTAL oscillator stable or external clock available. External clock stability is not checked by the device.

Table 53. Register RFU - (address 20h) bit description

Bit	Symbol	Value	Description
7	DOUBLE_SD_RESULT	0	configures the Sigma delta fractional-N modulation; see Section 7.14.7 "Delta-sigma modulator for fractional-N synthesis" on page 29 for details
6	RFU	0	reserved
5	RFU	0	reserved
4	RFU	0	reserved
3	RFU	0	reserved
2	RFU	0	reserved
1	RFU	0	reserved
0	RFU	0	reserved

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Table 54.   RX frequency offset

RF_LO_DIV	DOUBLE_SD_RESULT	Offset value	Frequency resolution (Hz)	RX frequency offset
0	0	614	488.3	299.805 kHz
0	1	307	976.6	
1	0	1228	244.1	
1	1	614	488.3	

8.2.1.17   Receiver gain control register RXGAIN

Gain configuration of the receiver for Hi gain and LO gain mode. If automatic gain switching is activated, the receiver configuration will be automatically changed from HI to LO gain when a certain signal level is exceeded.

Table 55.   Receiver gain control register RXGAIN - (address 21h) bit description

Bit	Symbol	Value	Description
7	RX_HI_GAIN	1	sets the desired gain for high gain mode including both RF front-end gain and channel filter gain settings
6		1	
5		1	
4		1	
3	RX_LO_GAIN	0	sets the desired gain for low gain mode including both RF front-end gain and channel filter gain settings
2		0	
1		0	
0		0	

8.2.1.18   Channel filter bandwidth and RSSI filter settings register RXBW

Table 56.   Channel filter bandwidth and RSSI filter settings register RXBW - (address 22h) bit description

Bit	Symbol	Value	Description
7	DEMOD_ASK	X	switches the digital baseband filter input and baseband signal processing chain to the ASK demodulator output
6	CF_BW	0	channel filter bandwidth selection bits, see Table 57
5		0	
4		0	
3	RSSI_FILTER_FC	X	RSSI corner frequency selection bits
2		X	
1		X	
0		X	

Table 57.   CF_BW bit functions

D6	D5	D4	Bandwidth (kHz)
0	0	0	300
0	0	1	200
0	1	0	150

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Table 57. **CF_BW bit functions** *…continued*

D6	D5	D4	Bandwidth (kHz)
0	1	1	100
1	0	0	75
1	0	1	50

8.2.1.19 Register GAINSTEP

Table 58. **Register GAINSTEP - (address 23h) bit description**

Bit	Symbol	Value	Description
7	0	0	-
6	RSSI_GAIN_STEP_ADJ	X	the receiver automatically adds this value to the filtered and properly scaled RSSI reading whenever it is in low gain mode to compensate for the difference (high gain minus low gain). This seamlessly extends the RSSI's dynamic range by switching the RX chain gain.
5		X	
4		X	
3		X	
2		X	
1		X	
0		X	

8.2.1.20 Register HIGAINLIM

Table 59. **Register HIGAINLIM - (address 24h) bit description**

Bit	Symbol	Value	Description
7	HI_GAIN_LIMIT	0	8-bit gain switching threshold value [1]
6		0	
5		0	
4		0	
3		X	
2		X	
1		X	
0		X	

[1] If the RSSI reading exceeds this value during a wakeup search, the RX gain can be switched from RX_HI_GAIN to RX_LO_GAIN automatically provided it is programmed to do so (flags E, F = 01b).

8.2.1.21 Registers UPPERRSSITH and LOWERRSSITH

Registers UPPERRSSITH (address 25h) and LOWERRSSITH (address 26h) contain the 8-bit upper and lower RSSI threshold level respectively. This value is compared against the digitised RSSI value in the RSSI level classification unit.

8.2.1.22 Register RXBBCON

Table 60. **Register RXBBCON - (address 27h) bit description**

Bit	Symbol	Value	Description
7	DEGLITCHER_WINDOW_LEN	X	control the deglitcher's hold-off time to suppress multiple signal transitions when a noisy baseband signal crosses the slicer threshold, see Table 62
6		X	

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Table 60.   Register RXBBCON - (address 27h) bit description …continued

Bit	Symbol	Value	Description
5	BASEBAND_ SETTL_TIME	X	adjusts the baseband settling delay. Delay is the time between the declared valid IF signal and the declared valid baseband signal. The delay is $2 \times (1 + \text{BASEBAND\_SETTL\_TIME}) \times$ chip duration. Correct adjustment of this delay is essential if operating a wakeup search in pessimistic mode, because signal measurement and classification must not be started until the whole RX chain (including the channel and baseband filters) are settled. The dominant settling time is usually the baseband filter and must be taken into account
4		X	
3	BASEBAND_ FILTER_FC	X	baseband digital filter cut-off frequency
2		X	
1		X	
0		X	

Table 61.   DEGLITCHER_WINDOW_LEN bit functions

D7	D6	Deglitcher lock duration
0	0	0
0	1	2 / 16 of chip width
1	0	3 / 16 of chip width
1	1	4 / 16 of chip width

8.2.1.23   Register UMODAMPTH

Table 62.   Register UMODAMPTH - (address 28h) bit description

Bit	Symbol	Value	Description
7	UPPER_MODAMP_ TH_EXP	X	$\text{UPPER\_MODAMP\_TH\_EXP} = max\left\{ 0, \left\lfloor log2\left(\dfrac{UMODAMPTH}{7.75}\right) \right\rfloor \right\}$
6		X	
5		X	
4		X	
3	UPPER_MODAMP_ TH_MANT	X	$\text{UPPER\_MODAMP\_TH\_MANT} = 0.5 + \dfrac{UMODAMPTH}{2^{\text{UPPER\_MODAMP\_TH\_EXP}}}$
2		X	
1		X	
0		X	

Register UMODAMPTH contains the upper modulation amplitude measurement threshold level (modulation amplitude classification unit). In FSK mode one increment corresponds to approximately 6.2 Hz when bit LARGE_FM_DEM_RANGE is logic 0 and approximately 18.6 Hz when bit LARGE_FM_DEM_RANGE is logic 1. In ASK mode one increment corresponds to approximately 1.5 dB/512 = 0.00293 dB.

In FSK mode: $\text{UMODAMPTH} = F_{DEV} \times \dfrac{1 + \dfrac{T}{100}}{200 \text{ kHz} \times (1 + 2 \times \text{LARGE\_FM\_DEM\_RANGE})} \times 32256$

where F_{DEV} = nominal peak-to-peak frequency deviation (Hz), T = tolerance (%).

In ASK mode: $UMODAMPTH = ASK_{MOD} \times \dfrac{1 + \dfrac{T}{100}}{1.5} \times 512$ where ASK_{MOD} = ASK

modulation amplitude ratio (dB), T = tolerance (%).

Remark: The specified amplitude is peak-to-peak.

8.2.1.24 Register LMODAMPTH

Register LMODAMPTH (address 29h) contains the lower modulation amplitude measurement threshold level (modulation amplitude classification unit). It configures the threshold level similar to register UMODAMPTH.

In FSK mode: $LMODAMPTH = F_{DEV} \times \dfrac{1 + \dfrac{T}{100}}{200 \text{ kHz} \times (1 + 2 \times \text{LARGE\_FM\_DEM\_RANGE})} \times 32256$

where F_{DEV} = nominal peak-to-peak frequency deviation (Hz), T = tolerance (%).

In ASK mode: $LMODAMPTH = ASK_{MOD} \times \dfrac{1 + \dfrac{T}{100}}{1.5} \times 512$ where ASK_{MOD} = ASK

modulation amplitude ratio (dB), T = tolerance (%).

Remark: The specified amplitude is peak-to-peak.

8.2.1.25 Register EMODAMPTH

Table 63. Register EMODAMPTH - (address 2Ah) bit description

Bit	Symbol	Value	Description
7	EDGE_MODAMP_TH	0	expected peak modulation value; calculation of EDGE_MODAMP_TH; see register UMODAMPTH
6		0	
5		0	
4		0	
3		0	
2		0	
1		0	
0		0	

The EMODAMPTH register contains the expected peak modulation value used as the amplitude reference value for the edge slicer. It configures the threshold level similar to register UMODAMPTH.

In FSK mode: $EMODAMPTH = F_{DEV} \times \dfrac{F_{DEV}}{200 \text{ kHz} \times (1 + 2 \times \text{LARGE\_FM\_DEM\_RANGE})} \times 32256$

where F_{DEV} = nominal peak-to-peak frequency deviation (Hz).

In ASK mode: $EMODAMPTH = \dfrac{ASK_{MOD}}{3} \times 512$ where ASK_{MOD} = ASK modulation

amplitude ratio (dB).

Remark: The specified amplitude is peak.

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8.2.1.26 Register RXDCON0

Table 64. **Register RXDCON0- (address 2Bh)**

Register	Nomenclature
RXDCON0	wakeup search settings
RXDCON1	preamble detection settings
RXDCON2	data reception settings

Table 65. **Register RXDCON0 - (address 2Bh) bit description**

Bit	Symbol	Value	Description
7	NUM_MODAMP_GAPS_W	X	the maximum expected duration, expressed as a number of chip widths,
6		X	between any two transitions minus 1, for example, if data stream '0000' were Manchester encoded, the data stream at chip level appears as '01010101', a transition occurring every single chip width, therefore the value is logic 0.
5	SLICERSEL_W	X	data slicer selection for wakeup search phase, see Table 66
4		X	
3	SLICERINIT_SEL_W	X	initial initialization mode selection for selected slicer type for wakeup search phase
2		X	
1	INIT_ACQ_BITS_W	X	2, 4 or 8-bit averaging on initial acquisition during wakeup search. The initial acquisition updates slicer initialisation register and slicer threshold after every calculation of 2, 4, and 8 bits; see Table 68
0		X	

Table 66. **SLICERSEL_W bit functions**

D5	D4	Function
0	0	edge slicer selected
0	1	level-sensitive slicer selected. The low-pass filter is not activated, which means that the current slicer threshold is held constant. Slicer threshold initialisation is accomplished according to the setting of SLICERINITSEL_W[1:0]
1	0	level-sensitive slicer is selected and low-pass filter with a time-constant of 2 bits (4 chips) is activated continuously. Slicer threshold initialisation is accomplished according to the setting of SLICERINITSEL_W[1:0].
1	1	level-sensitive slicer is selected and low-pass filter with a time-constant of 8 bits (16 chips) is activated continuously. Slicer threshold initialisation is accomplished according to the setting of SLICERINITSEL_W[1:0].

Table 67. **SLICERINITSEL_W bit functions**

D3	D2	Function
0	0	slicer threshold is never initialized

Table 67.   SLICERINITSEL_W bit functions *…continued*

D3	D2	Function
0	1	slicer threshold is initialized with the content of register SLICERINITH at the start of a RX event.
1	0	initial acquisition is achieved at the start of a RX event. Slicer threshold is updated each time a new result is available from the initial acquisition.
1	1	same as setting 10 but the initial acquisition is automatically restarted when a chip duration timeout occurs

Table 68.   INIT_ACQ_BITS_x bit functions

D1	D0	Number of bits used to calculate slicer threshold
0	0	0
0	1	2
1	0	4
1	1	8

8.2.1.27   Register RXDCON1

Table 69.   Dynamic RX mode control register RXDCON1 - (address 2Ch) bit description

Bit	Symbol	Value	Description[1]
7	NUM_MODAMP_ GAPS_P	X	number of expected modulation gaps during preamble detection
6		X	
5	SLICERSEL_P	X	data slicer selection for preamble detection phase
4		X	
3	SLICERINIT_ SEL_PD	X	initial initialization mode selection for selected slicer type for preamble detection and data reception
2		X	
1	INIT_ACQ_BITS_PD	X	2, 4 or 8-bit averaging on initial acquisition during preamble detection and data reception. Initial acquisition updates the slicer initialisation register and slicer threshold after every calculation of 2, 4, and 8 bits.
0		X	

[1]   See Table 64 for detailed explanation of control bits.

8.2.1.28   Register RXDCON2

Table 70.   Dynamic RX mode control register RXDCON2 - (address 2Dh) bit description

Bit	Symbol	Value	Description
7	NUM_MODAMP_ GAPS_D	X	number of expected modulation gaps during data reception
6		X	
5	SLICERSEL_D	X	data slicer selection for data reception phase
4		X	

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Table 70.   Dynamic RX mode control register RXDCON2 - (address 2Dh) bit description

Bit	Symbol	Value	Description
3	CODINGRESTR_W	X	wakeup search, coding verification unit. Selection of the permitted signal encoding, see Table 71
2		X	
1	CODINGRESTR_P	X	coding restriction for preamble detection. If logic 0, no restriction, both time intervals (1 × chip and 2 × chip width) are accepted in an arbitrary order. If logic 1, both time intervals are accepted and the sequence is checked for Manchester coding.
0	CODINGRESTR_D	X	coding restriction selection for data reception. If logic 0, no restriction, both time intervals (1 × chip and 2 × chip width) are accepted in an arbitrary order. If logic 1, both time intervals are accepted and the sequence is checked for Manchester coding.

[1]   See Table 64 for detailed explanation of control bits.

Table 71.   CODINGRESTR_W bit function

D3	D2	Function
0	0	no restriction, both time intervals (1 × chip and 2 × chip width) are accepted in an arbitrary order
0	1	only short time interval (1 × chip width) is accepted
1	0	only long time interval (2 × chip width) is accepted
1	1	both time intervals are accepted and the sequence is checked for Manchester coding

8.2.2 Registers only visible in bank 0

8.2.2.1 Signal monitoring register SIGMON0

Table 72.   Signal monitoring registers SIGMON0, SIGMON1 and SIGMON2

Register	Nomenclature
SIGMON0	wakeup search settings
SIGMON1	preamble detection settings
SIGMON2	data reception settings

Table 73.   Signal monitoring control register SIGMON0 - (address 2Eh) bit description

Bit	Symbol	Value	Description
7	WUPSMODE	X	wakeup search mode selection bit, see Table 74
6	SIGMON_EN_W	X	selection of signal monitor (signal signature recognition unit) to be activated during wakeup search, see Table 75
5		X	
4		X	
3		X	
2		X	
1		X	
0	0	0	-

Table 74.   WUPSMODE bit functions

D7	Function
0	'pessimistic' wakeup search (also called mode 1): wakeup search ends when either one of the enabled signal monitors signals a FAIL or all enabled signal monitors signal PASS. In the first case the result of the wakeup search is FAIL; in the latter case it is PASS
1	'optimistic' wakeup search (also called mode 2): wakeup search ends when either all enabled signal monitors signal a PASS or the wakeup search timer expires. In the first case the result of the wakeup search is PASS; in the latter case it is FAIL.

Table 75.   SIGMON_EN_W bit functions

Bit	Symbol	Value	Description (if set)
6	SIGMON_EN_W	X	enable chip timeout
5		X	enable chip timing
4		X	enable coding check
3		X	enable baud-rate check
2		X	enable RSSI level check
1		X	enable modulation amplitude detection

8.2.2.2   Signal monitoring control register SIGMON1

Table 76.   Signal monitoring control register SIGMON1 - (address 2Fh) bit description

Bit	Symbol	Value	Description
7	EN_PREADET_TIMEOUT	X	if logic 1, wakeup search timeout (WUPSTO) is also applied to the preamble detection
6	SIGMON_EN_P	X	selection of signal monitor (signal signature recognition unit) to be active during preamble detection, see Table 75
5		X	
4		X	
3		X	
2		X	
1		X	
0	ACCU_SIG_FAILS_P	X	logic 1 causes error indicators to be accumulated over the duration of preamble detection. Accumulator is reset at the start of preamble detection and when the microcontroller samples the status.

8.2.2.3 Signal monitoring control register SIGMON2

Table 77.   Signal monitoring control register SIGMON2 - (address 30h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	SIGMON_EN_D	X	selection of signal monitor (signal signature recognition unit) to be active during data reception, see Table 75. If an enabled signal monitor detects an abnormal condition, it is indicated by the IF_EOF (End-of-Frame flag).
5		X	
4		X	
3		X	
2		X	
1		X	
0	ACCU_SIG_FAILS_D	X	logic 1 causes the error indicators to be accumulated over the duration of data reception. The accumulator is reset at the start of data reception and when the microcontroller samples the status.

8.2.2.4 Register WUPSTO

Table 78.   Wakeup search timeout control register WUPSTO - (address 31h) bit description

Bit	Symbol	Value	Description
7	WUPSTIMEOUTPRESC	X	prescaler for wakeup search timeout counter, see Table 79
6		X	
5	WUPSTIMEOUT	X	sets timeout to WUPSTIMEOUT[4:0] $\times$ T$_{WUPSTO}$ for WUPSTIMEOUT[4:0] = 1 to 63. Value WUPSTIMEOUT[4:0] = 0 disables the timeout timer and sets timeout to infinity
4		X	
3		X	
2		X	
1		X	
0		X	

Table 79.   WUPSTIMEOUTPRESC bit functions

D7	D6	Clock selection for wakeup search timeout timer T$_{WUPSTO}$
0	0	T$_{BIT}$ $\times$ 2
0	1	T$_{BIT}$ $\times$ 4
1	0	T$_{BIT}$ $\times$ 16
1	1	T$_{BIT}$ $\times$ 64

8.2.2.5 Register SLICERINITL

Register SLICERINITL (address 32h) bits are the slicer's LSBs data threshold acquired during intialisation. This register can be read to measure, for example, the RX frequency offset or to save a correct threshold value for later use. The register can be written, for example to restore a previously saved threshold value. Note that the register SLICERINIT value is different from the actual threshold value.

8.2.2.6 Register SLICERINITH

Register SLICERINITH (address 33h) bits are the slicer's MSBs data threshold acquired during initialisation.

8.2.2.7 Register TIMINGCHK

Register TIMINGCHK (address 34h) configures the timing-check units.

Table 80.   Register TIMINGCHK - (address 34h) bit description

Bit	Symbol	Value	Description
7	RFU	X	reserved
6	BROBSLENGTH	X	baud rate observation length setting: number of observed
5		X	bits configurable to 8, 16, 24 or 32 bits, see Table 81
4	SUMBITTMGERRTH	X	baud-rate checker threshold value for the sum of 8-bits
3		X	timing, see Table 82
2		X	
1	SGLBITTMGERRTH	X	single chip timing check threshold value. The time
0		X	interval is accepted if its absolute value is below the limit. Corresponds to timing errors which are less than 12.5 %, 18.75 %, 25 % or 37.5% of a nominal chip width respectively; see Table 83

Table 81.   BROBSLENGTH bit functions

D6	D5	Number of nominal bits to be considered for baud-rate checker
0	0	8
0	1	16
1	0	24
1	1	32

Table 82.   SUMBITTMGERRTH bit functions

D4	D3	D2	Total timing error threshold in T_{CHIP} / 128 per 8 bits	Relative limit with respect to 8 nominal bits (%)
0	0	0	16	0.78
0	0	1	24	1.17
0	1	0	32	1.56
0	1	1	48	2.34
1	0	0	64	3.13
1	0	1	96	4.69
1	1	0	128	6.25
1	1	1	192	9.38

Table 83.   SGLBITTMGERRTH bit functions

D1	D0	Single chip timing error threshold in T_{CHIP} / 128 per interval
0	0	16
0	1	24
1	0	32
1	1	48

8.2.2.8 Register RXCON

Table 84. Receive mode control register RXCON - (address 35h) bit description

Bit	Symbol	Value	Description
7	STATAUTOSAMPLE	X	allows the software to control whether the status is sampled when certain Read commands are issued. Automatically set to logic 0 after a wakeup search and preamble detection to save the result of this command
6	AUTOSAMPLEMANUAL	X	logic 1 prevents bit STATAUTOSAMPLE being set on completion of an RSSILEVEL read
5	INV_RX_DATA	X	inverts the slicer output. If logic 0, in FSK mode the lower frequency is received as logic 1 and the higher frequency is received as logic 0, whereas in ASK mode the lower RF amplitude is received as logic 0 and the higher RF amplitude is received as logic 1. If synchronizing the Manchester decoder with a preamble it samples the slicer output in the middle of the first half of a bit.
4	CLOCK_RECOV_TC	X	set time-constant of clock recovery settling time, see Table 85
3		X	
2	RX_MANCHESTER	X	if logic 1, data is Manchester decoded. Manchester decoding is done by skipping every other chip clock pulse. Which two possible pulse trains is omitted is set after recognizing the programmed preamble during a preamble detection. If data reception is initiated without prior preamble detection, there is an equal chance that either the right or the wrong clock pulse train is suppressed. In the first case, RX data is decoded properly; in the latter case, RX data is inverted. The MANCHESTER_COUNT in register EXTRXSTATUS helps determines if data was received correctly or inverted.
1	RX_CLOCK_TRANSP	X	if logic 1, the clock output is always the chip clock produced by the clock recovery PLL. If logic 0, the clock output is always the bit clock which is equal to the chip clock in NRZ mode during data reception. During wakeup search and preamble detection the clock is held HIGH. The microcontroller must sample the RX data line with the bit clock 1-to-0 transition.
0	RX_DATA_TRANSP	X	If logic 1, the data output is taken from the deglitched slicer result. If logic 0, the deglitched slicer result is re-sampled with the bit clock's rising edge. Therefore the microcontroller must take the data with the bit clock 1-to-0 transition. During the wakeup search, the data line is kept LOW, whereas during preamble detection it is held HIGH.

Table 85. CLOCK_RECOV_TC bit functions

D4	D3	Maximum settling time (chips)	Maximum bit edge phase error (deg)	Tolerance (%)
0	0	3 (not recommended	8	8

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Table 85. **CLOCK_RECOV_TC bit functions** *…continued*

D4	D3	Maximum settling time (chips)	Maximum bit edge phase error (deg)	Tolerance (%)
0	1	7	15	4
1	0	15	30	2
1	1	31	60	1

8.2.2.9 Register RXFOLLOWUP

Table 86. **Receive mode follow-up control register RXFOLLOWUP - (address 36h) bit description**

Bit	Symbol	Value	Description
7	PREA_FU_TF	1	this bit is only effective: when preamble detection (PRDA), was initiated by the polling timer event, and preamble detection failed. if this bit is logic 1: device enters power-down. if this bit is logic 0: device stops, but stays on, a non-maskable interrupt occurs.
6	PREA_FU_CF	0	this bit is only effective: when preamble detection (PRDA), was initiated by command, and preamble detection failed. if this bit is logic 1: device enters power-down. if this bit is logic 0: device stops, but stays on.
5	WUPS_FU_TS	0	these bits are only effective: when wakeup search (WUPS), was initiated by the polling timer event, and a WUPS signal was detected. if these bits are logic 0X: device stops, but stays on, a non-maskable interrupt occurs. if these bits are logic 11: device enters data receive mode. a non-maskable interrupt occurs. if these bits are logic 10: device enters PRDA mode.
4		0	

Table 86. **Receive mode follow-up control register RXFOLLOWUP - (address 36h) bit description** *…continued*

Bit	Symbol	Value	Description

3	WUPS_FU_TF	1	this bit is only effective:
			    when wakeup search (WUPS),
			    was initiated by the polling timer event,
			    and WUPS detection failed.
			if this bit is logic 1:
			    device enters power-down.
			if this bit is logic 0:
			    device stops, but stays on,
			    a non-maskable interrupt occurs.

2
1
	WUPS_FU_CS	0
		0
			these bits are only effective:
			    when wakeup search (WUPS),
			    was initiated by command,
			    and a WUPS signal was detected.
			if these bits are logic 0X:
			    device stops, but stays on.
			    a non-maskable interrupt occurs.
			if these bits are logic 11:
			    device enters data receive mode.
			if these bits are logic 10:
			    device enters PRDA mode.

0	WUPS_FU_CF	0	this bit is only effective:
			    when wakeup search (WUPS),
			    was initiated by command,
			    and WUPS detection failed.
			if this bit is logic 1:
			    device enters power-down.
			if this bit is logic 0:
			    device stops, but stays on.

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8.2.2.10 Register SIGMONSTATUS

Table 87. Status register SIGMONSTATUS - (address 37h) bit description
See Section 7.27 "Wakeup search logic" on page 63 for further details.

Bit	Symbol	Value	Description
7	SIGMONSTATUS	S	if logic 1, the previous wakeup search or preamble detection has failed. If logic 0, the command completed successfully. Other status registers can be read to ascertain more information if required.
6		S	chip timeout
5		S	chip timing
4		S	coding
3		S	baud rate
2		S	RSSI level
1		S	modulation amplitude too high
0		S	modulation amplitude too low

8.2.2.11 Register SIGMONERROR

Table 88. Status register SIGMONERROR - (address 38h) bit description

Bit	Symbol	Value	Description
7	SIGMONERROR	S	WUP timeout
6		S	chip timeout
5		S	chip timing
4		S	coding
3		S	baud rate
2		S	RSSI level
1		S	modulation amplitude too high
0		S	modulation amplitude too low

Table 89. Signal monitor states set by registers SIGMONSTATUS and SIGMONERROR

SIGMONSTATUS	SIGMONERROR	Signal monitor status
0	0	decision not yet available
0	1	not possible
1	0	no error detected
1	1	error detected

8.2.2.12 Register RSSILEVEL

Table 90.   Register RSSI - (address 39h) bit description

Bit	Symbol	Value	Description
7	RSSI_LEVEL	0	result of RSSI conversion
6		0	
5		0	
4		0	
3		X	
2		X	
1		X	
0		X	

Register RSSI contains the measured RSSI level at the completion of a wakeup search or preamble detection, or at the moment the microcontroller recently triggered sampling the RX signal status.

8.2.2.13 Register PREACON

Table 91.   Preamble detection control register PREACON - (address 3Ah) bit description

Bit	Symbol	Value	Description
7	RFU	0	reserved
6	PREA_TOL	X	definition of allowed chip errors during preamble detection, see Table 92
5		X	
4	PREA_LEN	X	definition of pattern length of preamble to be detected. Defined in chips, 1 to 31 is the length in chips; 0 = 32 chips.
3		X	
2		X	
1		X	
0		X	

Table 92.   PREA_TOL bit functions

D6	D5	Value
0	0	0
0	1	1
1	0	2
1	1	3

8.2.2.14 Register PREA0

Register PREA0 (address 3Bh) contains the 8 least-significant chips[7:0] of the preamble pattern assuming the preamble MSB is sent first.

8.2.2.15 Register PREA1

Register PREA1 (address 3Ch) contains bits [15:8] of the preamble pattern.

8.2.2.16 Register PREA2

Register PREA2 (address 3Dh) contains bits [23:16] of the preamble pattern.

8.2.2.17 Register PREA3

Register PREA3 (address 3Eh) contains bits [31:24] of the preamble pattern.

8.2.3 Registers only visible in bank 1

8.2.3.1 Register EXTRXSTATUS

Table 93. Register EXTRXSTATUS - (address 2Eh) bit description

Bit	Symbol	Value	Description
7	RX_HIGH_GAIN	S	logic 1 when high gain is selected, logic 0 when low gain is selected (either automatically or by command)
6	LIVE_STATUS	S	logic 0 if the consistent set of status information is automatically sampled on completion of wakeup search or preamble detection. Logic 1 if the status was sampled by a Read operation from one of the 4 receiver status registers.
5	RX_CMD	S	RX sub-command code during which, or on completion, the status is sampled. 00 = IDLE, 01 = WUPS, 10 = PREA and 11 = DATA.
4		S	
3	MANCHESTER_ COUNT	S	accumulated sum of RX data changes within a single chip period, see Section 7.29 "RX data decoding" on page 68
2		S	
1		S	
0		S	

8.2.3.2 Register CFRCCAL

Table 94. Register CFRCCAL - (address 2Fh) bit description

Bit	Symbol	Value	Description
7	CF_IQ_CAL_RUNNING	S	status bit indicates running IQ calibration
6	CF_CAL_RUNNING	S	status bit indicates running RC calibration
5	0	0	-
4	0	0	-
3	CF_RC_CAL_RES	S	result of RC auto-calibration
2		S	
1		S	
0		S	

8.2.3.3 Register CFIQCAL

Table 95. IQ calibration register CFIQCAL - (address 30h) bit description

Bit	Symbol	Value	Description
7	START_CF_IQ_CAL	0	setting this bits starts the I/Q calibration sequence
6	CF_IQ_CALVAL	S	configuration for the best I/Q calibration. The result of a triggered calibration sequence used in production test. Configuration value must be initialized and stored by the external microcontroller for every individual device to achieve best image rejection performance.
5		0	
4		0	
3		0	
2		0	
1		0	
0		0	

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8.2.4 Expert registers

The expert registers enable the use of built-in functions for special application cases. It is recommended that these settings are not changed.

8.2.4.1 Register EXPERT0

Table 96.   Register EXPERT0 - (address 31h) bit description

Bit	Symbol	Value	Description
7	RED_VCO_SWING	0	automatically set at lower band, if logic 1, VCO output swing and LO power consumption are reduced. If logic 0, VCO is running at highest drive level.
6	LARGE_PLL_RST_DELAY	0	if logic 1, the PLL phase detector reset pulse width is increased from 2.1 ns to 3.1 ns
5	FASTCFFILTSETTL	0	if logic 0, sufficient delay is provided until the channel filter is declared settled after an input transient. Especially important if a WUPS is performed in pessimistic mode. Logic 1 reduces the delay allowing faster operation. A small reduction of settling accuracy is acceptable for all other RX commands.
4	PLL_ICP	0	manual programming of PLL charge pump current. The final charge pump current can be computed as a function of the register setting using formula: I_{cp} = PLL_ICP $\times 15\ \mu$A see Section 7.14.4 "Charge pump" on page 27.
3		0	
2		1	
1		0	
0		0	

8.2.4.2 Register EXPERT1

Table 97.   Register EXPERT1 - (address 32h) bit description

Bit	Symbol	Value	Description
7	XOSTARTUPDELAY	0	sets/influences delay after XO_READY detection. Required for influencing automated startup sequences, see Table 98
6		1	
5	ASKRSTBBMID	0	applies only when receiving ASK. If left at logic 0, baseband filter resets to logic 0 (corresponding to minus infinite dBm plus noise level) after an input transient. If logic 1, baseband filter resets to the mid-point corresponding to RSSI mid-range in dBm.
4	RFU	0	reserved
3		1	
2	DISFRAC	0	disables PLL fractional-N mode
1	LOCK_DET_TIME	0	sets additional delay after 'physical' PLL lock detection. Available delays are: 00 = 16 μs, 01 = 32 μs, 10 = 48 μs, 11 = 64 μs, required for influencing automated startup sequences.
0		1	

Table 98.   XOSTARTUPDELAY bit functions

D7	D6	Delay time
0	0	256 μs

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Table 98.   XOSTARTUPDELAY bit functions *…continued*

D7	D6	Delay time
0	1	512 μs (default Power-on reset value)
1	0	768 μs
1	1	1024 μs

8.2.4.3   Register EXPERT2

Table 99.   Register EXPERT2 - (address 33h) bit description

Bit	Symbol	Value	Description
7	FM_DEM_IANDQ	0	if logic 1, I and Q limiter outputs are used for FSK demodulation
6	LARGE_FM_DEM_ RANGE	0	logic 0 selects 200 kHz range (200 kHz to 400 kHz), logic 1 selects 600 kHz range (0 Hz to 600 kHz). 0 Hz is a theoretical value limited to the channel filter AC coupling lower corner frequency.
5	WIDE_AMPL_WINDOW	0	selects the number of samples window to be used for edge detection amplitude. Logic 0 selects 2 samples at −1 and +1 either side of center. Logic 1 selects 4 samples at −2, −1, +1 and +2 either side of center.
4	REDUCED_CHIP_ TIMEOUT	0	selects timeout value for the chip timing verification block. Logic 0 selects 3.5 chips, logic 1 selects 2.5 chips.
3	TWORSSIMSBITSSLOW	0	determines time taken to acquire the 2 MSBs in the RSSI ADC. Logic 0 selects 3 clocks for bit 5 and 1 clock for bit 4. Logic 1 selects 2 clocks for bit 5 and 2 clocks for bit 4.
2	FASTRSSIFILTSETTL	0	controls the RSSI filter settling time. Logic 0 selects 4 time-constants settling to within 2 % of the last step. Logic 1 selects 2 time-constants settling to within 14 % of the last step.
1	CAPRSI	1	allows the RSSI analog data low-pass filter to be trimmed changing the filter capacitor values which affect the low-pass cut-off frequency, see Table 101
0		0	

Table 100. FM demodulator configurations

D7	D6	Center frequency (kHz)	Input frequency range (kHz)	Maximum frequency deviation (kHz)	Number of delay elements
0	0	300	200 to 400	±100	40
0	1	300	0 to 600	±300	13
1	0	600	200 to 400	±100	20
1	1	600	0 to 600	±300	7

Table 101. CAPRSSI bit functions

D1	D0	Typical capacitor value (pF)	Time-constant (R = 300 kΩ typical)
0	0	0	0 (parasitics only)

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Table 101. CAPRSSI bit functions *…continued*

D1	D0	Typical capacitor value (pF)	Time-constant (R = 300 kΩ typical)
0	1	2	0.6 μs
1	0	5	1.5 μs
1	1	12	4.8 μs

8.2.4.4 Register EXPERT3

Table 102. Register EXPERT3 - (address 34h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	0	0	-
5	0	0	-
4	0	0	-
3	TESTBUFFERCAL	0	logic 1 turns the calibration path on. Required during test buffer calibration
2	ALLOWREGSWITCH	0	controls the behavior of the REG_xxx_ON test bits. If logic 0, the REG_xxx_ON bits are OR'd to the normal control lines allowing unconditional turn-on of selected regulators. If logic 1, the REG_xxx_ON bits replace the normal control lines allowing full control (on and off) of the regulators.
1	LTDIQPHASECAL	0	if logic 0, all possible matching combinations in the RX chain are attempted in order to achieve the best image rejection. If logic 1, certain phase trimming values are forbidden to eventually achieve a better overall performance over temperature.
0	DONOTDISTURBPTCAL	0	if logic 0, a polling timer calibration can run in parallel with the PLL startup. If logic 1, the PLL startup, when requested, is delayed until the polling timer calibration ends.

8.2.5 Test registers

The test register bits are initialized to logic 0 after power-up. Test registers must never be used in standard applications.

8.2.5.1 Register TEST0

Table 103. Register TEST0 - (address 35h) bit description

Bit	Symbol	Value	Description
7	CF_MULTITONE_EN	0	channel filter multi-tone testing
6	DIG_TEST_SEL	0	selects digital test signals to be used in conjunction with the P11C[3:0] and P12C[3:0] settings, see Section 8.2.1.7 on page 83 and Section 8.2.1.8 on page 84
5		0	
4		0	
3	RXD_DBG_SEL	0	selects digital test signals
2		0	
1		0	
0		0	

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8.2.5.2 Register TEST1

Table 104. Register TEST1 - (address 36h) bit description

Bit	Symbol	Value	Description
7	IQ_TEST_LV	0	must be set if IF output signals test buffer is used at supply voltages below 2.0 V
6	ANA_TEST_SEL	0	selects analog test signal
5		0	
4		0	
3	REG_DIG_DIS	0	disables voltage regulator digital section
2	PLL_CTRL	0	test and configures PLL
1		0	
0	VCO_TEST_ON	0	enables VCO test

8.2.5.3 Register TEST2

Table 105. Register TEST2 - (address 37h) bit description

Bit	Symbol	Value	Description
7	REG_VCO_ON	0	enables VCO voltage regulator
6	REG_PLL_ON	0	enables PLL voltage regulator
5	REG_PA_ON	0	enables PA voltage regulator
4	FORCE_REG_VCO_RDY	0	overrides VCO ready signal [1]
3	FORCE_REG_PLL_RDY	0	overrides PLL ready signal [1]
2	FORCE_REG_PA_RDY	0	overrides PA ready signal [1]
1	FORCE_LOCK_DETECT	0	overrides PLL lock detect signal [1]
0	FORCE_XO_RDY	0	overrides XO ready signal [1]

[1] These bits override internal status information and enable automatic sequences to run even if the corresponding status information indicates a failing block.

8.2.5.4 Register TEST3

Table 106. Register TEST3 - (address 38h) bit description

Bit	Symbol	Value	Description
7	VCO_ON	0	enable VCO
6	PRESC_ON	0	enable prescaler
5	PFD_ON	0	enable PLL phase detector
4	CLK_PLL_ON	0	enable PLL clock
3	RFU	0	reserved
2	RX_GAP_ON	0	enable bandgap reference, required for RX mode
1	RX_ON	0	enable receiver
0	RFU	0	reserved

8.2.5.5 Register TEST4

Table 107. Register TEST4 - (address 39h) bit description

Bit	Symbol	Value	Description
7	FORCE_CF_RC_CAL	0	issues an RC auto-calibration on request
6	SKIP_CF_RC_CAL	0	prevents RC auto-calibration
5	CF_RC_ADJUSTCAL	0	enables verification of the channel filter RC auto-calibration accuracy: time-constant reference value is adjusted by this value; see Table 108
4		0	
3	MAN_CF_RC_CALVAL	X	for manual entry of the RC auto-calibration value in CF_RC_CAL_RES[3:0]
2		X	
1		X	
0		X	

Table 108. Time-constant reference settings for RC auto-calibration

CF_RC_ADJUST CAL		R variation (%)
D5	D4	
0	0	0
0	1	+12.5
1	0	−6.2
1	1	−4.1

8.2.5.6 Register TEST5

Table 109. Register TEST5 - (address 3Ah) bit description

Bit	Symbol	Value	Description
7	XO_IOFFS	0	sets programmable offset current for oscillator control loop
6		0	
5		0	
4	XO_IOFFSET_SINK_EN	0	only active if XO_IOFFSET_EN is logic 1. If logic 1, the bias source must sink the offset current otherwise it is sourced
3	XO_IOFFSET_EN	0	enables crystal oscillator offset current: controls a test signal to control the bias current. Must be logic 0 during normal crystal oscillator operation.
2	XO_KICK_DIS	0	disables crystal oscillator start-up kick: controls a test signal to disable the start-up kick after power-on. Must be logic 0 during normal crystal oscillator operation.
1	XO_DET_DIS	0	disables crystal oscillator detector: controls a test signal to disable the detector. Must be logic 0 during normal crystal oscillator operation.
0	XO_BIAS_DIS	0	disables crystal oscillator bias circuit

9. Limiting values

Table 110. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
T_{stg}	storage temperature			−55	+125	°C
T_j	junction temperature			-	+95	°C
V_{IO}	input/output voltage	any VCC or I/O pin to GND		−0.3	+3.6	V
		all other pins to GND		−0.3	+2.8	V
I_{IO}	input/output current	maximum DC current for I/O pins		-	4	mA
$P_{i(max)}$	maximum input power	RX		-	12.9	dBm
I_{lu}	latch-up current		[1][2]	100	-	mA
V_{ESD}	electrostatic discharge voltage	human body model	[3]			
		peak		2	-	kV
		machine model	[3]			
		peak		200	-	V
P_{tot}	total power dissipation			-	120	mW

[1] Only applies to pins which are connected to active devices in the application. According to the standard, only relevant for VCC pins and digital I/Os.

[2] Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the Operating conditions and Electrical characteristics section of this specification is not implied.

[3] This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

10. Static characteristics

Table 111. Static characteristics
T_{amb} = −25 °C to +85 °C, V_{CC_xxx} = 2.7 V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between V_{REG_PLL} and GND_PLL, VREG_VCO and GND_VCO. Capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG quartz crystal NDK NX5032SA with C_L = 12 pF, unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Current consumption						
V_{CC}	supply voltage		2.1	2.7	3.6	V
T_{amb}	ambient temperature		−25	+25	+85	°C
I_{CC}	supply current	power-down mode				
		+25 °C	-	0.5	1.6	μA
		+85 °C	-	5	-	μA
		crystal oscillator on, digital module active; PLL and PA off	-	900	1200	μA
$I_{CC(LO)}$	local oscillator supply current	315 MHz/434 MHz/868 MHz band; LO and PLL on; PA off	-	5	7	mA

Table 111. Static characteristics *…continued*

$T_{amb} = -25$ °C to +85 °C, $V_{CC\_xxx} = 2.7$ V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between V_{REG_PLL} and GND_PLL, VREG_VCO and GND_VCO. Capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG quartz crystal NDK NX5032SA with $C_L = 12$ pF, unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CC(RX)}$	receiver supply current	315 MHz/434 MHz/868 MHz band				
		+25 °C	15.5	16.5	18	mA
		−25 °C to +85 °C	13.5	16.5	21.5	mA
Digital I/Os						
V_{IH}	HIGH-level input voltage	$V_{CC} = 2.1$ V to 3.6 V	$0.8V_{CC}$	-	V_{CC}	V
V_{IL}	LOW-level input voltage	$V_{CC} = 2.1$ V to 3.6 V	0	-	0.4	V
I_{IH}	HIGH-level input current		−1	-	+1	μA
I_{IL}	LOW-level input current		−1	-	+1	μA
V_{OH}	HIGH-level output voltage	SPI pins (SCLK, SDIO and SDO); $V_{CC} = 2.1$ V to 3.6 V	$0.7V_{CC}$	-	V_{CC}	V
		$V_{CC} = 2.1$ V to 3.6 V	$0.8V_{CC}$	-	V_{CC}	V
V_{OL}	LOW-level output voltage	SPI pins (SCLK, SDIO and SDO); $V_{CC} = 2.1$ V to 3.6 V	0	-	$0.3V_{CC}$	V
		$V_{CC} = 2.1$ V to 3.6 V	0	-	$0.2V_{CC}$	V
I_{OH}	HIGH level output current		−1	-	-	mA
I_{OL}	LOW level output current		1	-	-	mA
f_{io}	input/output frequency	10 pF output load	-	-	4	MHz

[1] Different biasing configurations are available in the receiver to trim performances (mainly sensitivity and linearity) versus power consumption.

11. Dynamic characteristics

Table 112. Dynamic characteristics

$T_{amb} = -25$ °C to +85 °C, $V_{CC\_xxx} = 2.7$ V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with $C_L = 12$ pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{RF}	RF frequency	315 MHz	300	315	320	MHz
		434 MHz	415	434	450	MHz
		868 MHz	865	868	870	MHz
		915 MHz	902	915	928	MHz
$f_{RF(step)}$	RF frequency step	315 MHz	-	150	-	Hz
		434 MHz	-	200	-	Hz
		868 MHz	-	400	-	Hz
		915 MHz	-	415	-	Hz
Demodulation						
f_{chip}	chip rate	Manchester (or NRZ) encoding	0.4	-	112	kchip/s
$f_{chip(step)}$	chip rate step		-	0.1	-	kchip/s

Table 112. Dynamic characteristics *…continued*

T_{amb} = −25 ℃ to +85 ℃, V_{CC_xxx} = 2.7 V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with C_L = 12 pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Reference crystal oscillator							
f_{xtal}	crystal frequency			15.95	16	16.05	MHz
$t_{startup(xtal)}$	crystal start-up time		[1]	-	-	1	ms
$C_{drv(xtal)}$	crystal driver capacitance	driver		-	1	-	pF
$R_{s(xtal)}$	crystal series resistance	−10 °C to +65 °C; 2.1 V minimum; quartz crystal NDK NX5032SA; C_L = 12 pF		-	-	700	Ω
$V_{i(clk)}$	clock input voltage	external clock applied to pin XTAL2	[2]				
		clock HIGH		-	1.8	-	V
		clock LOW		-	0	-	V
PLL							
$B_{PLL(loop)}$	PLL loop bandwidth	−3 dB closed loop at 868 MHz	[3]	-	150	-	kHz
$t_{cal(VCO)}$	VCO calibration time	auto-calibration	[4]	-	110	-	μs
$t_{lock(PLL)}$	PLL lock time		[4]	-	120	200	μs
Receiver section							
$|Z_i|$	input impedance	at 868 MHz	[5]	-	66 to j94	-	Ω
		at 434 MHz	[5]	-	125 to j139	-	Ω
		at 315 MHz	[5]	-	157 to j138	-	Ω
B	bandwidth	channel filter	[6]	50	-	300	kHz
$t_{startup(PLL)RX}$	receiver PLL start-up time	from PLL start-up to RX ready	[4]	-	250	350	μs
NF	noise figure	cascaded; maximum front-end gain		-	7	-	dB

Table 112. Dynamic characteristics *…continued*

T_{amb} = −25 ℃ to +85 ℃, V_{CC_xxx} = 2.7 V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with C_L = 12 pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
S_{RX}	receiver sensitivity	BER ≤ 10⁻³; E_b/N_0 of 9.8 dB maximum front-end gain				
		Manchester encoded data rate = 2.4 kbit/s; deviation = 2.4 kHz; channel filter B = 50 kHz	−109	−112	-	dBm
		Manchester encoded data rate = 4.8kbit/s; deviation = 4.8 kHz; channel filter B = 50 kHz	−108	−110	-	dBm
		Manchester encoded data rate = 9.6 kbit/s; deviation = 15 kHz; channel filter B = 75 kHz	−106	−109	-	dBm
		Manchester encoded data rate = 20 kbit/s; deviation = 20 kHz; channel filter B = 100 kHz	−103	−105	-	dBm
		Manchester encoded data rate = 2.4 kbit/s; channel filter B = 50 kHz; ASK modulation with 50 % duty cycle square wave; on/off keying; mean output power	-	−118	-	dBm
		Manchester encoded data rate = 4.8 kbit/s; channel filter B = 50 kHz; ASK modulation with 50 % duty-cycle square wave; on/off keying; mean output power	-	−117	-	dBm

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Table 112. Dynamic characteristics *…continued*

T_{amb} = −25 °C to +85 °C, V_{CC_xxx} = 2.7 V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with C_L = 12 pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
α_{ch}	channel rejection	co-channel; using Edge Slicer	-	−11	-	dB
		wanted 3 dB above the sensitivity level, CW jammer, BER ≤ 10^{-2}				
		channel spacing = channel bandwidth	10	-	-	dB
		≥ 2 channels separation	30	-	-	dB

Table 112. Dynamic characteristics *…continued*

T_{amb} = −25 °C to +85 °C, V_{CC_xxx} = 2.7 V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with C_L = 12 pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\alpha_{sup(f)image}$	image frequency suppression		-	30	-	dB
		with calibration, 315 MHz and 434 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 2.4 kbit/s channel filter B = 50 kHz	[7] 50	-	-	dB
		with calibration, 315 MHz and 434 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 20 kbit/s channel filter B = 300 kHz	45	-	-	dB
		with calibration, 868 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 2.4 kbit/s channel filter B = 50 kHz	[7] 45	-	-	dB
		with calibration, 868 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 20 kbit/s channel filter B = 300 kHz	40	-	-	dB

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Table 112. Dynamic characteristics …continued

$T_{amb} = -25$ °C to +85 °C, $V_{CC\_xxx} = 2.7$ V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with $C_L = 12$ pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$\alpha_{ch(image)}$	image channel rejection	wanted 3 dB above the sensitivity level; CW jammer at image frequency; BER $\leq 10^{-2}$; calibration with external RF signal, FSK modulation	[7]	-	22	-	dB
		315 MHz and 434 MHz; Manchester encoded data rate = 2.4 kbit/s; channel filter B = 50 kHz	[7]	40	-	-	dB
		315 MHz and 434 MHz; Manchester encoded data rate = 20 kbit/s; channel filter B = 300 kHz	[7]	30	-	-	dB
		868 MHz; Manchester encoded data rate = 2.4 kbit/s; channel filter B = 50 kHz	[7]	30	-	-	dB
		868 MHz; Manchester encoded data rate = 20 kbit/s; channel filter B = 300 kHz	[7]	25	-	-	dB
α_{oob}	out-of-band rejection	blocking signal					
		$\pm$ 1 MHz from edge band		40	-	-	dB
		$\pm$ 2 MHz from edge band		50	-	-	dB
		$\pm$ 5 MHz from edge band		60	-	-	dB
		$\pm$ 10 MHz from edge band		60	-	-	dB
ICP_{1dB}	1 dB input compression point	to mixer output; front-end maximum gain		-	-36	-	dBm

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Table 112. Dynamic characteristics *…continued*

T_{amb} = −25 °C to +85 °C, V_{CC_xxx} = 2.7 V, GND_xxx = 0 V; capacitors of 22 nF // 270 pF connected between VREG_PLL and GND_PLL, VREG_VCO and GND_VCO; capacitor of 47 nF // 270 pF connected between VREG_DIG and GND_DIG; quartz crystal NDK NX5032SA with C_L = 12 pF; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IP3	third-order intercept point	+5 MHz and 10 MHz; to mixer output; front-end maximum gain	-	−23	-	dBm
$P_{L(lo)}$	local oscillator leakage power	at RX input; LO > 1 GHz	-	-	−47	dBm
$P_{sp(RX)}$	receiver spurious power	emission in RX mode				
		9 kHz to 1 GHz	-	-	−57	dBm
		1 GHz to 4 GHz	-	-	−47	dBm
RSSI						
$RSSI_{range(dyn)}$	received signal strength indicator dynamic range		-	80	-	dB
$RSSI_{acc(abs)}$	absolute accuracy of received signal strength indicator	input power variation (in range of −90 dBm) to achieve nominal digital code of 89 LSB for any device under any condition	[7] -	±12	-	dB
Δ_{RSSI}	received signal strength indicator variation	input power variation (in range of −90 dBm) for one device over supply and temperature	[7] -	±3	-	dB
G_{RSSI}	RSSI gain		0.4	-	0.9	dB/LSB
$RSSI_{min}$	minimum received signal strength indicator	linked to reference sensitivity	-	−110	−100	dBm

[1] Start-up time includes XOSTARUPDELAY = 256 µs.

[2] Only for test purposes, and not to be used in the application.

[3] On-chip loop filter: ICP value = 2.

[4] Guaranteed by design.

[5] Input resistance in series with reactance in high gain mode. These values are indicative, determine input impedance on an application basis, and refer to the application note.

[6] There are six bandwidth settings for 50 kHz, 75 kHz, 100 kHz, 150 kHz, 200 kHz and 300 kHz.

[7] Values derived from characterization result.

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12. Application information
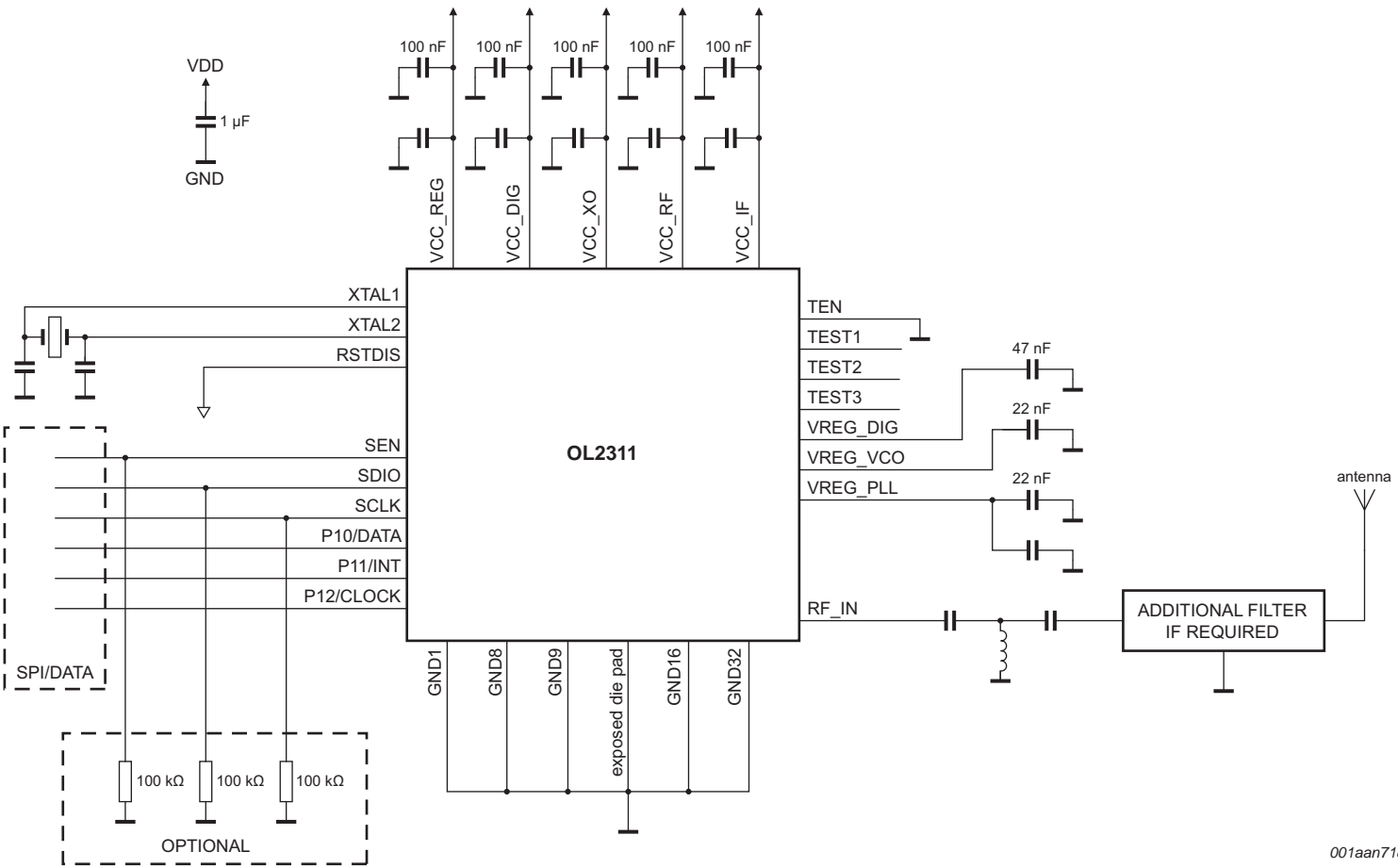
The values for the matching circuit components must be finalized after test board layout.

All connections to GND must be separated.

Fig 46. Application diagram

13. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads;
32 terminals; body 5 x 5 x 0.85 mm SOT617-3

Dimensions

Unit[1]		A[1]	A_1	b	c	D[1]	D_h	E[1]	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	max	0.85	0.05	0.30	0.2	5.1	3.75	5.1	3.75	0.5	3.5	3.5	0.5	0.1	0.05	0.05	0.1
	nom																
	min		0.00	0.18		4.9	3.45	4.9	3.45				0.3				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot617-3_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT617-3		MO-220				~~11-06-14~~ 11-06-21
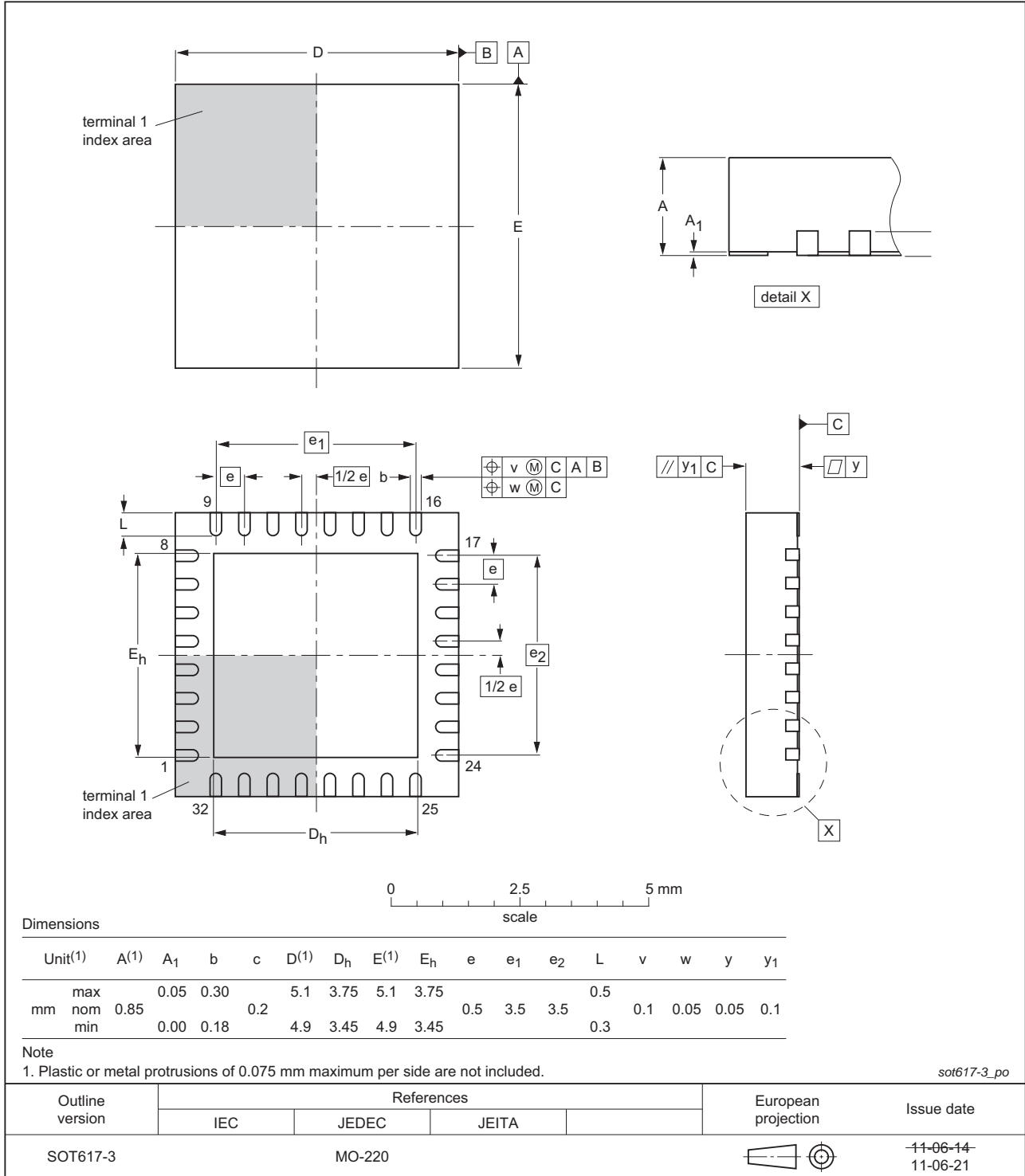
Fig 47. Package outline SOT617-3 (HVQFN32)

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14. Abbreviations

Table 113. Abbreviations

Acronym	Description
AM	Amplitude Modulation
ASK	Amplitude-Shift Keying
ADC	Analog-to-Digital Converter
BER	Bit Error Rate
CW	Continuous Wave
DAC	Digital-to-Analog Converter
EOF	End Of File
FM	Frequency Modulation
FRMP	FSK RaMP
FSK	Frequency Shift Keying
GFSK	Gaussian Frequency Shift Keying
ICP	Input Compression Point
IF	Intermediate Frequency
ISM	Industrial, Scientific and Medical
LC	inductor Capacitor
LNA	Low-Noise Amplifier
LO	Local Oscillator
LSB	Least Significant Bit
MISO	Master In Slave Out
MOSI	Master Out Slave In
MSB	Most Significant Bit
NRZ	Not Return to Zero
OSR	OverSampling Ratio
PA	Power Amplifier
PAM	Power Amplifier Mode
PFD	Phase Frequency Detector
PLL	Phase-Locked Loop
POR	Power-On Reset
PRDA	PReamble detection followed by DAta reception
PREA	PREAmble
PRNG	Pseudo-Random Number Generator
RC	Resistor Capacitor
RF	Radio Frequency
RFU	Reserved for Future Use
RSSI	Residual Signal Strength Indicator
RT	Room Temperature
RX	Receiver
SAW	Surface Acoustic Wave
SFR	Special Function Register

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Table 113. Abbreviations *…continued*

Acronym	Description
SPI	Serial Peripheral Interface
SRD	Short-Range Device
TX	Transmitter
VCO	Voltage-Controlled Oscillator
WUP	Wake UP
WUPS	Wake UP Search
XO	Crystal Oscillator

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15. Revision history

Table 114. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
OL2311 v.1	20111208	Product data sheet	-	-

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16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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18. Tables

19. Figures

20. Contents

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